



MACRONIX
INTERNATIONAL CO., LTD.

MX25L12845E

MX25L12845E
HIGH PERFORMANCE
SERIAL FLASH SPECIFICATION

Contents

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128M-BIT [x 1/x 2/x 4] CMOS MXSMIO® (SERIAL MULTI I/O) FLASH MEMORY**FEATURES****GENERAL**

- Serial Peripheral Interface compatible -- Mode 0 and Mode 3
- 128Mb: 134,217,728 x 1 bit structure or 67,108,864 x 2 bits (two I/O mode) structure or 33,554,432 x 4 bits (four I/O mode) structure
- 4096 Equal Sectors with 4K bytes each
 - Any Sector can be erased individually
- 512 Equal Blocks with 32K bytes each
 - Any Block can be erased individually
- 256 Equal Blocks with 64K bytes each
 - Any Block can be erased individually
- Power Supply Operation
 - 2.7 to 3.6 volt for read, erase, and program operations
- Latch-up protected to 100mA from -1V to Vcc +1V

PERFORMANCE

- High Performance
VCC = 2.7~3.6V
 - Normal read
 - 50MHz
 - Fast read (Normal Serial Mode)
 - 1 I/O: 104MHz with 8 dummy cycles
 - 2 I/O: 70MHz with 4 dummy cycles
 - 4 I/O: 70MHz with 6 dummy cycles
 - Fast read (Double Transfer Rate Mode)
 - 1 I/O: 50MHz with 6 dummy cycles
 - 2 I/O: 50MHz with 6 dummy cycles
 - 4 I/O: 50MHz with 8 dummy cycles
 - Fast program time: 1.4ms(typ.) and 5ms(max.)/page (256-byte per page)
 - Byte program time: 9us (typical)
 - Continuously Program mode (automatically increase address under word program mode)
 - Fast erase time: 60ms (typ.)/sector (4K-byte per sector) ; 0.7s(typ.) /block (64K-byte per block); 80s(typ.) /chip
- Low Power Consumption
 - Low active read current: 19mA(max.) at 104MHz, 15mA(max.) at 66MHz and 10mA(max.) at 33MHz
 - Low active programming current: 25mA (max.)
 - Low active erase current: 25mA (max.)
 - Low standby current: 100uA (max.)
 - Deep power down current: 40uA (max.)
- Typical 100,000 erase/program cycles

SOFTWARE FEATURES

- Input Data Format
 - 1-byte Command code

- Advanced Security Features
 - BP0-BP3 block group protect
 - Flexible individual block protect when OTP WPSEL=1
 - Additional 4K bits secured OTP for unique identifier
- Auto Erase and Auto Program Algorithms
 - Automatically erases and verifies data at selected sector
 - Automatically programs and verifies data at selected page by an internal algorithm that automatically times the program pulse width (Any page to be programmed should have page in the erased state first.)
- Status Register Feature
- Electronic Identification
 - JEDEC 1-byte Manufacturer ID and 2-byte Device ID
 - RES command for 1-byte Device ID
 - REMS, REMS2, REMS4 and REMS4D commands for 1-byte Manufacturer ID and 1-byte Device ID
- Support Serial Flash Discoverable Parameters (SFDP) mode

HARDWARE FEATURES

- SCLK Input
 - Serial clock input
- SI/SIO0
 - Serial Data Input or Serial Data Input/Output for 2 x I/O mode and 4 x I/O mode
- SO/SIO1/PO7
 - Serial Data Output or Serial Data Input/Output for 2 x I/O mode and 4 x I/O mode or Parallel Data
- WP#/SIO2
 - Hardware write protection or serial data Input/Output for 4 x I/O mode
- NC/SIO3
 - NC pin or serial data Input/Output for 4 x I/O mode
- PO0~PO6
 - For parallel mode data (only 128Mb provide parallel mode)
- PACKAGE
 - 16-pin SOP (300mil)
 - 8-WSON (8x6mm)
 - **All devices are RoHS Compliant and Halogen-free**

GENERAL DESCRIPTION

MX25L12845E is 134,217,728 bits serial Flash memory, which is configured as 16,777,216 x 8 internally. When it is in two or four I/O mode, the structure becomes 67,108,864 bits x 2 or 33,554,432 bits x 4. The MX25L12845E features a serial peripheral interface and software protocol allowing operation on a simple 3-wire bus. The three bus signals are a clock input (SCLK), a serial data input (SI), and a serial data output (SO). Serial access to the device is enabled by CS# input.

MX25L12845E provides high performance read mode, which may latch address and data on both rising and falling edge of clock. By using this high performance read mode, the data throughput may be doubling. Moreover, the performance may reach direct code execution, the RAM size of the system may be reduced and further saving system cost.

MX25L12845E, MXSMIO® (Serial Multi I/O) flash memory, provides sequential read operation on the whole chip and multi-I/O features.

When it is in dual I/O mode, the SI pin and SO pin become SIO0 pin and SIO1 pin for address/dummy bits input and data output. When it is in quad I/O mode, the SI pin, SO pin, WP# pin and NC pin become SIO0 pin, SIO1 pin, SIO2 pin and SIO3 pin for address/dummy bits input and data Input/Output. Parallel mode is also provided in this device. It features 8 bit input/output for increasing throughputs. This feature is recommended to be used for factory production purpose.

After program/erase command is issued, auto program/erase algorithms which program/erase and verify the specified page or sector/block locations will be executed. Program command is executed on byte basis, or page (256 bytes) basis, or word basis. Continuously Program mode and erase command are executed on 4K-byte sector, 32K-byte/64K-byte block, or whole chip basis.

To provide user with ease of interface, a status register is included to indicate the status of the chip. The status read command can be issued to detect completion status of a program or erase operation via the WIP bit.

When the device is not in operation and CS# is high, it is put in standby mode and draws less than 100uA DC current.

The MX25L12845E utilizes Macronix's proprietary memory cell, which reliably stores memory contents even after 100,000 program and erase cycles.

Table 1. Additional Features

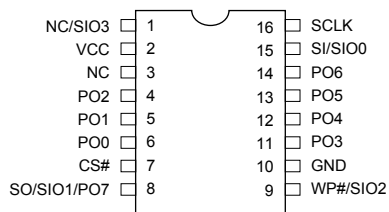
| Additional Features Part Name | Protection and Security | | Read Performance | | | | | | |
|----------------------------------|---|--------------------|----------------------|---------------------|---------------------|------------------------|------------------------|------------------------|-----------------------------|
| | Flexible or Individual block (or sector) protection | 4K-bit secured OTP | 1 I/O Read (104 MHz) | 2 I/O Read (70 MHz) | 4 I/O Read (70 MHz) | 1 I/O DT Read (50 MHz) | 2 I/O DT Read (50 MHz) | 4 I/O DT Read (50 MHz) | 8 I/O Parallel Mode (6 MHz) |
| MX25L12845E | V | V | V | V | V | V | V | V | V (Note 1) |

| Additional Features Part Name | Identifier | | | | | |
|----------------------------------|-----------------------|------------------------|-------------------------|-------------------------|--------------------------|------------------------|
| | RES (command: AB hex) | REMS (command: 90 hex) | REMS2 (command: EF hex) | REMS4 (command: DF hex) | REMS4D (command: CF hex) | RDID (command: 9F hex) |
| MX25L12845E | 17 (hex) | C2 17 (hex) | C2 17 (hex) | C2 17 (hex) | C2 17 (hex) | C2 20 18 (hex) |

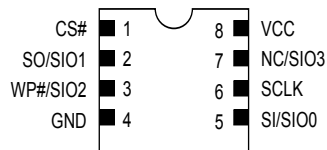
Note 1: Only MX25L12845E provide parallel mode.

PIN CONFIGURATION

16-PIN SOP (300mil)

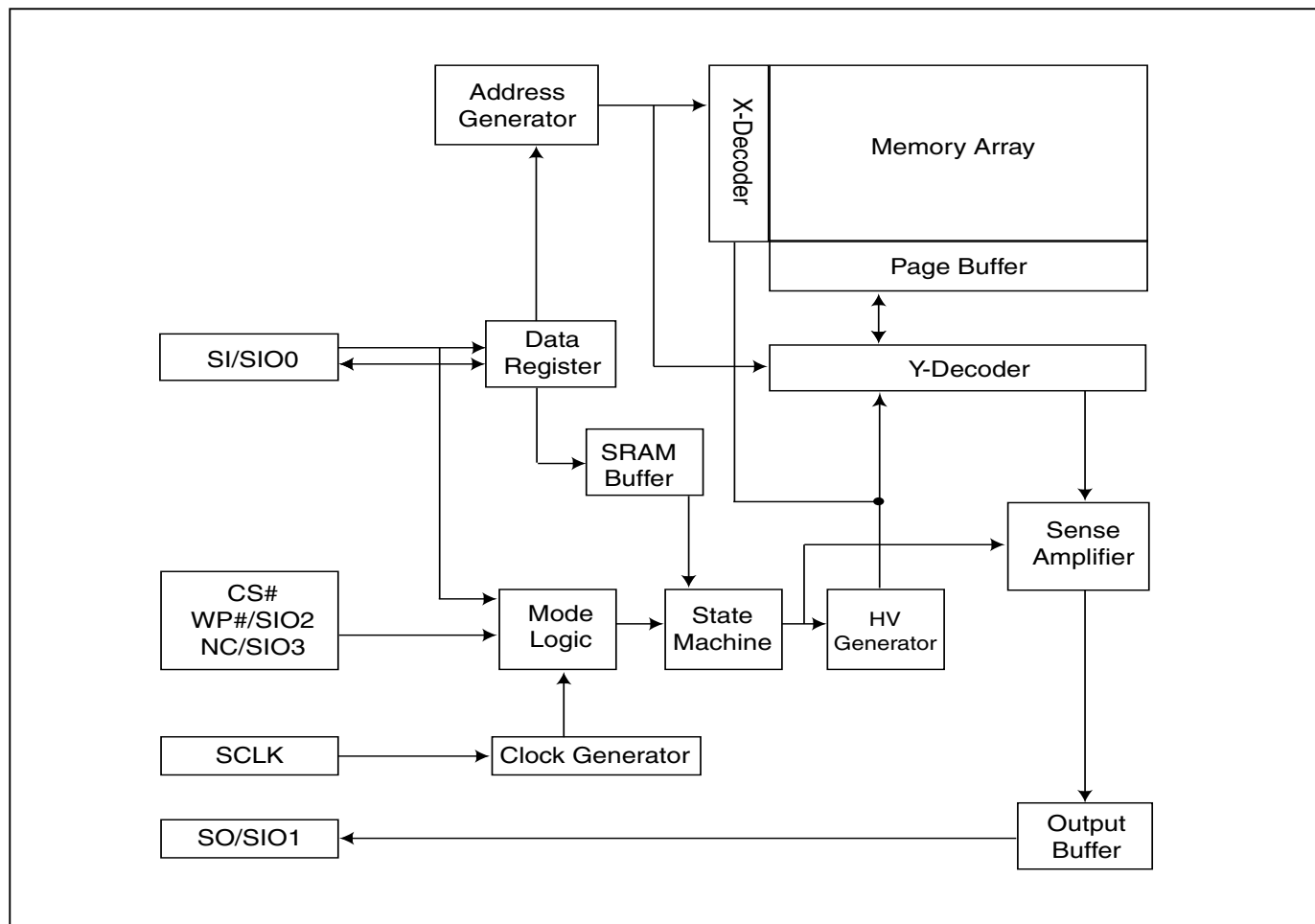


8-WSON (8x6mm)



PIN DESCRIPTION

| SYMBOL | DESCRIPTION |
|-------------|--|
| CS# | Chip Select |
| SI/SIO0 | Serial Data Input (for 1xI/O)/ Serial Data Input & Output (for 2xI/O or 4xI/O mode) |
| SO/SIO1/PO7 | Serial Data Output (for 1xI/O)/Serial Data Input & Output (for 2xI/O or 4xI/O mode) / Parallel Data Output/Input |
| SCLK | Clock Input |
| WP#/SIO2 | Write protection: connect to GND or Serial Data Input & Output (for 4xI/O mode) |
| NC/SIO3 | NC pin (Not connect) or Serial Data Input & Output (for 4xI/O mode) |
| VCC | + 3.3V Power Supply |
| GND | Ground |
| PO0~PO6 | Parallel data output/input (PO0~PO6 can be connected to NC in Serial Mode) |
| NC | No Connection |

BLOCK DIAGRAM

DATA PROTECTION

During power transition, there may be some false system level signals which result in inadvertent erasure or programming. The device is designed to protect itself from these accidental write cycles.

The state machine will be reset as standby mode automatically during power up. In addition, the control register architecture of the device constrains that the memory contents can only be changed after specific command sequences have completed successfully.

In the following, there are several features to protect the system from the accidental write cycles during VCC power-up and power-down or from system noise.

- Valid command length checking: The command length will be checked whether it is at byte base and completed on byte boundary.
- Write Enable (WREN) command: WREN command is required to set the Write Enable Latch bit (WEL) before issuing other commands to change data. The WEL bit will return to reset stage under following situations:
 - Power-up
 - Write Disable (WRDI) command completion
 - Write Status Register (WRSR) command completion
 - Page Program (PP, 4PP) command completion
 - Continuously Program mode (CP) instruction completion
 - Sector Erase (SE) command completion
 - Block Erase (BE, BE32K) command completion
 - Chip Erase (CE) command completion
 - Single Block Lock/Unlock (SBLK/SBULK) instruction completion
 - Gang Block Lock/Unlock (GBLK/GBULK) instruction completion
- Deep Power Down Mode: By entering deep power down mode, the flash device also is under protected from writing all commands except Release from Deep Power Down mode command (RDP) and Read Electronic Signature command (RES).

I. Block lock protection

- The Software Protected Mode (SPM) uses (BP3, BP2, BP1, BP0) bits to allow part of memory to be protected as read only. The protected area definition is shown as table of "[Protected Area Sizes](#)", the protected areas are more flexible which may protect various area by setting value of BP0-BP3 bits. Please refer to table of "[Protected Area Sizes](#)".
- The Hardware Protected Mode (HPM) uses WP#/SIO2 to protect the (BP3, BP2, BP1, BP0) bits and SRWD bit. If the system goes into four I/O mode, the feature of HPM will be disabled.
- MX25L12845E provides individual block (or sector) write protect & unprotect. User may enter the mode with WPSEL command and conduct individual block (or sector) write protect with SBLK instruction, or SBULK for individual block (or sector) unprotect. Under the mode, user may conduct whole chip (all blocks) protect with GBLK instruction and unlock the whole chip with GBULK instruction.

Table 2. Protected Area Sizes

| Status bit | | | | Protection Area |
|------------|-----|-----|-----|-----------------------------------|
| BP3 | BP2 | BP1 | BP0 | 128Mb |
| 0 | 0 | 0 | 0 | 0 (none) |
| 0 | 0 | 0 | 1 | 1 (2 blocks, block 254th-255th) |
| 0 | 0 | 1 | 0 | 2 (4 blocks, block 252nd-255th) |
| 0 | 0 | 1 | 1 | 3 (8 blocks, block 248th-255th) |
| 0 | 1 | 0 | 0 | 4 (16 blocks, block 240th-255th) |
| 0 | 1 | 0 | 1 | 5 (32 blocks, block 224th-255th) |
| 0 | 1 | 1 | 0 | 6 (64 blocks, block 192nd-255th) |
| 0 | 1 | 1 | 1 | 7 (128 blocks, block 128th-255th) |
| 1 | 0 | 0 | 0 | 8 (256 blocks, all) |
| 1 | 0 | 0 | 1 | 9 (256 blocks, all) |
| 1 | 0 | 1 | 0 | 10 (256 blocks, all) |
| 1 | 0 | 1 | 1 | 11 (256 blocks, all) |
| 1 | 1 | 0 | 0 | 12 (256 blocks, all) |
| 1 | 1 | 0 | 1 | 13 (256 blocks, all) |
| 1 | 1 | 1 | 0 | 14 (256 blocks, all) |
| 1 | 1 | 1 | 1 | 15 (256 blocks, all) |

Note: The device is ready to accept a Chip Erase instruction if, and only if, all Block Protect (BP3, BP2, BP1, BP0) are 0.

II. Additional 4K-bit secured OTP for unique identifier: to provide 4K-bit One-Time Program area for setting device unique serial number - Which may be set by factory or system maker. Please refer to [Table 3. 4K-bit Secured OTP Definition](#).

- Security register bit 0 indicates whether the chip is locked by factory or not.
- To program the 4K-bit secured OTP by entering 4K-bit secured OTP mode (with ENSO command), and going through normal program procedure, and then exiting 4K-bit secured OTP mode by writing EXSO command.
- Customer may lock-down the customer lockable secured OTP by writing WRSCUR(write security register) command to set customer lock-down bit1 as "1". Please refer to table of "[Security Register Definition](#)" for security register bit definition and table of "[4K-bit Secured OTP Definition](#)" for address range definition.
- **Note:** Once lock-down whatever by factory or customer, it cannot be changed any more. While in 4K-bit Secured OTP mode, array access is not allowed.

Table 3. 4K-bit Secured OTP Definition

| Address range | Size | Standard Factory Lock | Customer Lock |
|---------------|----------|--------------------------------|------------------------|
| xxx000~xxx00F | 128-bit | ESN (electrical serial number) | Determined by customer |
| xxx010~xxx1FF | 3968-bit | N/A | |

Memory Organization

Table 4. Memory Organization

| Block(64K-byte) | Block(32K-byte) | Sector | Address Range | |
|-----------------|-----------------|--------|---------------|---------|
| 255 | 511 | 4095 | FFF000h | FFFFFh |
| | | ⋮ | | |
| | | 4088 | FF8000h | FF8FFFh |
| | 510 | 4087 | FF7000h | FF7FFFh |
| | | ⋮ | | |
| | | 4080 | FF0000h | FF0FFFh |
| 254 | 509 | 4079 | FEF000h | FEFFFFh |
| | | ⋮ | | |
| | | 4072 | FE8000h | FE8FFFh |
| | 508 | 4071 | FE7000h | FE7FFFh |
| | | ⋮ | | |
| | | 4064 | FE0000h | FE0FFFh |
| 253 | 507 | 4063 | FDF000h | FDFFFFh |
| | | ⋮ | | |
| | | 4056 | FD8000h | FD8FFFh |
| | 506 | 4055 | FD7000h | FD7FFFh |
| | | ⋮ | | |
| | | 4048 | FD0000h | FD0FFFh |

individual block
lock/unlock unit:64K-byte

individual 16 sectors
lock/unlock unit:4K-byte

individual block
lock/unlock unit:64K-byte

| | | | | |
|---|---|----|---------|---------|
| 2 | 5 | 47 | 02F000h | 02FFFFh |
| | | ⋮ | | |
| | | 40 | 028000h | 028FFFh |
| | 4 | 39 | 027000h | 027FFFh |
| | | ⋮ | | |
| | | 32 | 020000h | 020FFFh |
| 1 | 3 | 31 | 01F000h | 01FFFFh |
| | | ⋮ | | |
| | | 24 | 018000h | 018FFFh |
| | 2 | 23 | 017000h | 017FFFh |
| | | ⋮ | | |
| | | 16 | 010000h | 010FFFh |
| 0 | 1 | 15 | 00F000h | 00FFFFh |
| | | ⋮ | | |
| | | 8 | 008000h | 008FFFh |
| | 0 | 7 | 007000h | 007FFFh |
| | | ⋮ | | |
| | | 0 | 000000h | 000FFFh |

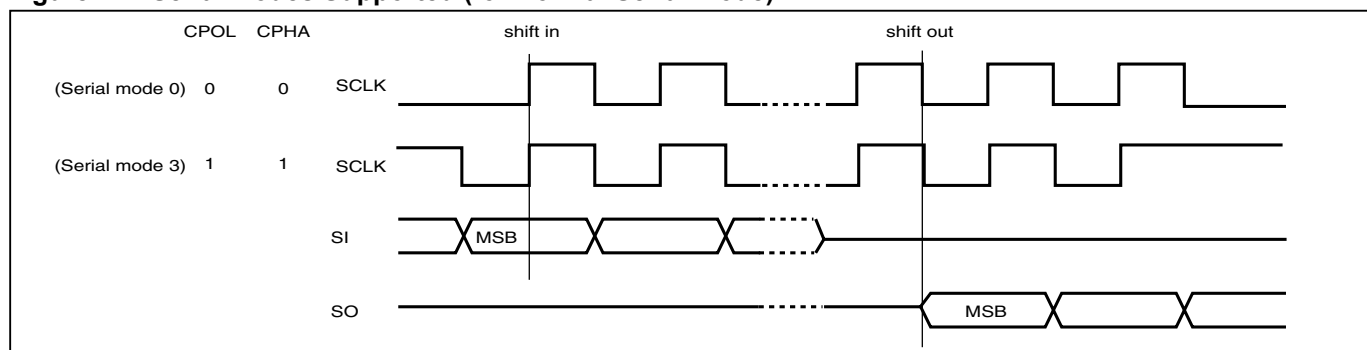
individual block
lock/unlock unit:64K-byte

individual 16 sectors
lock/unlock unit:4K-byte

DEVICE OPERATION

1. Before a command is issued, status register should be checked to ensure device is ready for the intended operation.
2. When incorrect command is inputted to this device, it enters standby mode and remains in standby mode until next CS# falling edge. In standby mode, SO pin of the device is High-Z.
3. When correct command is inputted to this device, it enters active mode and remains in active mode until next CS# rising edge.
4. For standard single data rate serial mode, input data is latched on the rising edge of Serial Clock (SCLK) and data is shifted out on the falling edge of SCLK. The difference of Serial mode 0 and mode 3 is shown as [Figure 1-1](#). For high performance (Double Transfer Rate Read serial mode), data is latched on both rising and falling edge of clock and data shifts out on both rising and falling edge of clock as [Figure 1-2](#).
5. For the following instructions: RDID, RDSR, RDSCUR, READ, FAST_READ, RDSFDP, 2READ, 4READ, FASTDTRD, 2DTRD, 4DTRD, RDBLOCK, RES, REMS, REMS2, REMS4, and REMS4D the shifted-in instruction sequence is followed by a data-out sequence. After any bit of data being shifted out, the CS# can be high. For the following instructions: WREN, WRDI, WRSR, SE, BE, BE32K, HPM, CE, PP, CP, 4PP, RDP, DP, WPSEL, SBLK, SBULK, GBLK, GBULK, ENSO, EXSO, WRSCUR, ENPLM, EXPLM and CLSR the CS# must go high exactly at the byte boundary; otherwise, the instruction will be rejected and not executed.
6. While a Write Status Register, Program, or Erase operation is in progress, access to the memory array is neglected and will not affect the current operation of Write Status Register, Program, Erase.

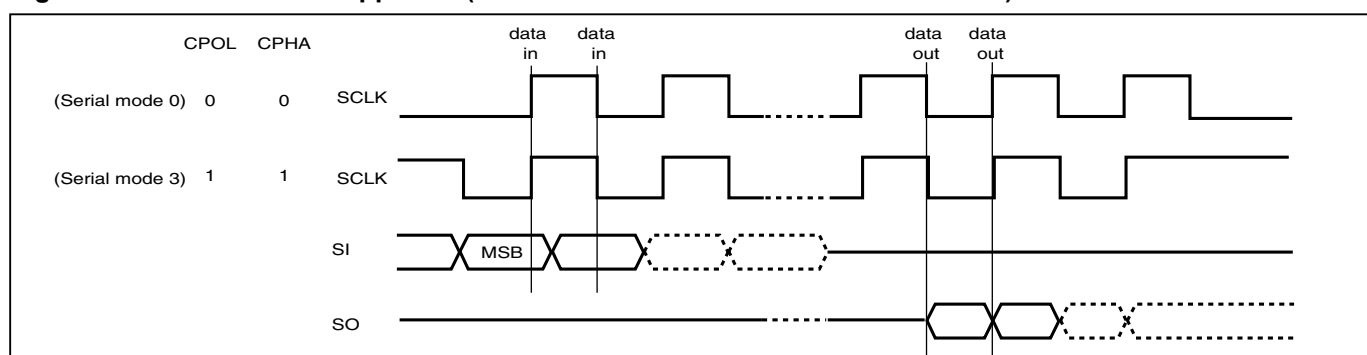
Figure 1-1. Serial Modes Supported (for Normal Serial mode)



Note:

CPOL indicates clock polarity of Serial master, CPOL=1 for SCLK high while idle, CPOL=0 for SCLK low while not transmitting. CPHA indicates clock phase. The combination of CPOL bit and CPHA bit decides which Serial mode is supported.

Figure 1-2. Serial Modes Supported (for Double Transfer Rate serial read mode)



COMMAND DESCRIPTION

Table 5. Command Sets

| COMMAND (byte) | WREN (write enable) | WRDI (write disable) | RDID (read identification) | RDSR (read status register) | WRSR (write status register) | FASTDTRD (fast DT read) | 2DTRD (Dual I/O DT Read) | 4DTRD (Quad I/O DT Read) |
|----------------|---------------------------------------|---|---|---|--|---|--|--|
| Command (hex) | 06 | 04 | 9F | 05 | 01 | 0D | BD | ED |
| Input Cycles | | | | | Data(8) | ADD(12) | ADD(6) | ADD(3) |
| Dummy Cycles | | | | | | 6 | 6 | 1+7 |
| Action | sets the (WEL) write enable latch bit | resets the (WEL) write enable latch bit | outputs JEDEC ID: 1-byte Manufacturer ID & 2-byte Device ID | to read out the values of the status register | to write new values to the status register | n bytes read out (Double Transfer Rate) until CS# goes high | n bytes read out (Double Transfer Rate) by 2xI/O until CS# goes high | n bytes read out (Double Transfer Rate) by 4xI/O until CS# goes high |

| COMMAND (byte) | READ (read data) | FAST READ (fast read data) | RDSFDP (Read SFDP) | 2READ (2 x I/O read command) Note1 | 4READ (4 x I/O read command) | 4PP (quad page program) | SE (sector erase) | BE (block erase 64KB) |
|----------------|--------------------------------------|--------------------------------------|--------------------|---|---|---|------------------------------|----------------------------------|
| Command (hex) | 03 | 0B | 5A | BB | EB | 38 | 20 | D8 |
| Input Cycles | ADD(24) | ADD(24) | ADD(24) | ADD(12) | ADD(6) | ADD(6)+Data(512) | ADD(24) | ADD(24) |
| Dummy Cycles | | 8 | 8 | 4 | 2+4 | | | |
| Action | n bytes read out until CS# goes high | n bytes read out until CS# goes high | Read SFDP mode | n bytes read out by 2 x I/O until CS# goes high | n bytes read out by 4 x I/O until CS# goes high | quad input to program the selected page | to erase the selected sector | to erase the selected 64KB block |

| COMMAND (byte) | BE 32K (block erase 32KB) | CE (chip erase) | PP (Page program) | CP (Continuously program mode) | DP (Deep power down) | RDP (Release from deep power down) | RES (read electronic ID) | REMS (read electronic manufacturer & device ID) |
|----------------|----------------------------------|---------------------|------------------------------|--|-----------------------------|------------------------------------|------------------------------|---|
| Command (hex) | 52 | 60 or C7 | 02 | AD | B9 | AB | AB | 90 |
| Input Cycles | ADD(24) | | ADD(24)+Data(2048) | ADD(24)+Data(16) | | | | ADD(24) |
| Dummy Cycles | | | | | | | 24 | |
| Action | to erase the selected 32KB block | to erase whole chip | to program the selected page | continuously program whole chip, the address is automatically increase | enters deep power down mode | release from deep power down mode | to read out 1-byte Device ID | output the Manufacturer ID & Device ID |

| COMMAND (byte) | BE 32K (block erase 32KB) | REMS4 (read ID for 4x I/O mode) | REMS4D (read ID for 4x I/O DT mode) | ENSO (enter secured OTP) | EXSO (exit secured OTP) | RDSCUR (read security register) | WRSCUR (write security register) |
|----------------|----------------------------------|--|--|--------------------------------------|-------------------------------------|------------------------------------|---|
| Command (hex) | 52 | DF | CF | B1 | C1 | 2B | 2F |
| Input Cycles | ADD(24) | ADD(24) | ADD(24) | | | | |
| Dummy Cycles | | | | | | | |
| Action | to erase the selected 32KB block | output the Manufacturer ID & device ID | output the Manufacturer ID & Device ID | to enter the 4K-bit Secured OTP mode | to exit the 4K-bit Secured OTP mode | to read value of security register | to set the lock-down bit as "1" (once lock-down, cannot be updated) |

| COMMAND (byte) | ENPLM (Enter Parallel Mode) | EXPLM (EXIT Parallel Mode) | CLSR (Clear SR Fail Flags) | HPM (High Performance Enable Mode) | WPSEL (write protection selection) | SBLK (single block lock) *Note 2 | SBULK (single block unlock) |
|----------------|---------------------------------|---|---|------------------------------------|---|---|---|
| Command (hex) | 55 | 45 | 30 | A3 | 68 | 36 | 39 |
| Input Cycles | | | | | | ADD(24) | ADD(24) |
| Dummy Cycles | | | | | | | |
| Action | 8xI/O parallel programming mode | to exit 8xI/O parallel programming mode | clear security register bit 6 and bit 5 | Quad I/O high Performance mode | to enter and enable individual block protect mode | individual block (64K-byte) or sector (4K-byte) write protect | individual block (64K-byte) or sector (4K-byte) unprotect |

| COMMAND (byte) | RDBLOCK (block protect read) | GBLK (gang block lock) | GBULK (gang block unlock) |
|----------------|--|--------------------------|---------------------------|
| Command (hex) | 3C | 7E | 98 |
| Input Cycles | ADD(24) | | |
| Dummy Cycles | | | |
| Action | read individual block or sector write protect status | whole chip write protect | whole chip unprotect |

Notes:

1. It is not recommended to adopt any other code not in the command definition table, which will potentially enter the hidden mode.
- 2: In individual block write protection mode, all blocks/sectors is locked as default.

(1) Write Enable (WREN)

The Write Enable (WREN) instruction is for setting Write Enable Latch (WEL) bit. For those instructions like PP, 4PP, CP, SE, BE, BE32K, CE, WRSR, SBLK, SBULK, GBLK and GBULK, which are intended to change the device content, should be set every time after the WREN instruction setting the WEL bit.

The sequence of issuing WREN instruction is: CS# goes low→ sending WREN instruction code→ CS# goes high. (Please refer to [Figure 11](#))

(2) Write Disable (WRDI)

The Write Disable (WRDI) instruction is for resetting Write Enable Latch (WEL) bit.

The sequence of issuing WRDI instruction is: CS# goes low→ sending WRDI instruction code→ CS# goes high. (Please refer to [Figure 12](#))

The WEL bit is reset by following situations:

- Power-up
- Write Disable (WRDI) instruction completion
- Write Status Register (WRSR) instruction completion
- Page Program (PP, 4PP) instruction completion
- Sector Erase (SE) instruction completion
- Block Erase (BE, BE32K) instruction completion
- Chip Erase (CE) instruction completion
- Continuously Program mode (CP) instruction completion
- Single Block Lock/Unlock (SBLK/SBULK) instruction completion
- Gang Block Lock/Unlock (GBLK/GBULK) instruction completion

(3) Read Identification (RDID)

The RDID instruction is for reading the Manufacturer ID of 1-byte and followed by Device ID of 2-byte. The MXIC Manufacturer ID is C2(hex), the memory type ID is 20(hex) as the first-byte Device ID, and the individual Device ID of second-byte ID are listed as table of "[ID Definitions](#)". (Please refer to [Table 6](#))

The sequence of issuing RDID instruction is: CS# goes low→ sending RDID instruction code → 24-bits ID data out on SO→ to end RDID operation can use CS# to high at any time during data out. (Please refer to [Figure 13](#))

While Program/Erase operation is in progress, it will not decode the RDID instruction, so there's no effect on the cycle of program/erase operation which is currently in progress. When CS# goes high, the device is at standby stage.

(4) Read Status Register (RDSR)

The RDSR instruction is for reading Status Register. The Read Status Register can be read at any time (even in program/erase/write status register condition) and continuously. It is recommended to check the Write in Progress (WIP) bit before sending a new instruction when a program, erase, or write status register operation is in progress.

The sequence of issuing RDSR instruction is: CS# goes low→ sending RDSR instruction code→ Status Register data out on SO (Please refer to [Figure 14](#)).

The definition of the status register bits is as below:

WIP bit. The Write in Progress (WIP) bit, a volatile bit, indicates whether the device is busy in program/erase/write status register progress. When WIP bit sets to 1, which means the device is busy in program/erase/write status register progress. When WIP bit sets to 0, which means the device is not in progress of program/erase/write status register cycle.

WEL bit. The Write Enable Latch (WEL) bit, a volatile bit, indicates whether the device is set to internal write enable latch. When WEL bit sets to "1", which means the internal write enable latch is set, the device can accept program/erase/write status register instruction. When WEL bit sets to 0, which means no internal write enable latch; the device will not accept program/erase/write status register instruction. The program/erase command will be ignored and will reset WEL bit if it is applied to a protected memory area.

BP3, BP2, BP1, BP0 bits. The Block Protect (BP3, BP2, BP1, BP0) bits, non-volatile bits, indicate the protected area (as defined in Table 2) of the device to against the program/erase instruction without hardware protection mode being set. To write the Block Protect (BP3, BP2, BP1, BP0) bits requires the Write Status Register (WRSR) instruction to be executed. Those bits define the protected area of the memory to against Page Program (PP), Sector Erase (SE), Block Erase (BE) and Chip Erase (CE) instructions (only if all Block Protect bits set to 0, the CE instruction can be executed).

QE bit. The Quad Enable (QE) bit, non-volatile bit, while it is "0" (factory default), it performs non-Quad and WP# is enable. While QE is "1", it performs Quad I/O mode and WP# is disabled. In the other word, if the system goes into four I/O mode (QE=1), the feature of HPM will be disabled.

SRWD bit. The Status Register Write Disable (SRWD) bit, non-volatile bit, default value is "0". SRWD bit is operated together with Write Protection (WP#/SIO2) pin for providing hardware protection mode. The hardware protection mode requires SRWD sets to 1 and WP#/SIO2 pin signal is low stage. In the hardware protection mode, the Write Status Register (WRSR) instruction is no longer accepted for execution and the SRWD bit and Block Protect bits (BP3, BP2, BP1, BP0) are read only.

Status Register

| bit7 | bit6 | bit5 | bit4 | bit3 | bit2 | bit1 | bit0 |
|--------------------------------------|-------------------------------------|--------------------------------|--------------------------------|--------------------------------|--------------------------------|--------------------------------------|---|
| SRWD (status register write protect) | QE (Quad Enable) | BP3 (level of protected block) | BP2 (level of protected block) | BP1 (level of protected block) | BP0 (level of protected block) | WEL (write enable latch) | WIP (write in progress bit) |
| 1=status register write disable | 1= Quad Enable 0=not Quad Enable | (note 1) | (note 1) | (note 1) | (note 1) | 1=write enable 0=not write enable | 1=write operation 0=not in write operation |
| Non-volatile bit | Non-volatile bit | Non-volatile bit | Non-volatile bit | Non-volatile bit | Non-volatile bit | volatile bit | volatile bit |

Note: see the [Table 2 "Protected Area Size"](#) in page 11.

(5) Write Status Register (WRSR)

The WRSR instruction is for changing the values of Status Register Bits. Before sending WRSR instruction, the Write Enable (WREN) instruction must be decoded and executed to set the Write Enable Latch (WEL) bit in advance. The WRSR instruction can change the value of Block Protect (BP3, BP2, BP1, BP0) bits to define the protected area of memory (as shown in [Table 2](#)). The WRSR also can set or reset the Quad enable (QE) bit and set or reset the Status Register Write Disable (SRWD) bit in accordance with Write Protection (WP#/SIO2) pin signal, but has no effect on bit1(WEL) and bit0 (WIP) of the status register. The WRSR instruction cannot be executed once the Hardware Protected Mode (HPM) is entered.

The sequence of issuing WRSR instruction is: CS# goes low→ sending WRSR instruction code→ Status Register data on SI→ CS# goes high. (Please refer to [Figure 15](#))

The CS# must go high exactly at the byte boundary; otherwise, the instruction will be rejected and not executed. The self-timed Write Status Register cycle time (tW) is initiated as soon as Chip Select (CS#) goes high. The Write in Progress (WIP) bit still can be check out during the Write Status Register cycle is in progress. The WIP sets 1 during the tW timing, and sets 0 when Write Status Register Cycle is completed, and the Write Enable Latch (WEL) bit is reset.

Protection Modes

| Mode | Status register condition | WP# and SRWD bit status | Memory |
|--------------------------------|---|--|--|
| Software protection mode(SPM) | Status register can be written in (WEL bit is set to "1") and the SRWD, BP0-BP3 bits can be changed | WP#=1 and SRWD bit=0, or WP#=0 and SRWD bit=0, or WP#=1 and SRWD=1 | The protected area cannot be program or erase. |
| Hardware protection mode (HPM) | The SRWD, BP0-BP3 of status register bits cannot be changed | WP#=0, SRWD bit=1 | The protected area cannot be program or erase. |

Note: As defined by the values in the Block Protect (BP3, BP2, BP1, BP0) bits of the Status Register, as shown in [Table 2](#).

As the table above showing, the summary of the Software Protected Mode (SPM) and Hardware Protected Mode (HPM):

Software Protected Mode (SPM):

- When SRWD bit=0, no matter WP#/SIO2 is low or high, the WREN instruction may set the WEL bit and can change the values of SRWD, BP3, BP2, BP1, BP0. The protected area, which is defined by BP3, BP2, BP1, BP0, is at software protected mode (SPM).
- When SRWD bit=1 and WP#/SIO2 is high, the WREN instruction may set the WEL bit can change the values of SRWD, BP3, BP2, BP1, BP0. The protected area, which is defined by BP3, BP2, BP1, BP0, is at software protected mode (SPM)

Hardware Protected Mode (HPM):

- When SRWD bit=1, and then WP#/SIO2 is low (or WP#/SIO2 is low before SRWD bit=1), it enters the hardware protected mode (HPM). The data of the protected area is protected by software protected mode by BP3, BP2, BP1, BP0 and hardware protected mode by the WP#/SIO2 to against data modification.

Note:

To exit the hardware protected mode requires WP#/SIO2 driving high once the hardware protected mode is entered. If the WP#/SIO2 pin is permanently connected to high, the hardware protected mode can never be entered; only can use software protected mode via BP3, BP2, BP1, BP0.

If the system goes into four I/O mode, the feature of HPM will be disabled.

(6) Read Data Bytes (READ)

The read instruction is for reading data out. The address is latched on rising edge of SCLK, and data shifts out on the falling edge of SCLK at a maximum frequency f_R . The first address byte can be at any location. The address is automatically increased to the next higher address after each byte data is shifted out, so the whole memory can be read out at a single READ instruction. The address counter rolls over to 0 when the highest address has been reached.

The sequence of issuing READ instruction is: CS# goes low → sending READ instruction code → 3-byte address on SI → data out on SO → to end READ operation can use CS# to high at any time during data out. (Please refer to [Figure 16](#))

(7) Read Data Bytes at Higher Speed (FAST_READ)

The FAST_READ instruction is for quickly reading data out. The address is latched on rising edge of SCLK, and data of each bit shifts out on the falling edge of SCLK at a maximum frequency f_C . The first address byte can be at any location. The address is automatically increased to the next higher address after each byte data is shifted out, so the whole memory can be read out at a single FAST_READ instruction. The address counter rolls over to 0 when the highest address has been reached.

The sequence of issuing FAST_READ instruction is: CS# goes low → sending FAST_READ instruction code → 3-byte address on SI → 1-dummy byte (default) address on SI → data out on SO → to end FAST_READ operation can use CS# to high at any time during data out. (Please refer to [Figure 17](#))

While Program/Erase/Write Status Register cycle is in progress, FAST_READ instruction is rejected without any impact on the Program/Erase/Write Status Register current cycle.

(8) Fast Double Transfer Rate Read (FASTDTRD)

The FASTDTRD instruction is for doubling reading data out, signals are triggered on both rising and falling edge of clock. The address is latched on both rising and falling edge of SCLK, and data of each bit shifts out on both rising and falling edge of SCLK at a maximum frequency f_{C2} . The 2-bit address can be latched-in at one clock, and 2-bit data can be read out at one clock, which means one bit at rising edge of clock, the other bit at falling edge of clock. The first address byte can be at any location.

The address is automatically increased to the next higher address after each byte data is shifted out, so the whole memory can be read out at a single FASTDTRD instruction. The address counter rolls over to 0 when the highest address has been reached.

The sequence of issuing FASTDTRD instruction is: CS# goes low → sending FASTDTRD instruction code (1bit per clock) → 3-byte address on SI (2-bit per clock) → 6-dummy clocks (default) on SI → data out on SO (2-bit per clock) → to end FASTDTRD operation can use CS# to high at any time during data out. (Please refer to [Figure 18](#))

While Program/Erase/Write Status Register cycle is in progress, FASTDTRD instruction is rejected without any impact on the Program/Erase/Write Status Register current cycle.

(9) 2 x I/O Read Mode (2READ)

The 2READ instruction enables Double Transfer Rate of Serial Flash in read mode. The address is latched on rising edge of SCLK, and data of every two bits (interleave on 2 I/O pins) shift out on the falling edge of SCLK at a maxi-

maximum frequency fT . The first address byte can be at any location. The address is automatically increased to the next higher address after each byte data is shifted out, so the whole memory can be read out at a single 2READ instruction. The address counter rolls over to 0 when the highest address has been reached. Once writing 2READ instruction, the following address/dummy/data out will perform as 2-bit instead of previous 1-bit.

The sequence of issuing 2READ instruction is: CS# goes low → sending 2READ instruction → 24-bit address interleaved on SIO1 & SIO0 → 4-bit dummy cycle on SIO1 & SIO0 → data out interleaved on SIO1 & SIO0 → to end 2READ operation can use CS# to high at any time during data out (Please refer to [Figure 19 for 2 x I/O Read Mode Timing Waveform](#)).

While Program/Erase/Write Status Register cycle is in progress, 2READ instruction is rejected without any impact on the Program/Erase/Write Status Register current cycle.

(10) 2 x I/O Double Transfer Rate Read Mode (2DTRD)

The 2DTRD instruction enables Double Transfer Rate throughput on dual I/O of Serial Flash in read mode. The address (interleaved on dual I/O pins) is latched on both rising and falling edge of SCLK, and data (interleaved on dual I/O pins) shift out on both rising and falling edge of SCLK at a maximum frequency $fT2$. The 4-bit address can be latched-in at one clock, and 4-bit data can be read out at one clock, which means two bits at rising edge of clock, the other two bits at falling edge of clock. The first address byte can be at any location.

The address is automatically increased to the next higher address after each byte data is shifted out, so the whole memory can be read out at a single 2DTRD instruction. The address counter rolls over to 0 when the highest address has been reached. Once writing 2DTRD instruction, the following address/dummy/ data out will perform as 4-bit instead of previous 1-bit.

The sequence of issuing 2DTRD instruction is: CS# goes low → sending 2DTRD instruction (1-bit per clock) → 24-bit address interleaved on SIO1 & SIO0 (4-bit per clock) → 6-bit dummy clocks on SIO1 & SIO0 → data out interleaved on SIO1 & SIO0 (4-bit per clock) → to end 2DTRD operation can use CS# to high at any time during data out (Please refer to [Figure 20 for 2 x I/O Double Transfer Rate Read Mode Timing Waveform](#)).

While Program/Erase/Write Status Register cycle is in progress, 2DTRD instruction is rejected without any impact on the Program/Erase/Write Status Register current cycle.

(11) 4 x I/O Read Mode (4READ)

The 4READ instruction enables quad throughput of Serial Flash in read mode. A Quad Enable (QE) bit of status Register must be set to "1" before sending the 4READ instruction. The address is latched on rising edge of SCLK, and data of every four bits (interleaved on 4 I/O pins) shift out on the falling edge of SCLK at a maximum frequency fQ . The first address byte can be at any location. The address is automatically increased to the next higher address after each byte data is shifted out, so the whole memory can be read out at a single 4READ instruction. The address counter rolls over to 0 when the highest address has been reached. Once writing 4READ instruction, the following address/dummy/data out will perform as 4-bit instead of previous 1-bit.

The sequence of issuing 4READ instruction is: CS# goes low → sending 4READ instruction → 24-bit address interleaved on SIO3, SIO2, SIO1 & SIO0 → 6 dummy cycles → data out interleaved on SIO3, SIO2, SIO1 & SIO0 → to end 4READ operation can use CS# to high at any time during data out (Please refer to [Figure 21 for 4 x I/O Read Mode Timing Waveform](#)).

Another sequence of issuing 4READ instruction especially useful in random access is : CS# goes low → sending 4 READ instruction → 3-bytes address interleaved on SIO3, SIO2, SIO1 & SIO0 → performance enhance toggling bit

P[7:0] → 4 dummy cycles → data out still CS# goes high → CS# goes low (reduce 4 Read instruction) → 24-bit random access address (Please refer to [Figure 22 for 4x I/O Read Enhance Performance Mode timing waveform](#)).

In the performance-enhancing mode (Notes of [Figure 22](#)), P[7:4] must be toggling with P[3:0]; likewise P[7:0]=A5h, 5Ah, F0h or 0Fh can make this mode continue and reduce the next 4READ instruction. Once P[7:4] is no longer toggling with P[3:0]; likewise P[7:0]=FFh, 00h, AAh or 55h. These commands will reset the performance enhance mode. And afterwards CS# is raised and then lowered, the system then will return to normal operation.

While Program/Erase/Write Status Register cycle is in progress, 4READ instruction is rejected without any impact on the Program/Erase/Write Status Register current cycle.

(12) 4 x I/O Double Transfer Rate Read Mode (4DTRD)

The 4DTRD instruction enables Double Transfer Rate throughput on quad I/O of Serial Flash in read mode. A Quad Enable (QE) bit of status Register must be set to "1" before sending the 4DTRD instruction. The address (interleave on 4 I/O pins) is latched on both rising and falling edge of SCLK, and data (interleave on 4 I/O pins) shift out on both rising and falling edge of SCLK at a maximum frequency fQ2. The 8-bit address can be latched-in at one clock, and 8-bit data can be read out at one clock, which means four bits at rising edge of clock, the other four bits at falling edge of clock. The first address byte can be at any location. The address is automatically increased to the next higher address after each byte data is shifted out, so the whole memory can be read out at a single 4DTRD instruction. The address counter rolls over to 0 when the highest address has been reached. Once writing 4DTRD instruction, the following address/dummy/data out will perform as 8-bit instead of previous 1-bit.

The sequence of issuing 4DTRD instruction is: CS# goes low → sending 4DTRD instruction (1-bit per clock) → 24-bit address interleave on SIO3, SIO2, SIO1 & SIO0 (8-bit per clock) → 8 dummy clocks → data out interleave on SIO3, SIO2, SIO1 & SIO0 (8-bit per clock) → to end 4DTRD operation can use CS# to high at any time during data out (Please refer to [Figure 23 for 4 x I/O Read Mode Double Transfer Rate Timing Waveform](#)).

Another sequence of issuing enhanced mode of 4DTRD instruction especially useful in random access is: CS# goes low → sending 4DTRD instruction (1-bit per clock) → 3-bytes address interleave on SIO3, SIO2, SIO1 & SIO0 (8-bit per clock) → performance enhance toggling bit P[7:0] → 7 dummy clocks → data out (8-bit per clock) still CS# goes high → CS# goes low (eliminate 4 Read instruction) → 24-bit random access address (Please refer to [Figure 24 for 4x I/O Double Transfer Rate read enhance performance mode timing waveform](#)).

While Program/Erase/Write Status Register cycle is in progress, 4DTRD instruction is rejected without any impact on the Program/Erase/Write Status Register current cycle.

(13) Sector Erase (SE)

The Sector Erase (SE) instruction is for erasing the data of the chosen sector to be "1". The instruction is used for any 4K-byte sector. A Write Enable (WREN) instruction must execute to set the Write Enable Latch (WEL) bit before sending the Sector Erase (SE). Any address of the sector (see [Table 4](#)) is a valid address for Sector Erase (SE) instruction. The CS# must go high exactly at the byte boundary (the least significant bit of the address been latched-in); otherwise, the instruction will be rejected and not executed.

The sequence of issuing SE instruction is: CS# goes low → sending SE instruction code → 3-byte address on SI → CS# goes high. (Please refer to [Figure 25](#))

The self-timed Sector Erase Cycle time (tSE) is initiated as soon as Chip Select (CS#) goes high. The Write in Progress (WIP) bit still can be checked while the Sector Erase cycle is in progress. The WIP sets during the tSE timing, and clears when Sector Erase Cycle is completed, and the Write Enable Latch (WEL) bit is cleared. If the sector is protected by BP3~0 (WPSEL=0) or by individual lock (WPSEL=1), the array data will be protected (no change) and the WEL bit still be reset.

(14) Block Erase (BE)

The Block Erase (BE) instruction is for erasing the data of the chosen block to be "1". The instruction is used for 64K-byte block erase operation. A Write Enable (WREN) instruction must be executed to set the Write Enable Latch (WEL) bit before sending the Block Erase (BE). Any address of the block (see [Table 4](#)) is a valid address for Block Erase (BE) instruction. The CS# must go high exactly at the byte boundary (the least significant bit of address byte been latched-in); otherwise, the instruction will be rejected and not executed.

The sequence of issuing BE instruction is: CS# goes low → sending BE instruction code → 3-byte address on SI → CS# goes high. (Please refer to [Figure 26](#))

The self-timed Block Erase Cycle time (tBE) is initiated as soon as Chip Select (CS#) goes high. The Write in Progress (WIP) bit still can be checked while the Sector Erase cycle is in progress. The WIP sets during the tBE timing, and clears when Block Erase Cycle is completed, and the Write Enable Latch (WEL) bit is cleared. If the block is protected by BP3~0 (WPSEL=0) or by individual lock (WPSEL=1), the array data will be protected (no change) and the WEL bit still be reset.

(15) Block Erase (BE32K)

The Block Erase (BE32) instruction is for erasing the data of the chosen block to be "1". The instruction is used for 32K-byte block erase operation. A Write Enable (WREN) instruction must be executed to set the Write Enable Latch (WEL) bit before sending the Block Erase (BE32). Any address of the block (see [Table 4](#)) is a valid address for Block Erase (BE32) instruction. The CS# must go high exactly at the byte boundary (the least significant bit of address byte been latched-in); otherwise, the instruction will be rejected and not executed.

The sequence of issuing BE32 instruction is: CS# goes low → sending BE32 instruction code → 3-byte address on SI → CS# goes high. (Please refer to [Figure 26](#))

The self-timed Block Erase Cycle time (tBE) is initiated as soon as Chip Select (CS#) goes high. The Write in Progress (WIP) bit still can be checked while the Block Erase cycle is in progress. The WIP sets during the tBE timing, and clears when Block Erase Cycle is completed, and the Write Enable Latch (WEL) bit is cleared. If the block is protected by BP3~0 (WPSEL=0) or by individual lock (WPSEL=1), the array data will be protected (no change) and the WEL bit still be reset.

(16) Chip Erase (CE)

The Chip Erase (CE) instruction is for erasing the data of the whole chip to be "1". A Write Enable (WREN) instruction must be executed to set the Write Enable Latch (WEL) bit before sending the Chip Erase (CE). The CS# must go high exactly at the byte boundary; otherwise, the instruction will be rejected and not executed.

The sequence of issuing CE instruction is: CS# goes low → sending CE instruction code → CS# goes high. (Please refer to [Figure 27](#))

The self-timed Chip Erase Cycle time (tCE) is initiated as soon as Chip Select (CS#) goes high. The Write in Progress (WIP) bit still can be checked while the Chip Erase cycle is in progress. The WIP sets during the tCE timing, and clears when Chip Erase Cycle is completed, and the Write Enable Latch (WEL) bit is cleared. If the chip is protected the Chip Erase (CE) instruction will not be executed, but WEL will be reset.

(17) Page Program (PP)

The Page Program (PP) instruction is for programming the memory to be "0". A Write Enable (WREN) instruction must be executed to set the Write Enable Latch (WEL) bit before sending the Page Program (PP). The device programs only the last 256 data bytes sent to the device. If the entire 256 data bytes are going to be programmed, A7-A0 (the eight least significant address bits) should be set to 0. The last address byte (the 8 least significant address bits, A7-A0) should be set to 0 for 256 bytes page program. If A7-A0 are not all zero, transmitted data that exceed page length are programmed from the starting address (24-bit address that last 8 bit are all 0) of currently selected page. If the data bytes sent to the device exceeds 256, the last 256 data byte is programmed at the request page and previous data will be disregarded. If the data bytes sent to the device has not exceeded 256, the data will be programmed at the request address of the page. There will be no effort on the other data bytes of the same page.

The sequence of issuing PP instruction is: CS# goes low→ sending PP instruction code→ 3-byte address on SI→ at least 1-byte on data on SI→ CS# goes high. (Please refer to [Figure 28](#))

The CS# must be kept to low during the whole Page Program cycle; The CS# must go high exactly at the byte boundary(the latest eighth bit of data being latched in), otherwise, the instruction will be rejected and will not be executed.

The self-timed Page Program Cycle time (tPP) is initiated as soon as Chip Select (CS#) goes high. The Write in Progress (WIP) bit still can be checked while the Page Program cycle is in progress. The WIP sets during the tPP timing, and clears when Page Program Cycle is completed, and the Write Enable Latch (WEL) bit is cleared. If the page is protected by BP3~0 (WPSEL=0) or by individual lock (WPSEL=1), the array data will be protected (no change) and the WEL bit will still be reset.

(18) 4 x I/O Page Program (4PP)

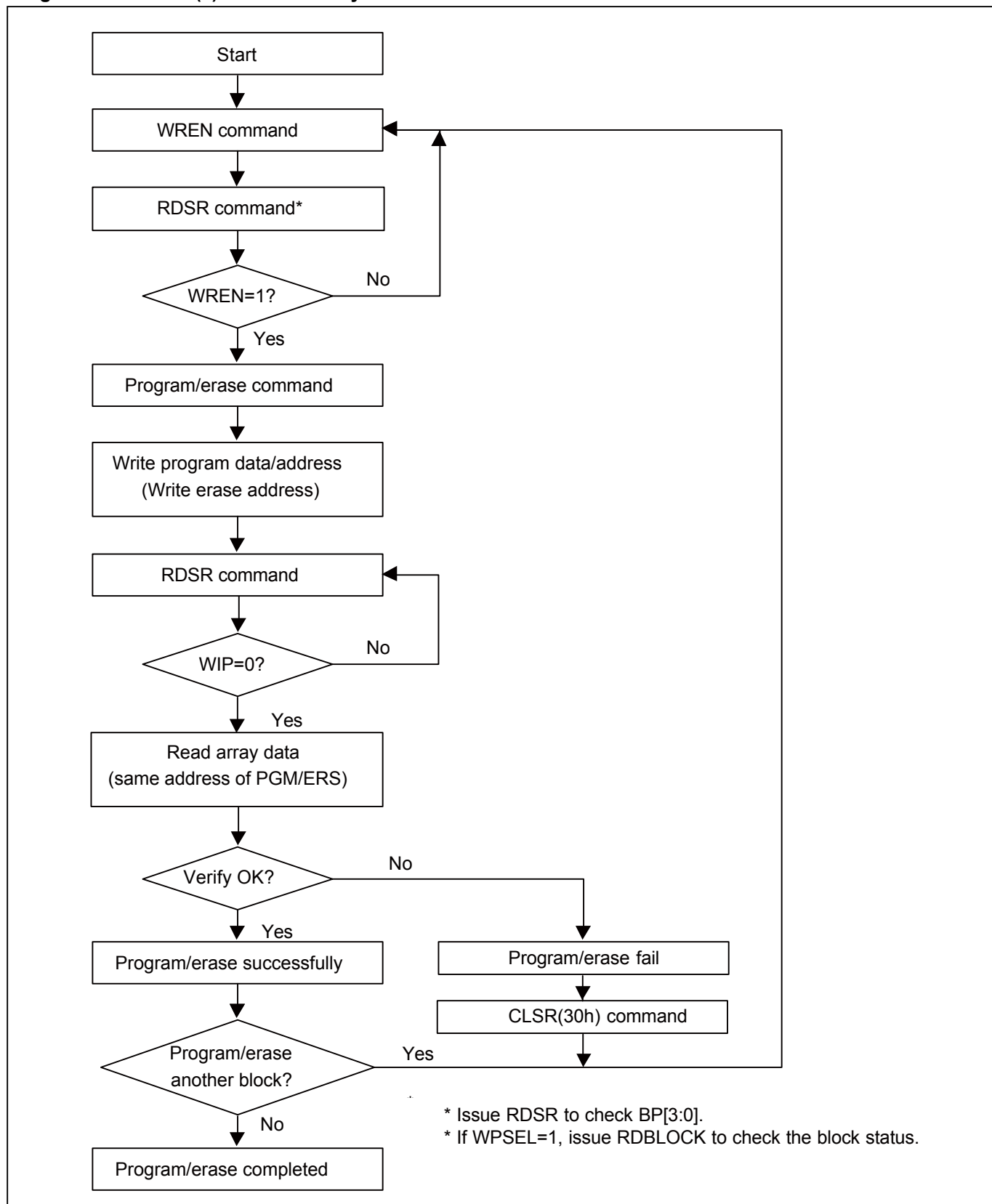
The Quad Page Program (4PP) instruction is for programming the memory to be "0". A Write Enable (WREN) instruction must be executed to set the Write Enable Latch (WEL) bit and Quad Enable (QE) bit must be set to "1" before sending the Quad Page Program (4PP). The Quad Page Programming takes four pins: SIO0, SIO1, SIO2, and SIO3, which can raise programer performance and and the effectiveness of application of lower clock less than 20MHz. For system with faster clock, the Quad page program cannot provide more performance, because the required internal page program time is far more than the time data flows in. Therefore, we suggest that while executing this command (especially during sending data), user can slow the clock speed down to 20MHz below. The other function descriptions are as same as standard page program.

The sequence of issuing 4PP instruction is: CS# goes low→ sending 4PP instruction code→ 3-byte address on SIO[3:0]→ at least 1-byte on data on SIO[3:0]→ CS# goes high. (Please refer to [Figure 29](#))

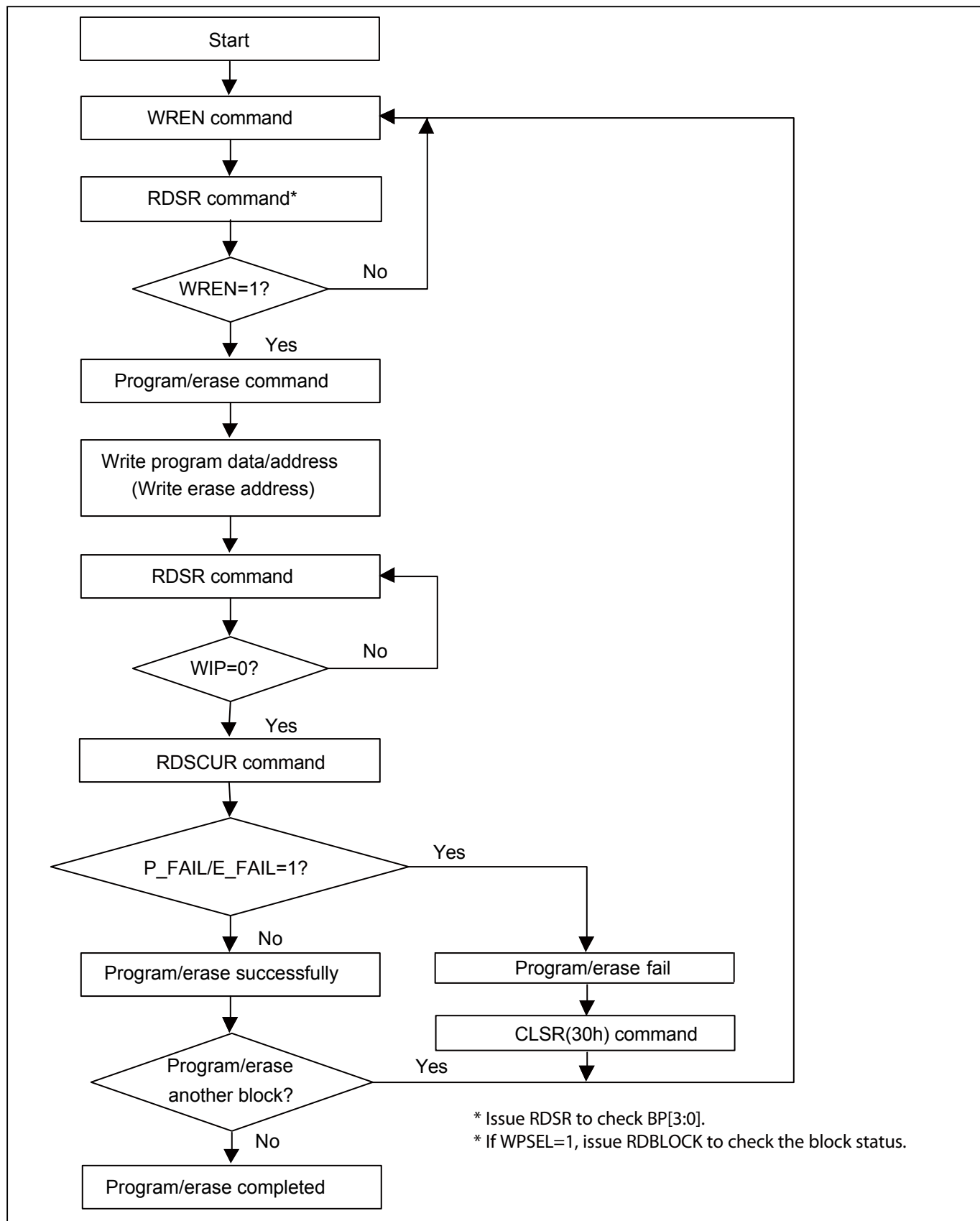
If the page is protected by BP3~0 (WPSEL=0) or by individual lock (WPSEL=1), the array data will be protected (no change) and the WEL bit will still be reset.

The Program/Erase function instruction function flow is as follows:

Program/Erase Flow(1) with read array data



Program/Erase Flow(2) without read array data



(19) Continuously program mode (CP mode)

The CP mode may enhance program performance by automatically increasing address to the next higher address after each byte data has been programmed.

The Continuously program (CP) instruction is for multiple byte program to Flash. A write Enable (WREN) instruction must execute to set the Write Enable Latch (WEL) bit before sending the Continuously program (CP) instruction. CS# requires to go high before CP instruction is executing. After CP instruction and address input, two bytes of data is input sequentially from MSB(bit7) to LSB(bit0). The first byte data will be programmed to the initial address range with A0=0 and second byte data with A0=1. If only one byte data is input, the CP mode will not process. If more than two bytes data are input, the additional data will be ignored and only two byte data are valid. Any byte to be programmed should be in the erase state (FF) first. It will not roll over during the CP mode, once the last unprotected address has been reached, the chip will exit CP mode and reset write Enable Latch bit (WEL) as "0" and CP mode bit as "0". Please check the WIP bit status if it is not in write progress before entering next valid instruction. During CP mode, the valid commands are CP command (AD hex), WRDI command (04 hex), RDSR command (05 hex), and RDSCUR command (2B hex). And the WRDI command is valid after completion of a CP programming cycle, which means the WIP bit=0.

The sequence of issuing CP instruction is : CS# goes low → sending CP instruction code → 3-byte address on SI pin → two data bytes on SI → CS# goes high to low → sending CP instruction and then continue two data bytes are programmed → CS# goes high to low → till last desired two data bytes are programmed → CS# goes high to low → sending WRDI (Write Disable) instruction to end CP mode → send RDSR instruction to verify if CP mode word program ends, or send RDSCUR to check bit4 to verify if CP mode ends. (Please refer to [Figure 30 of CP mode timing waveform](#))

Two methods to detect the completion of a program cycle during CP mode:

- 1) Software method-I: by checking WIP bit of Status Register to detect the completion of CP mode.
- 2) Software method-II: by waiting for a tBP time out to determine if it may load next valid command or not.

If the page is protected by BP3~0 (WPSEL=0) or by individual lock (WPSEL=1), the array data will be protected (no change) and the WEL bit will still be reset.

(20) Parallel Mode (Highly recommended for production throughputs increasing)

The parallel mode provides 8 bit inputs/outputs for increasing throughputs of factory production purpose. The parallel mode requires 55h command code, after writing the parallel mode command and then CS# going high, after that, the Memory can be available to accept RDID/RES & REMS/READ/PP command as the normal writing command procedure. To exit parallel mode, it requires 45h command code, or power-off/on sequence. The sequence of issuing Paralle Mode instruction is : CS# goes low→sending Parallel Mode Code→CS# goes high (Please refer to [Figure 31-1](#), and refer to [Figure 31-2~31-7](#) for other parallel mode).

- a. For normal write command (by SI), No effect
- b. Under parallel mode, the fastest access clock freq. will be changed to 6MHz (SCLK pin clock freq.)
- c. For parallel mode, the tV will be changed to 70ns.

(21) Deep Power-down (DP)

The Deep Power-down (DP) instruction is for setting the device to minimum power consumption (the standby current is reduced from ISB1 to ISB2). The Deep Power-down mode requires the Deep Power-down (DP) instruction to enter, during the Deep Power-down mode, the device is not active and all Write/Program/Erase instruction are ignored. When CS# goes high, the device is only in standby mode, not deep power-down mode. It's different from Standby mode.

The sequence of issuing DP instruction is: CS# goes low→ sending DP instruction code→ CS# goes high. (Please refer to [Figure 32](#))

Once the DP instruction is set, all instruction will be ignored except the Release from Deep Power-down mode (RDP) and Read Electronic Signature (RES) instruction. (those instructions allow the ID being reading out). When Power-down, the deep power-down mode automatically stops, and when power-up, the device automatically is in standby mode. For RDP instruction the CS# must go high exactly at the byte boundary (the latest eighth bit of instruction code been latched-in); otherwise, the instruction will not executed. As soon as Chip Select (CS#) goes high, a delay of tDP is required before entering the Deep Power-down mode and reducing the current to ISB2.

(22) Release from Deep Power-down (RDP), Read Electronic Signature (RES)

The Release from Deep Power-down (RDP) instruction is completed by driving Chip Select (CS#) High. When Chip Select (CS#) is driven High, the device is put in the standby Power mode. If the device was not previously in the Deep Power-down mode, the transition to the standby Power mode is immediate. If the device was previously in the Deep Power-down mode, though, the transition to the standby Power mode is delayed by tRES2, and Chip Select (CS#) must remain High for at least tRES2(max), as specified in [Table 8](#). Once in the standby mode, the device waits to be selected, so that it can receive, decode and execute instructions.

RES instruction is for reading out the old style of 8-bit Electronic Signature, whose values are shown as table of [ID Definitions](#). This is not the same as RDID instruction. It is not recommended to use for new design. For new design, please use RDID instruction. Even in [Deep power-down](#) mode, the RDP and RES are also allowed to be executed, only except the device is in progress of program/erase/write cycles; there's no effect on the current program/erase/write cycles in progress. The sequence is shown as [Figure 33, 34](#).

The RES instruction is ended by CS# goes high after the ID been read out at least once. The ID outputs repeatedly if continuously send the additional clock cycles on SCLK while CS# is at low. If the device was not previously in [Deep Power-down](#) mode, the device transition to standby mode is immediate. If the device was previously in [Deep Power-down](#) mode, there's a delay of tRES2 to transit to standby mode, and CS# must remain to high at least tRES2(max). Once in the standby mode, the device waits to be selected, so it can be receive, decode, and execute instruction.

The RDP instruction is for releasing from [Deep Power-down](#) Mode.

(23) Read Electronic Manufacturer ID & Device ID (REMS), (REMS2), (REMS4), (REMS4D)

The REMS, REMS2, REMS4 and REMS4D instruction provides both the JEDEC assigned Manufacturer ID and the specific Device ID.

The instruction is initiated by driving the CS# pin low and shift the instruction code "90h", "CFh", "DFh" or "EFh" followed by two dummy bytes and one bytes address (A7~A0). After which, the Manufacturer ID for MXIC (C2h) and the Device ID are shifted out on the falling edge of SCLK with most significant bit (MSB) first as shown in Figure 34. The Device ID values are listed in table of [ID Definitions](#). If the one-byte address is initially set to 01h, then the Device ID will be read first and then followed by the Manufacturer ID. The Manufacturer and Device IDs can be read continuously, alternating from one to the other. The instruction is completed by driving CS# high.

Table 6. ID Definitions

| Command Type | MX25L12845E | | |
|-------------------------|-----------------|-------------|----------------|
| RDID | manufacturer ID | memory type | memory density |
| | C2 | 20 | 18 |
| RES | electronic ID | | |
| | 17 | | |
| REMS/REMS2/REMS4/REMS4D | manufacturer ID | device ID | |
| | C2 | 17 | |

(24) Enter Secured OTP (ENSO)

The ENSO instruction is for entering the additional 4K-bit Secured OTP mode. While the device is in 4K-bit Secured OTP mode, array access is not available. The additional 4K-bit Secured OTP is independent from main array and may be used to store unique serial number for system identifier. After entering the Secured OTP mode, follow standard read or program procedure to read out the data or update data. The Secured OTP data cannot be updated again once it is lock-down.

The sequence of issuing ENSO instruction is: CS# goes low→ sending ENSO instruction to enter Secured OTP mode→ CS# goes high.

Please note that WRSR/WRSCUR/WPSEL/SBLK/GBLK/SBULK/GBULK/CE/BE/SE/BE32K commands are not acceptable during the access of secure OTP region. Once Security OTP is lock down, only read related commands are valid.

(25) Exit Secured OTP (EXSO)

The EXSO instruction is for exiting the additional 4K-bit Secured OTP mode.

The sequence of issuing EXSO instruction is: CS# goes low→ sending EXSO instruction to exit Secured OTP mode→ CS# goes high.

(26) Read Security Register (RDSCUR)

The RDSCUR instruction is for reading the value of Security Register. The Read Security Register can be read at any time (even in program/erase/write status register/write security register condition) and continuously.

The sequence of issuing RDSCUR instruction is : CS# goes low→ sending RDSCUR instruction → Security Register data out on SO→ CS# goes high.

The definition of the Security Register is as below:

Secured OTP Indicator bit. The Secured OTP indicator bit shows the chip is locked by factory or not. When it is "0", it indicates non-factory lock; "1" indicates factory- lock.

Lock-down Secured OTP (LDSO) bit. By writing WRSCUR instruction, the LDSO bit may be set to "1" for customer lock-down purpose. However, once the bit is set to "1" (lock-down), the LDSO bit and the 4K-bit Secured OTP area cannot be updated any more.

Continuously Program Mode(CP mode) bit. The Continuously Program Mode bit indicates the status of CP mode, "0" indicates not in CP mode; "1" indicates in CP mode.

Program Fail Flag bit. While a program failure happened, the Program Fail Flag bit would be set. This bit will also be set when the user attempts to program a protected main memory region or a locked OTP region. This bit can indicate whether one or more of program operations fail, and can be reset by command CLSR (30h)

Erase Fail Flag bit. While a erase failure happened, the Erase Fail Flag bit would be set. This bit will also be set when the user attempts to erase a protected main memory region or a locked OTP region. This bit can indicate whether one or more of erase operations fail, and can be reset by command CLSR (30h)

Write Protection Select bit. The Write Protection Select bit indicates that WPSEL has been executed successfully. Once this bit has been set (WPSEL=1), all the blocks or sectors will be write-protected after the power-on every time. Once WPSEL has been set, it cannot be changed again, which means it's only for individual WP mode.

Under the individual block protection mode (WPSEL=1), hardware protection is performed by driving WP#=0. Once WP#=0 all array blocks/sectors are protected regardless of the contents of SRAM lock bits.

Security Register Definition

| bit7 | bit6 | bit5 | bit4 | bit3 | bit2 | bit1 | bit0 |
|--|---|---|--|--------------|--------------|--|---|
| WPSEL | E_FAIL | P_FAIL | Continuously Program mode (CP mode) | x | x | LDSO (lock-down 4K-bit Secured OTP) | 4K-bit Secured OTP |
| 0=normal WP mode 1=individual WP mode (default=0) | 0=normal Erase succeed 1=indicate Erase failed (default=0) | 0=normal Program succeed 1=indicate Program failed (default=0) | 0=normal Program mode 1=CP mode (default=0) | reserved | reserved | 0 = not lockdown 1 = lock-down (cannot program/erase OTP) | 0 = nonfactory lock 1 = factory lock |
| non-volatile bit | volatile bit | volatile bit | volatile bit | volatile bit | volatile bit | non-volatile bit | non-volatile bit |
| OTP | Read Only | Read Only | Read Only | Read Only | Read Only | OTP | Read Only |

(27) Write Security Register (WRSCUR)

The WRSCUR instruction is for changing the values of Security Register Bits. Unlike write status register, the WREN instruction is not required before sending WRSCUR instruction. The WRSCUR instruction may change the values of bit1 (LDSO bit) for customer to lock-down the 4K-bit Secured OTP area. Once the LDSO bit is set to "1", the Secured OTP area cannot be updated any more.

The sequence of issuing WRSCUR instruction is :CS# goes low→ sending WRSCUR instruction → CS# goes high.

The CS# must go high exactly at the boundary; otherwise, the instruction will be rejected and not executed.

(28) Write Protection Selection (WPSEL)

There are two write protection methods, (1) BP protection mode (2) individual block protection mode. If WPSEL=0, flash is under BP protection mode. If WPSEL=1, flash is under individual block protection mode. The default value of WPSEL is "0". WPSEL command can be used to set WPSEL=1. **Please note that WPSEL is an OTP bit. Once WPSEL is set to 1, there is no chance to recovery WPSEL back to "0".** If the flash is put on BP mode, the individual block protection mode is disabled. Contrarily, if flash is on the individual block protection mode, the BP mode is disabled.

Every time after the system is powered-on, the Security Register bit 7 is checked. If WPSEL=1, all the blocks and sectors will be write protected by default. User may only unlock the blocks or sectors via SBULK and GBULK instructions. Program or erase functions can only be operated after the Unlock instruction is executed.

BP protection mode, WPSEL=0:

ARRAY is protected by BP3~BP0 and BP3~BP0 bits are protected by "SRWD=1 and WP#=0", where SRWD is bit 7 of status register that can be set by WRSR command.

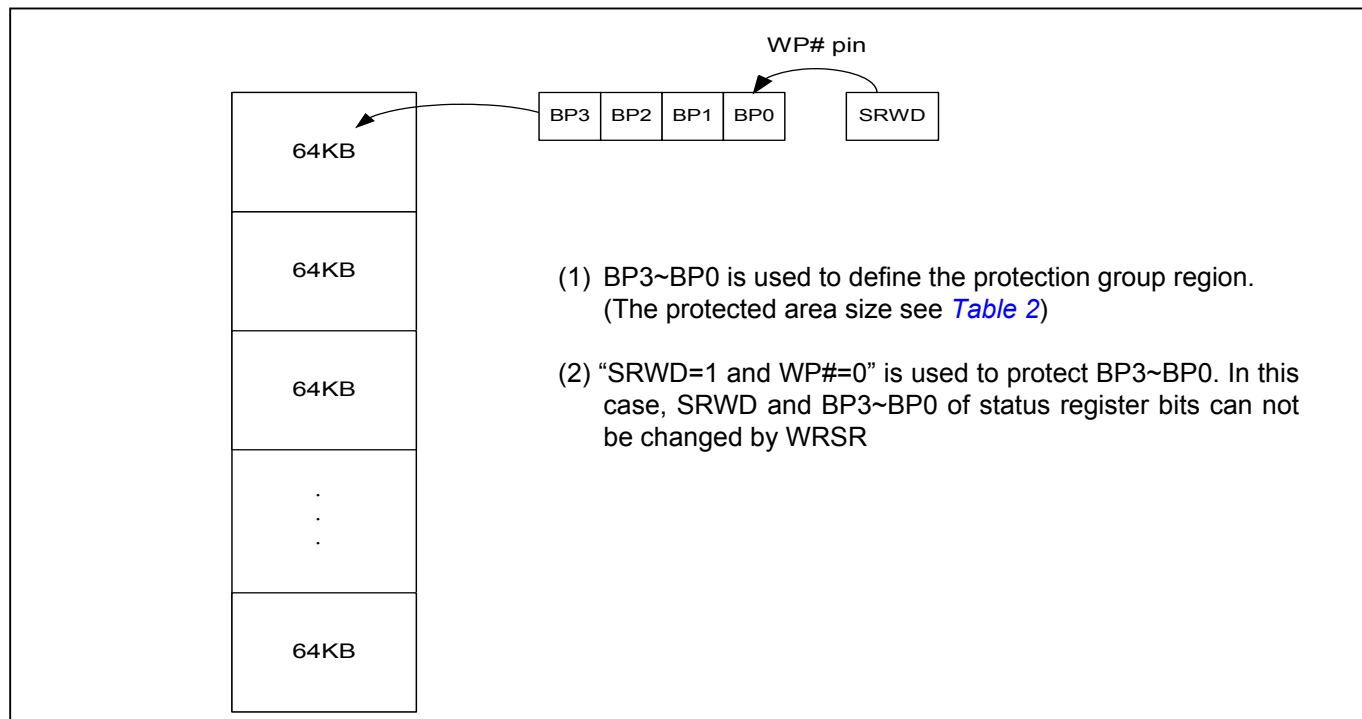
Individual block protection mode, WPSEL=1:

Blocks are individually protected by their own SRAM lock bits which are set to "1" after power up. SBULK and SBLK command can set SRAM lock bit to "0" and "1". When the system accepts and executes WPSEL instruction, the bit 7 in security register will be set. It will activate SBLK, SBULK, RDBLOCK, GBLK, GBULK etc instructions to conduct block lock protection and replace the original Software Protect Mode (SPM) use (BP3~BP0) indicated block methods. Under the individual block protection mode (WPSEL=1), hardware protection is performed by driving WP#=0. Once WP#=0 all array blocks/sectors are protected regardless of the contents of SRAM lock bits.

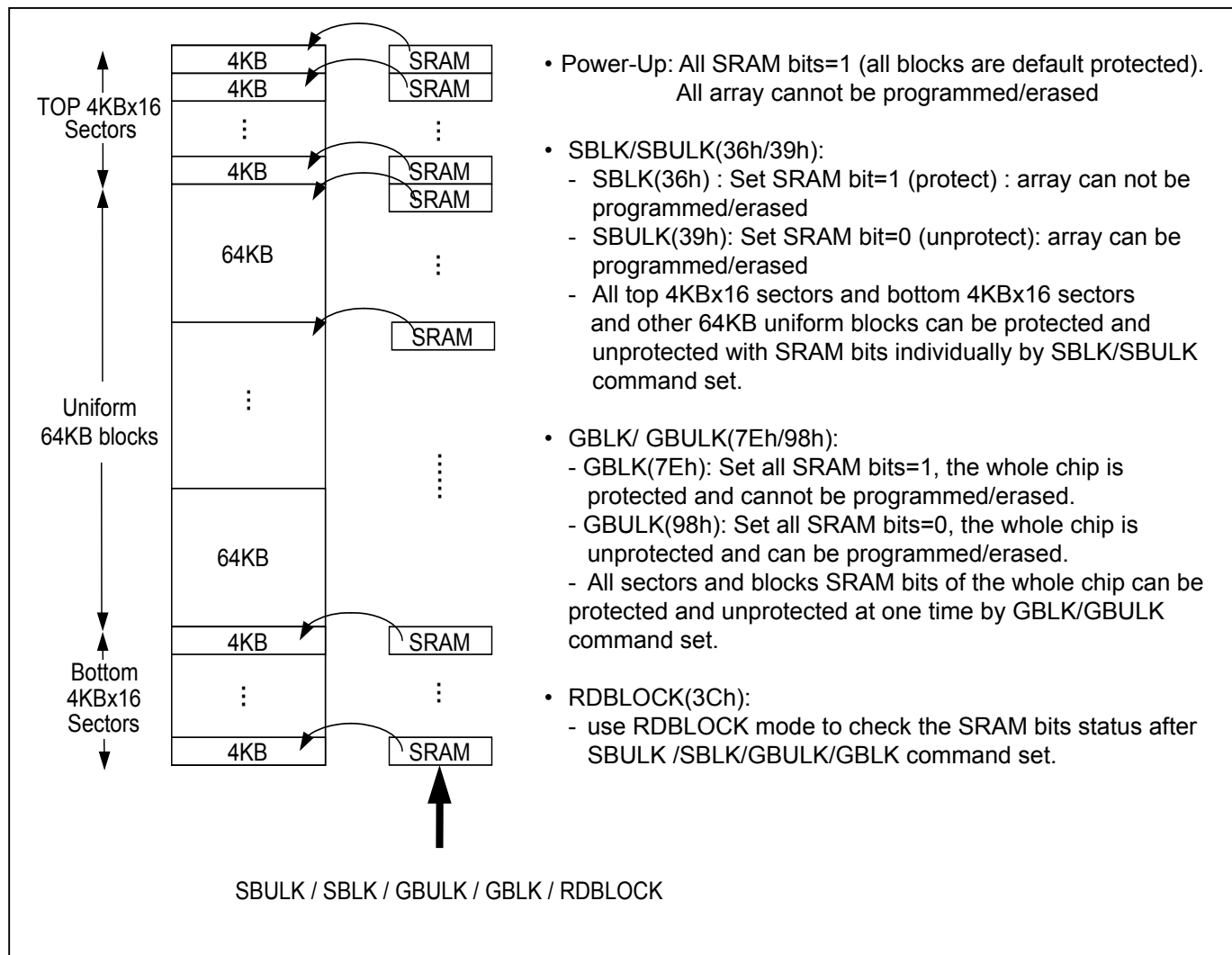
The sequence of issuing WPSEL instruction is: CS# goes low → sending WPSEL instruction to enter the individual block protect mode → CS# goes high.

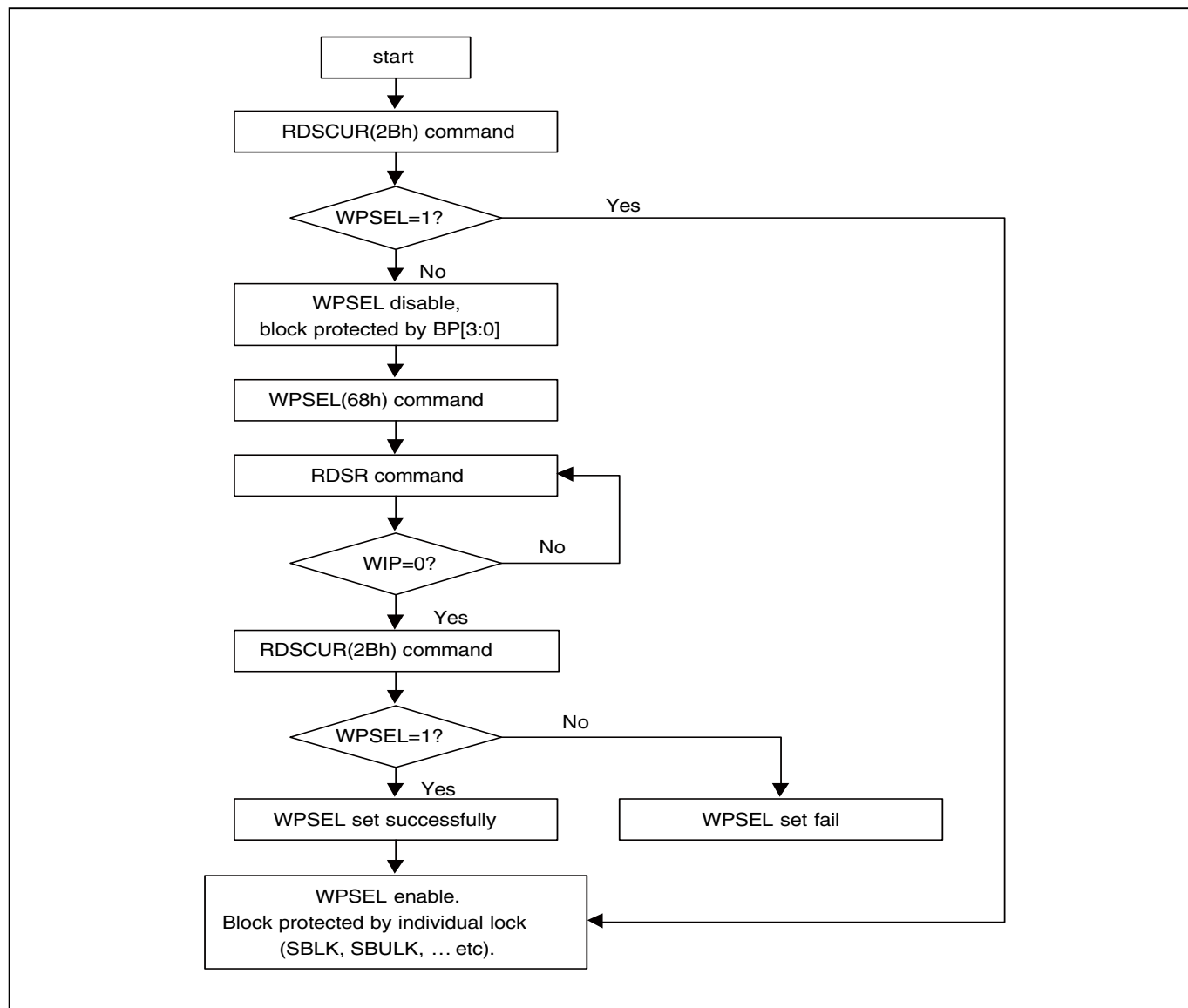
WPSEL instruction function flow is as follows:

BP and SRWD if WPSEL=0



The individual block lock mode is effective after setting WPSEL=1



WPSEL Flow

(29) Single Block Lock/Unlock Protection (SBLK/SBULK)

These instructions are only effective after WPSEL was executed. The SBLK instruction is for write protection a specified block(or sector) of memory, using A23-A16 or (A23-A12) address bits to assign a 64Kbyte block (or 4K bytes sector) to be protected as read only. The SBULK instruction will cancel the block (or sector) write protection state. This feature allows user to stop protecting the entire block (or sector) through the chip unprotect command (GBULK).

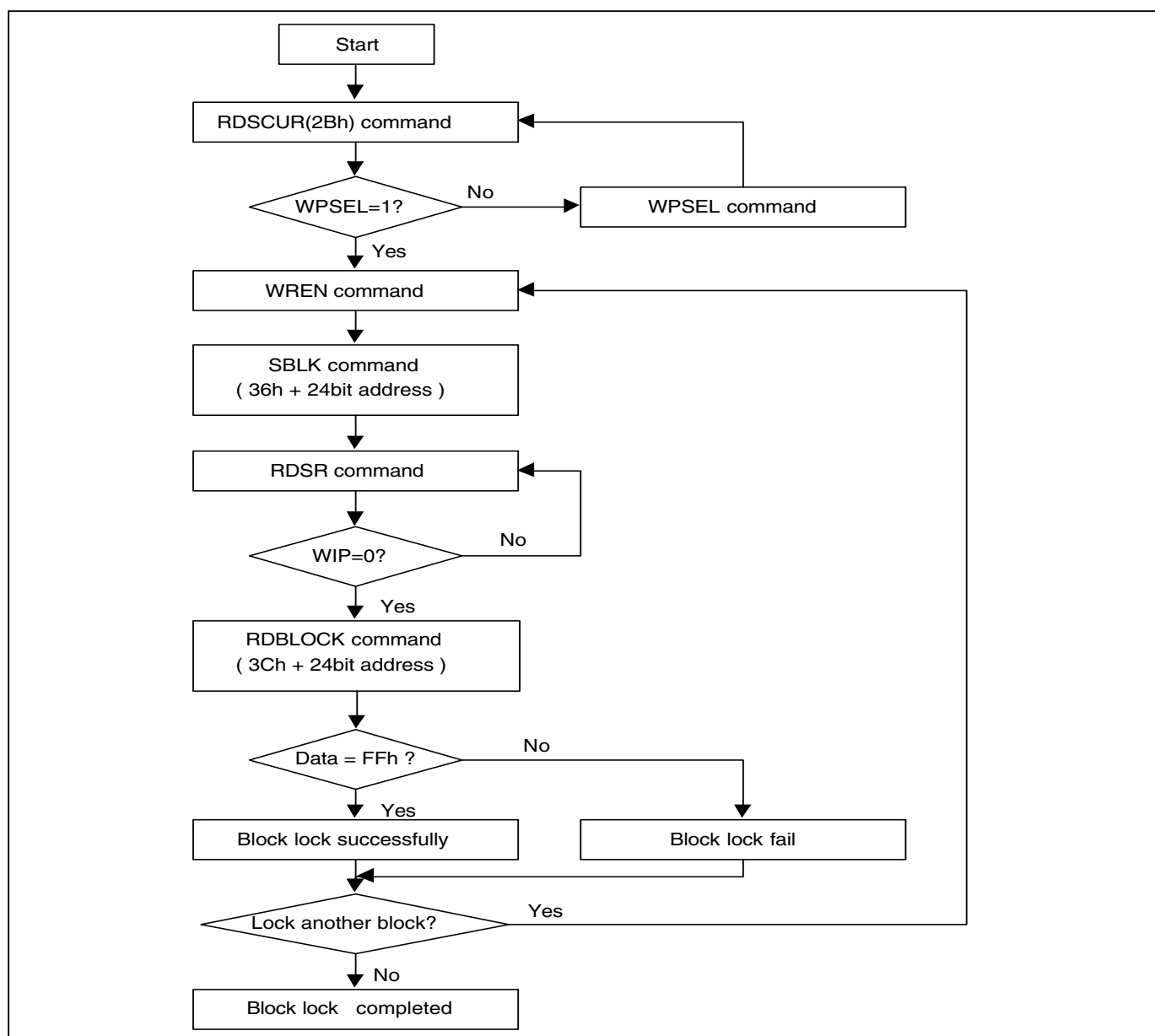
The WREN (Write Enable) instruction is required before issuing SBLK/SBULK instruction.

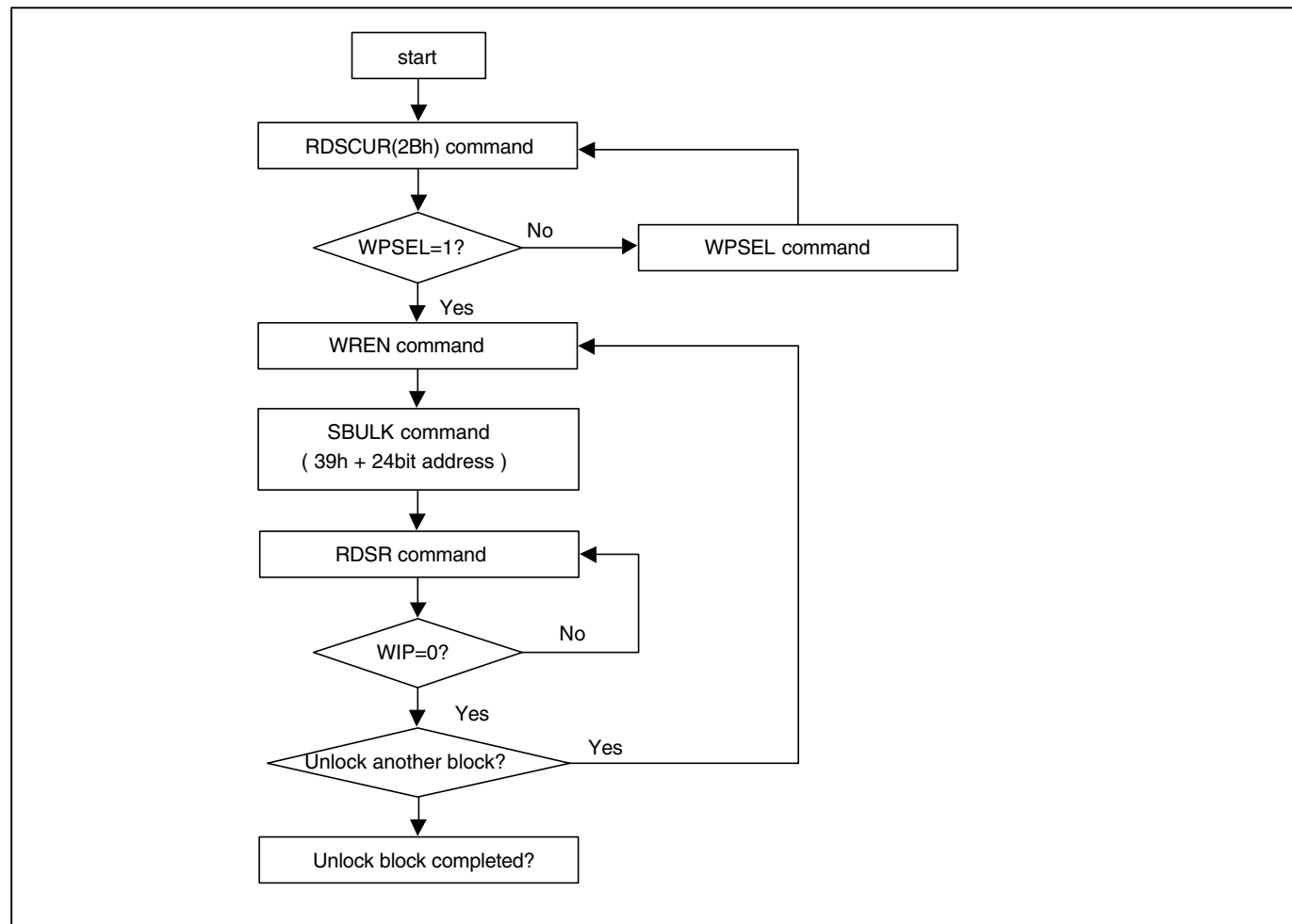
The sequence of issuing SBLK/SBULK instruction is: CS# goes low → send SBLK/SBULK (36h/39h) instruction → send 3 address bytes assign one block (or sector) to be protected on SI pin → CS# goes high. (Please refer to [Figure 37](#))

The CS# must go high exactly at the byte boundary, otherwise the instruction will be rejected and not be executed.

SBLK/SBULK instruction function flow is as follows:

Block Lock Flow



Block Unlock Flow

(30) Read Block Lock Status (RDBLOCK)

This instruction is only effective after WPSEL was executed. The RDBLOCK instruction is for reading the status of protection lock of a specified block(or sector), using A23-A16 (or A23-A12) address bits to assign a 64K bytes block (4K bytes sector) and read protection lock status bit which the first byte of Read-out cycle. The status bit is "1" to indicate that this block has be protected, that user can read only but cannot write/program /erase this block. The status bit is "0" to indicate that this block hasn't be protected, and user can read and write this block.

The sequence of issuing RDBLOCK instruction is: CS# goes low → send RDBLOCK (3Ch) instruction → send 3 address bytes to assign one block on SI pin → read block's protection lock status bit on SO pin → CS# goes high. (Please refer to [Figure 38](#))

(31) Gang Block Lock/Unlock (GBLK/GBULK)

These instructions are only effective after WPSEL was executed. The GBLK/GBULK instruction is for enable/disable the lock protection block of the whole chip.

The WREN (Write Enable) instruction is required before issuing GBLK/GBULK instruction.

The sequence of issuing GBLK/GBULK instruction is: CS# goes low → send GBLK/GBULK (7Eh/98h) instruction → CS# goes high. (Please refer to [Figure 39](#))

The CS# must go high exactly at the byte boundary, otherwise, the instruction will be rejected and not be executed.

(32) Clear SR Fail Flags (CLSR)

The CLSR instruction is for resetting the Program/Erase Fail Flag bit of Security Register. It should be executed before program/erase another block during programming/erasing flow without read array data.

The sequence of issuing CLSR instruction is: CS# goes low → send CLSR instruction code → CS# goes high.

The CS# must go high exactly at the byte boundary; otherwise, the instruction will be rejected and not executed.

(33) Read SFDP Mode (RDSFDP)

The Serial Flash Discoverable Parameter (SFDP) standard provides a consistent method of describing the functional and feature capabilities of serial flash devices in a standard set of internal parameter tables. These parameter tables can be interrogated by host system software to enable adjustments needed to accommodate divergent features from multiple vendors. The concept is similar to the one found in the Introduction of JEDEC Standard, JESD68 on CFI.

The sequence of issuing RDSFDP instruction is CS# goes low→send RDSFDP instruction (5Ah)→send 3 address bytes on SI pin→send 1 dummy byte on SI pin→read SFDP code on SO→to end RDSFDP operation can use CS# to high at any time during data out.

SFDP is a standard of JEDEC. JESD216. v1.0.

Read Serial Flash Discoverable Parameter (RDSFDP) Sequence

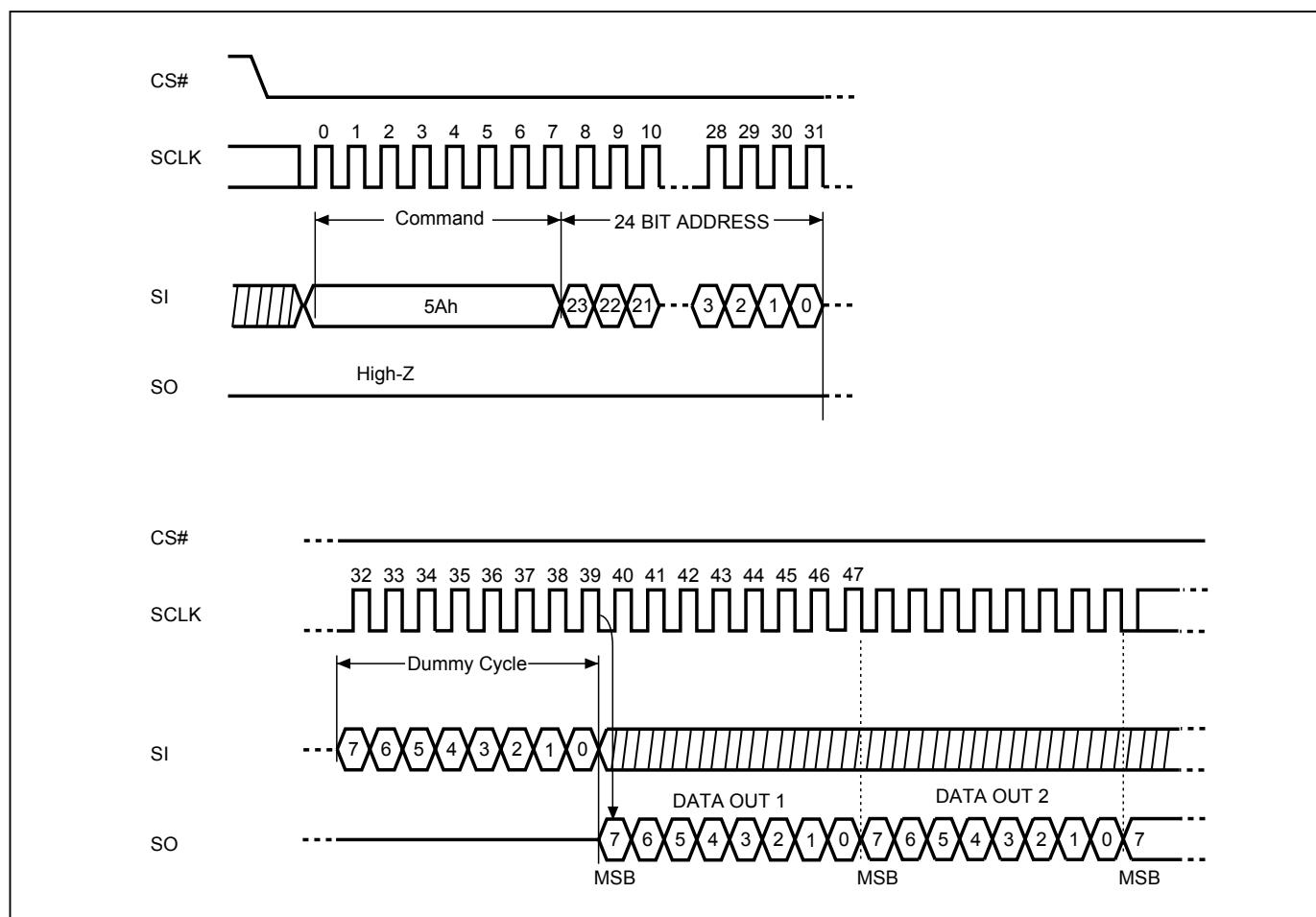


Table a. Signature and Parameter Identification Data Values

| Description | Comment | Add (h) (Byte) | DW Add (Bit) | Data (h/b) (Note1) | Data (h) |
|--|---|-------------------|-----------------|-----------------------|-------------|
| SFDP Signature | Fixed: 50444653h | 00h | 07:00 | 53h | 53h |
| | | 01h | 15:08 | 46h | 46h |
| | | 02h | 23:16 | 44h | 44h |
| | | 03h | 31:24 | 50h | 50h |
| SFDP Minor Revision Number | Start from 00h | 04h | 07:00 | 00h | 00h |
| SFDP Major Revision Number | Start from 01h | 05h | 15:08 | 01h | 01h |
| Number of Parameter Headers | Start from 01h | 06h | 23:16 | 01h | 01h |
| Unused | | 07h | 31:24 | FFh | FFh |
| ID number (JEDEC) | 00h: it indicates a JEDEC specified header. | 08h | 07:00 | 00h | 00h |
| Parameter Table Minor Revision Number | Start from 00h | 09h | 15:08 | 00h | 00h |
| Parameter Table Major Revision Number | Start from 01h | 0Ah | 23:16 | 01h | 01h |
| Parameter Table Length (in double word) | How many DWORDs in the Parameter table | 0Bh | 31:24 | 09h | 09h |
| Parameter Table Pointer (PTP) | First address of JEDEC Flash Parameter table | 0Ch | 07:00 | 30h | 30h |
| | | 0Dh | 15:08 | 00h | 00h |
| | | 0Eh | 23:16 | 00h | 00h |
| Unused | | 0Fh | 31:24 | FFh | FFh |
| ID number (Macronix manufacturer ID) | it indicates Macronix manufacturer ID | 10h | 07:00 | C2h | C2h |
| Parameter Table Minor Revision Number | Start from 00h | 11h | 15:08 | 00h | 00h |
| Parameter Table Major Revision Number | Start from 01h | 12h | 23:16 | 01h | 01h |
| Parameter Table Length (in double word) | How many DWORDs in the Parameter table | 13h | 31:24 | 04h | 04h |
| Parameter Table Pointer (PTP) | First address of Macronix Flash Parameter table | 14h | 07:00 | 60h | 60h |
| | | 15h | 15:08 | 00h | 00h |
| | | 16h | 23:16 | 00h | 00h |
| Unused | | 17h | 31:24 | FFh | FFh |

Table b. Parameter Table (0): JEDEC Flash Parameter Tables

| Description | Comment | Add (h) (Byte) | DW Add (Bit) | Data (h/b) (Note1) | Data (h) |
|---|--|-------------------|-----------------|-----------------------|-------------|
| Block/Sector Erase sizes | 00: Reserved, 01: 4KB erase, 10: Reserved, 11: not support 4KB erase | 30h | 01:00 | 01b | E5h |
| Write Granularity | 0: 1Byte, 1: 64Byte or larger | | 02 | 1b | |
| Write Enable Instruction Requested for Writing to Volatile Status Registers | 0: Nonvolatile status bit 1: Volatile status bit (BP status register bit) | | 03 | 0b | |
| Write Enable Opcode Select for Writing to Volatile Status Registers | 0: use 50h opcode, 1: use 06h opcode Note: If target flash status register is nonvolatile, then bits 3 and 4 must be set to 00b. | | 04 | 0b | |
| Unused | Contains 111b and can never be changed | | 07:05 | 111b | |
| 4KB Erase Opcode | | 31h | 15:08 | 20h | 20h |
| (1-1-2) Fast Read (Note2) | 0=not support 1=support | 32h | 16 | 0b | B8h |
| Address Bytes Number used in addressing flash array | 00: 3Byte only, 01: 3 or 4Byte, 10: 4Byte only, 11: Reserved | | 18:17 | 00b | |
| Double Transfer Rate (DTR) Clocking | 0=not support 1=support | | 19 | 1b | |
| (1-2-2) Fast Read | 0=not support 1=support | | 20 | 1b | |
| (1-4-4) Fast Read | 0=not support 1=support | | 21 | 1b | |
| (1-1-4) Fast Read | 0=not support 1=support | | 22 | 0b | |
| Unused | | | 23 | 1b | |
| Unused | | 33h | 31:24 | FFh | FFh |
| Flash Memory Density | | 37h:34h | 31:00 | 07FFFFFFh | |
| (1-4-4) Fast Read Number of Wait states (Note3) | 0 0000b: Wait states (Dummy Clocks) not support | 38h | 04:00 | 0 0100b | 44h |
| (1-4-4) Fast Read Number of Mode Bits (Note4) | 000b: Mode Bits not support | | 07:05 | 010b | |
| (1-4-4) Fast Read Opcode | | 39h | 15:08 | EBh | EBh |
| (1-1-4) Fast Read Number of Wait states | 0 0000b: Wait states (Dummy Clocks) not support | 3Ah | 20:16 | 0 0000b | 00h |
| (1-1-4) Fast Read Number of Mode Bits | 000b: Mode Bits not support | | 23:21 | 000b | |
| (1-1-4) Fast Read Opcode | | 3Bh | 31:24 | FFh | FFh |

| Description | Comment | Add (h) (Byte) | DW Add (Bit) | Data (h/b) (Note1) | Data (h) |
|---|---|-------------------|-----------------|-----------------------|-------------|
| (1-1-2) Fast Read Number of Wait states | 0 0000b: Wait states (Dummy Clocks) not support | 3Ch | 04:00 | 0 0000b | 00h |
| (1-1-2) Fast Read Number of Mode Bits | 000b: Mode Bits not support | | 07:05 | 000b | |
| (1-1-2) Fast Read Opcode | | 3Dh | 15:08 | 0xFFh | 0xFFh |
| (1-2-2) Fast Read Number of Wait states | 0 0000b: Wait states (Dummy Clocks) not support | 3Eh | 20:16 | 0 0100b | 04h |
| (1-2-2) Fast Read Number of Mode Bits | 000b: Mode Bits not support | | 23:21 | 000b | |
| (1-2-2) Fast Read Opcode | | 3Fh | 31:24 | BBh | BBh |
| (2-2-2) Fast Read | 0=not support 1=support | 40h | 00 | 0b | EEh |
| Unused | | | 03:01 | 111b | |
| (4-4-4) Fast Read | 0=not support 1=support | | 04 | 0b | |
| Unused | | | 07:05 | 111b | |
| Unused | | 43h:41h | 31:08 | 0xFFh | 0xFFh |
| Unused | | 45h:44h | 15:00 | 0xFFh | 0xFFh |
| (2-2-2) Fast Read Number of Wait states | 0 0000b: Wait states (Dummy Clocks) not support | 46h | 20:16 | 0 000b | 00h |
| (2-2-2) Fast Read Number of Mode Bits | 000b: Mode Bits not support | | 23:21 | 000b | |
| (2-2-2) Fast Read Opcode | | 47h | 31:24 | FFh | FFh |
| Unused | | 49h:48h | 15:00 | 0xFFh | 0xFFh |
| (4-4-4) Fast Read Number of Wait states | 0 0000b: Wait states (Dummy Clocks) not support | 4Ah | 20:16 | 0 0000b | 00h |
| (4-4-4) Fast Read Number of Mode Bits | 000b: Mode Bits not support | | 23:21 | 000b | |
| (4-4-4) Fast Read Opcode | | 4Bh | 31:24 | FFh | FFh |
| Sector Type 1 Size | Sector/block size = 2 ^N bytes (Note5) 0x00b: this sector type doesn't exist | 4Ch | 07:00 | 0Ch | 0Ch |
| Sector Type 1 erase Opcode | | 4Dh | 15:08 | 20h | 20h |
| Sector Type 2 Size | Sector/block size = 2 ^N bytes 0x00b: this sector type doesn't exist | 4Eh | 23:16 | 0Fh | 0Fh |
| Sector Type 2 erase Opcode | | 4Fh | 31:24 | 52h | 52h |
| Sector Type 3 Size | Sector/block size = 2 ^N bytes 0x00b: this sector type doesn't exist | 50h | 07:00 | 10h | 10h |
| Sector Type 3 erase Opcode | | 51h | 15:08 | D8h | D8h |
| Sector Type 4 Size | Sector/block size = 2 ^N bytes 0x00b: this sector type doesn't exist | 52h | 23:16 | 00h | 00h |
| Sector Type 4 erase Opcode | | 53h | 31:24 | FFh | FFh |

Table c. Parameter Table (1): Macronix Flash Parameter Tables

| Description | Comment | Add (h) (Byte) | DW Add (Bit) | Data (h/b) (Note1) | Data (h) |
|---|---|-------------------|-----------------|-----------------------|-------------|
| Vcc Supply Maximum Voltage | 2000h=2.000V 2700h=2.700V 3600h=3.600V | 61h:60h | 07:00 15:08 | 00h 36h | 00h 36h |
| Vcc Supply Minimum Voltage | 1650h=1.650V 2250h=2.250V 2350h=2.350V 2700h=2.700V | 63h:62h | 23:16 31:24 | 00h 27h | 00h 27h |
| HW Reset# pin | 0=not support 1=support | 65h:64h | 00 | 0b | 4FF4h |
| HW Hold# pin | 0=not support 1=support | | 01 | 0b | |
| Deep Power Down Mode | 0=not support 1=support | | 02 | 1b | |
| SW Reset | 0=not support 1=support | | 03 | 0b | |
| SW Reset Opcode | Reset Enable (66h) should be issued before Reset command | | 11:04 | 1111 1111b (FFh) | |
| Program Suspend/Resume | 0=not support 1=support | | 12 | 0b | |
| Erase Suspend/Resume | 0=not support 1=support | | 13 | 0b | |
| Unused | | | 14 | 1b | |
| Wrap-Around Read mode | 0=not support 1=support | | 15 | 0b | |
| Wrap-Around Read mode Opcode | | 66h | 23:16 | FFh | FFh |
| Wrap-Around Read data length | 08h:support 8B wrap-around read 16h:8B&16B 32h:8B&16B&32B 64h:8B&16B&32B&64B | 67h | 31:24 | FFh | FFh |
| Individual block lock | 0=not support 1=support | 6Bh:68h | 00 | 1b | C8D9h |
| Individual block lock bit (Volatile/Nonvolatile) | 0=Volatile 1=Nonvolatile | | 01 | 0b | |
| Individual block lock Opcode | | | 09:02 | 0011 0110b (36h) | |
| Individual block lock Volatile protect bit default protect status | 0=protect 1=unprotect | | 10 | 0b | |
| Secured OTP | 0=not support 1=support | | 11 | 1b | |
| Read Lock | 0=not support 1=support | | 12 | 0b | |
| Permanent Lock | 0=not support 1=support | | 13 | 0b | |
| Unused | | | 15:14 | 11b | |
| Unused | | | 31:16 | 0xFFh | 0xFFh |
| Unused | | 6Fh:6Ch | 31:00 | 0xFFh | 0xFFh |

Note 1: h/b is hexadecimal or binary.

Note 2: **(x-y-z)** means I/O mode nomenclature used to indicate the number of active pins used for the opcode (x), address (y), and data (z). At the present time, the only valid Read SFDP instruction modes are: (1-1-1), (2-2-2), and (4-4-4)

Note 3: **Wait States** is required dummy clock cycles after the address bits or optional mode bits.

Note 4: **Mode Bits** is optional control bits that follow the address bits. These bits are driven by the system controller if they are specified. (eg, read performance enhance toggling bits)

Note 5: 4KB=2⁰Ch, 32KB=2⁰Fh, 64KB=2¹0h

Note 6: 0xFFh means all data is blank ("1b").

POWER-ON STATE

The device is at the following states after power-up:

- Standby mode (please note it is not Deep Power-down mode)
- Write Enable Latch (WEL) bit is reset

The device must not be selected during power-up and power-down stage until the VCC reaches the following levels:

- VCC minimum at power-up stage and then after a delay of tVSL
- GND at power-down

Please note that a pull-up resistor on CS# may ensure a safe and proper power-up/down level.

An internal Power-on Reset (POR) circuit may protect the device from data corruption and inadvertent data change during power up state.

For further protection on the device, if the VCC does not reach the VCC minimum level, the correct operation is not guaranteed. The read, write, erase, and program command should be sent after the time delay:

- tVSL after VCC reached VCC minimum level

The device can accept read command after VCC reached VCC minimum and a time delay of tVSL.

Please refer to the figure of "[Power-up Timing](#)".

Note:

- To stabilize the VCC level, the VCC rail decoupled by a suitable capacitor close to package pins is recommended. (generally around 0.1uF)

ELECTRICAL SPECIFICATIONS

ABSOLUTE MAXIMUM RATINGS

| RATING | | VALUE |
|-------------------------------|------------------|-------------------|
| Ambient Operating Temperature | Industrial grade | -40°C to 85°C |
| Storage Temperature | | -65°C to 150°C |
| Applied Input Voltage | | -0.5V to VCC+0.5V |
| Applied Output Voltage | | -0.5V to VCC+0.5V |
| VCC to Ground Potential | | -0.5V to 4.0V |

NOTICE:

1. Stresses greater than those listed under ABSOLUTE MAXIMUM RATINGS may cause permanent damage to the device. This is stress rating only and functional operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended period may affect reliability.
2. Specifications contained within the following tables are subject to change.
3. During voltage transitions, all pins may overshoot Vss to -2.0V and Vcc to +2.0V for periods up to 20ns, see Figure 2, 3.

Figure 2. Maximum Negative Overshoot Waveform

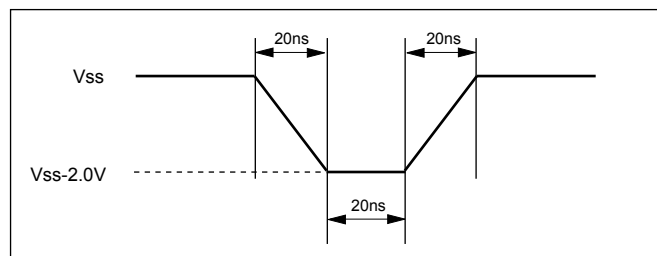
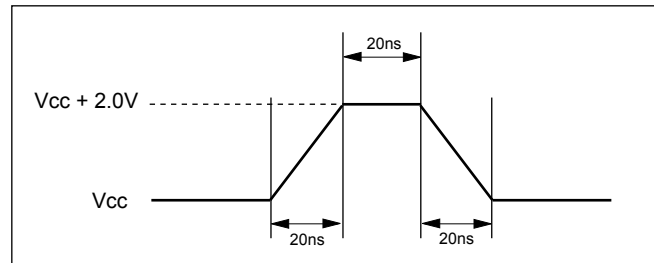


Figure 3. Maximum Positive Overshoot Waveform



CAPACITANCE TA = 25°C, f = 1.0 MHz

| Symbol | Parameter | Min. | Typ. | Max. | Unit | Conditions |
|--------|--------------------|------|------|------|------|------------|
| CIN | Input Capacitance | | | 20 | pF | VIN = 0V |
| COU | Output Capacitance | | | 20 | pF | VOU = 0V |

Figure 4. INPUT TEST WAVEFORMS AND MEASUREMENT LEVEL

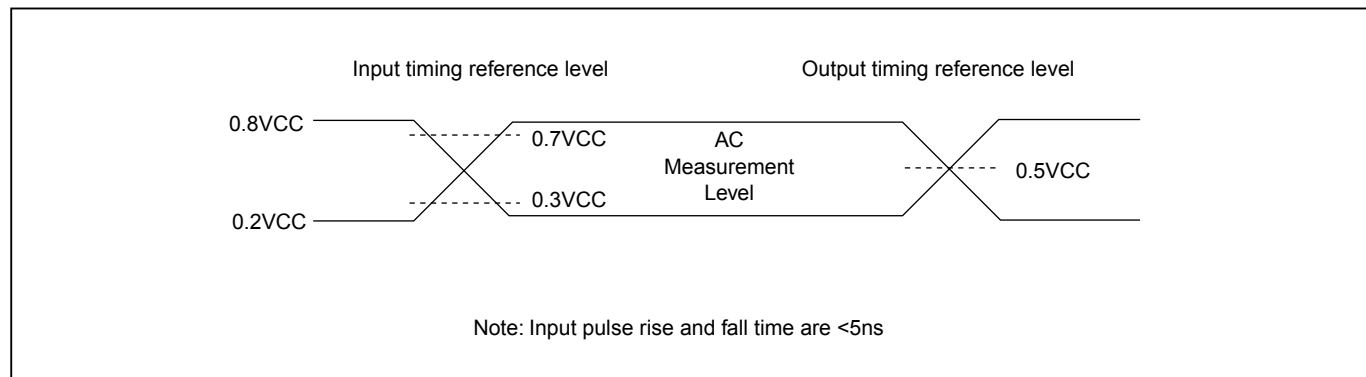


Figure 5. OUTPUT LOADING

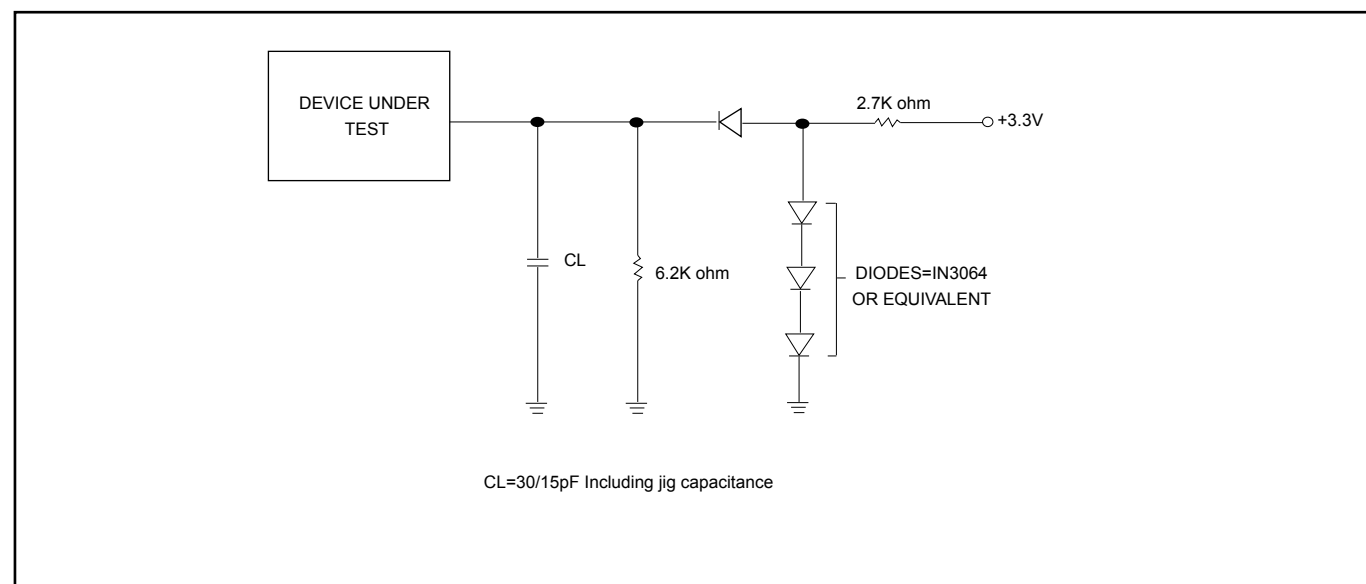


Table 7. DC CHARACTERISTICS (Temperature = -40°C to 85°C for Industrial grade, VCC = 2.7V ~ 3.6V)

| Symbol | Parameter | Notes | Min. | Max. | Units | Test Conditions |
|--------|--|-------|---------|---------|-------|--|
| ILI | Input Load Current | 1 | | ± 2 | uA | VCC = VCC Max, VIN = VCC or GND |
| ILO | Output Leakage Current | 1 | | ± 2 | uA | VCC = VCC Max, VOUT=VCC or GND |
| ISB1 | VCC Standby Current | 1 | | 100 | uA | VIN = VCC or GND, CS# = VCC |
| ISB2 | Deep Power-down Current | | | 40 | uA | VIN = VCC or GND, CS# = VCC |
| ICC1 | VCC Read | 1 | | 22 | mA | fQ=70MHz (4 x I/O read) SCLK=0.1VCC/0.9VCC, SO=Open |
| | | | | 19 | mA | f=104MHz SCLK=0.1VCC/0.9VCC, SO=Open |
| | | | | 17 | mA | fT=70MHz (2 x I/O read) SCLK=0.1VCC/0.9VCC, SO=Open |
| | | | | 15 | mA | f=66MHz SCLK=0.1VCC/0.9VCC, SO=Open |
| | | | | 10 | mA | f=33MHz, SCLK=0.1VCC/0.9VCC, SO=Open |
| ICC2 | VCC Program Current (PP) | 1 | | 25 | mA | Program in Progress, CS# = VCC |
| ICC3 | VCC Write Status Register (WRSR) Current | | | 20 | mA | Program status register in progress, CS#=VCC |
| ICC4 | VCC Sector Erase Current (SE) | 1 | | 25 | mA | Erase in Progress, CS#=VCC |
| ICC5 | VCC Chip Erase Current (CE) | 1 | | 20 | mA | Erase in Progress, CS#=VCC |
| VIL | Input Low Voltage | | -0.5 | 0.8 | V | |
| VIH | Input High Voltage | | 0.7VCC | VCC+0.4 | V | |
| VOL | Output Low Voltage | | | 0.4 | V | IOL = 1.6mA; IOL = 140uA for parallel mode |
| VOH | Output High Voltage | | VCC-0.2 | | V | IOH = -100uA; IOH = 65uA for parallel mode |

Notes :

1. Typical values at VCC = 3.3V, T = 25°C. These currents are valid for all product versions (package and speeds).
2. Typical value is calculated by simulation.

Table 8. AC CHARACTERISTICS (Temperature = -40°C to 85°C for Industrial grade, VCC = 2.7V ~ 3.6V)

| Symbol | Alt. | Parameter | | Min. | Max. | Unit |
|----------------------|------|---|---------------------|-----------------|------|------|
| fSCLK | fC | Clock Frequency for the following instructions: FAST_READ, RDSFDP, PP, SE, BE, CE, DP, RES, RDP, WREN, WRDI, RDID, RDSR, WRSR | Serial | D.C. | 104 | MHz |
| | | | Parallel | | 6 | MHz |
| fRCLK | fR | Clock Frequency for READ instructions | | | 50 | MHz |
| fTCLK | fT | Clock Frequency for 2READ instructions | | | 70 | MHz |
| | fQ | Clock Frequency for 4READ instructions | VCC=2.7V-3.6V | | 70 | MHz |
| | | | VCC=3.0V-3.6V | | 85 | MHz |
| | fC2 | Clock Frequency for FASTDTRD instructions | | | 50 | MHz |
| | fT2 | Clock Frequency for 2DTRD instructions | | | 50 | MHz |
| | fQ2 | Clock Frequency for 4DTRD instructions | | | 50 | MHz |
| f4PP | | Clock Frequency for 4PP (Quad page program) | | | 20 | MHz |
| tCH ⁽¹⁾ | tCLH | Clock High Time | Serial | 4.5 (Fast_Read) | | ns |
| | | | Serial | 9 (Read) | | ns |
| | | | Parallel | 30 | | ns |
| tCL ⁽¹⁾ | tCLL | Clock Low Time | Serial | 4.5 (Fast_Read) | | ns |
| | | | Serial | 9 (Read) | | ns |
| | | | Parallel | 30 | | ns |
| tCLCH ⁽²⁾ | | Clock Rise Time ⁽³⁾ (peak to peak) | Serial | 0.1 | | V/ns |
| | | | Parallel | 0.25 | | V/ns |
| tCHCL ⁽²⁾ | | Clock Fall Time ⁽³⁾ (peak to peak) | Serial | 0.1 | | V/ns |
| | | | Parallel | 0.25 | | V/ns |
| tSLCH | tCSS | CS# Active Setup Time (relative to SCLK) | | 5 | | ns |
| tCHSL | | CS# Not Active Hold Time (relative to SCLK) | | 5 | | ns |
| tDVCH | tDSU | Data In Setup Time | Serial | 2 | | ns |
| | | | Parallel | 10 | | ns |
| tCHDX | tDH | Data In Hold Time | Serial | 5 | | ns |
| | | | Parallel | 10 | | ns |
| tCHSH | | CS# Active Hold Time (relative to SCLK) | Serial | 5 | | ns |
| | | | Parallel | 30 | | ns |
| tSHCH | | CS# Not Active Setup Time (relative to SCLK) | | 5 | | ns |
| tSHSL ⁽³⁾ | tCSH | CS# Deselect Time | Read | 15 | | ns |
| | | | Write/Erase/Program | 50 | | ns |
| tSHQZ ⁽²⁾ | tDIS | Output Disable Time | 2.7V-3.6V Serial | | 10 | ns |
| | | | 3.0V-3.6V Serial | | 8 | ns |
| | | | Parallel | | 20 | ns |
| tCLQV | tV | Clock Low to Output Valid VCC=2.7V~3.6V | Loading: 15pF | 1 I/O | 9 | ns |
| | | | | 2 I/O & 4 I/O | 9.5 | ns |
| | | | Loading: 30pF | 2 I/O & 4 I/O | 12 | ns |
| | | | | Parallel | 70 | ns |

| Symbol | Alt. | Parameter | Min. | Typ. | Max. | Unit |
|----------------------|------|--|------|------|------|------|
| tCLQV2 | tV2 | Clock Low to Output Valid (DTR mode) VCC=2.7V~3.6V, Loading: 15pF | | | 9.5 | ns |
| tCLQX | tHO | Output Hold Time | 2 | | | ns |
| tWHSL | | Write Protect Setup Time | 20 | | | ns |
| tSHWL | | Write Protect Hold Time | 100 | | | ns |
| tDP ⁽²⁾ | | CS# High to Deep Power-down Mode | | | 10 | us |
| tRES1 ⁽²⁾ | | CS# High to Standby Mode without Electronic Signature Read | | | 100 | us |
| tRES2 ⁽²⁾ | | CS# High to Standby Mode with Electronic Signature Read | | | 100 | us |
| tW | | Write Status Register Cycle Time | | 40 | 100 | ms |
| tBP | | Byte-Program | | 9 | 300 | us |
| tPP | | Page Program Cycle Time | | 1.4 | 5 | ms |
| tSE | | Sector Erase Cycle Time (4KB) | | 60 | 300 | ms |
| tBE | | Block Erase Cycle Time (32KB) | | 0.5 | 2 | s |
| tBE | | Block Erase Cycle Time (64KB) | | 0.7 | 2 | s |
| tCE | | Chip Erase Cycle Time | | 80 | 200 | s |
| tWPS | | Write Protection Selection Time | | | 1 | ms |
| tWSR | | Write Security Register Time | | | 1 | ms |

Notes:

1. tCH + tCL must be greater than or equal to 1/ fC.
2. Value guaranteed by characterization, not 100% tested in production.
3. Only applicable as a constraint for a WRSR instruction when SRWD is set at 1.

Timing Analysis

Figure 6. Serial Input Timing

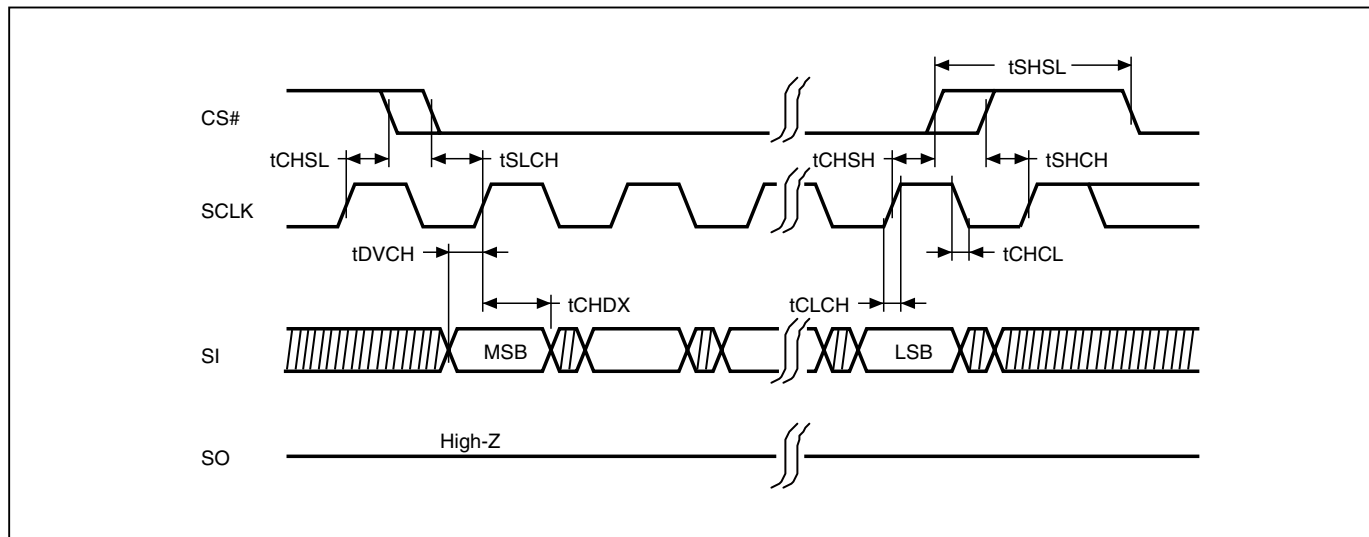


Figure 7. Output Timing

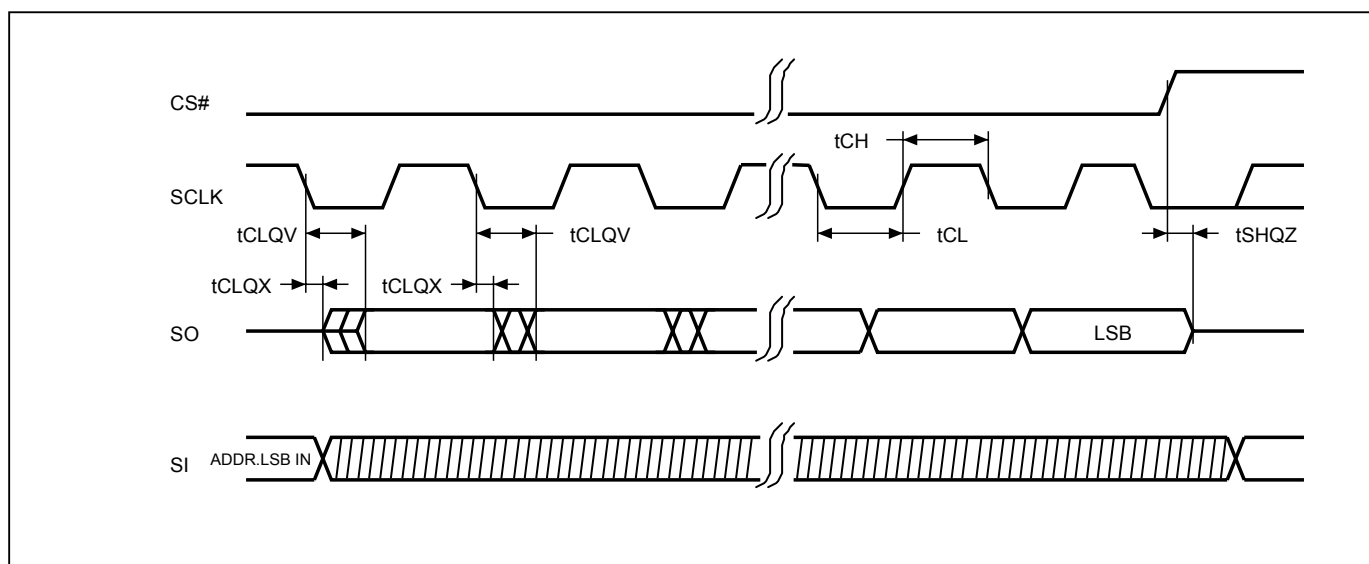


Figure 8. Serial Input Timing for Double Transfer Rate Mode

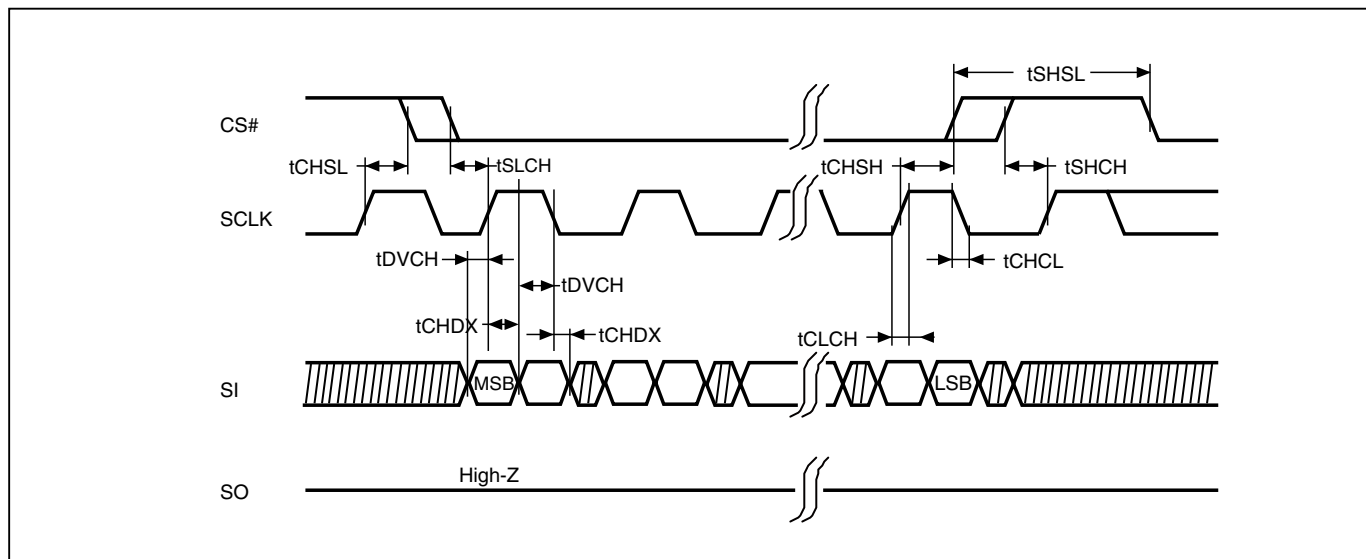


Figure 9. Serial Output Timing for Double Transfer Rate Mode

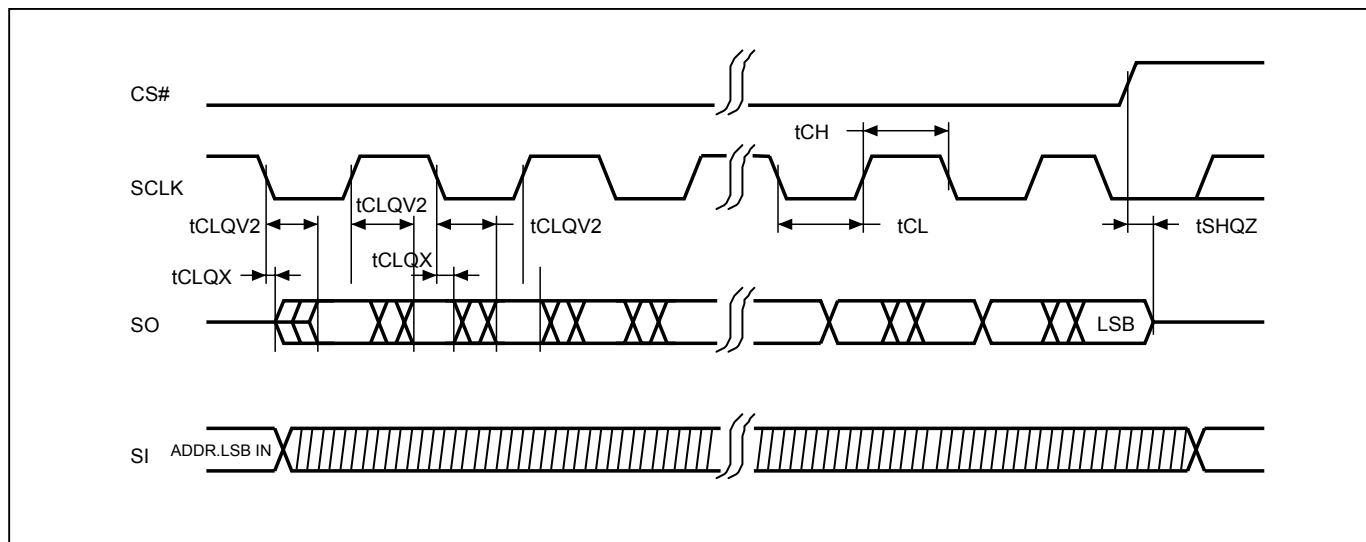


Figure 10. WP# Setup Timing and Hold Timing during WRSR when SRWD=1

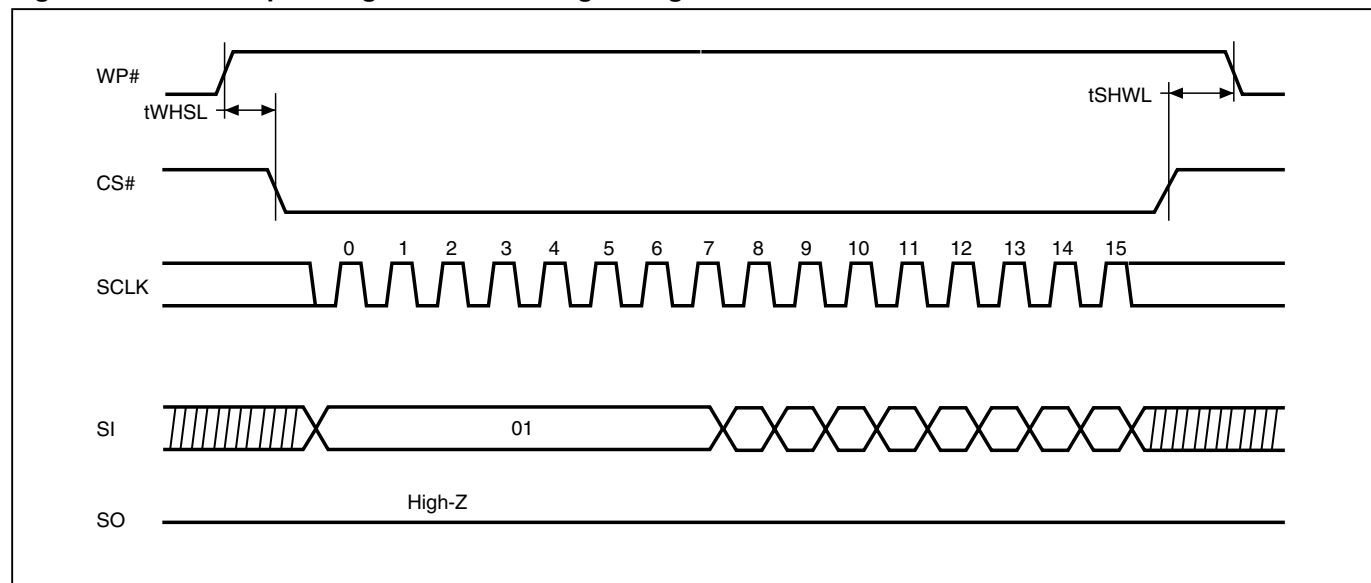


Figure 11. Write Enable (WREN) Sequence (Command 06)

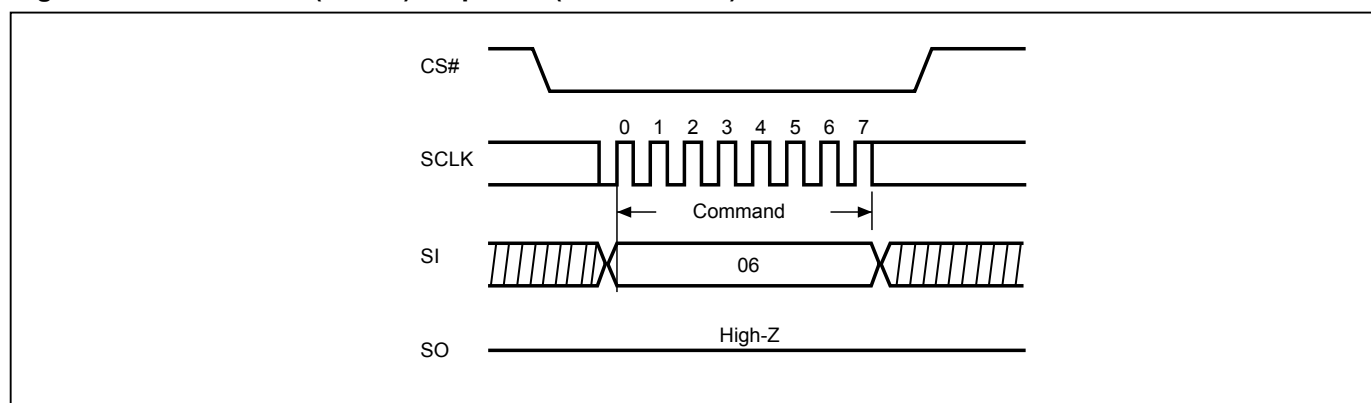


Figure 12. Write Disable (WRDI) Sequence (Command 04)

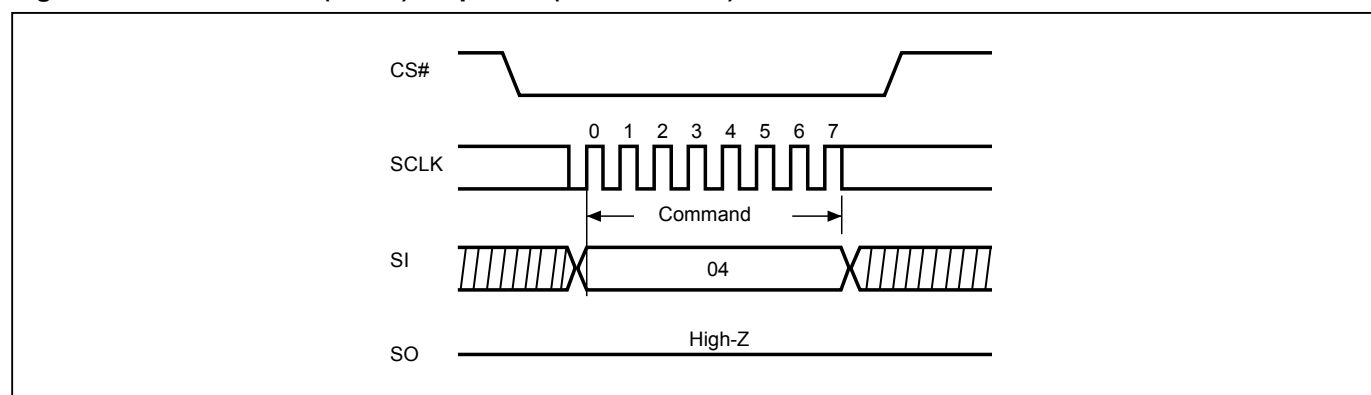


Figure 13. Read Identification (RDID) Sequence (Command 9F)

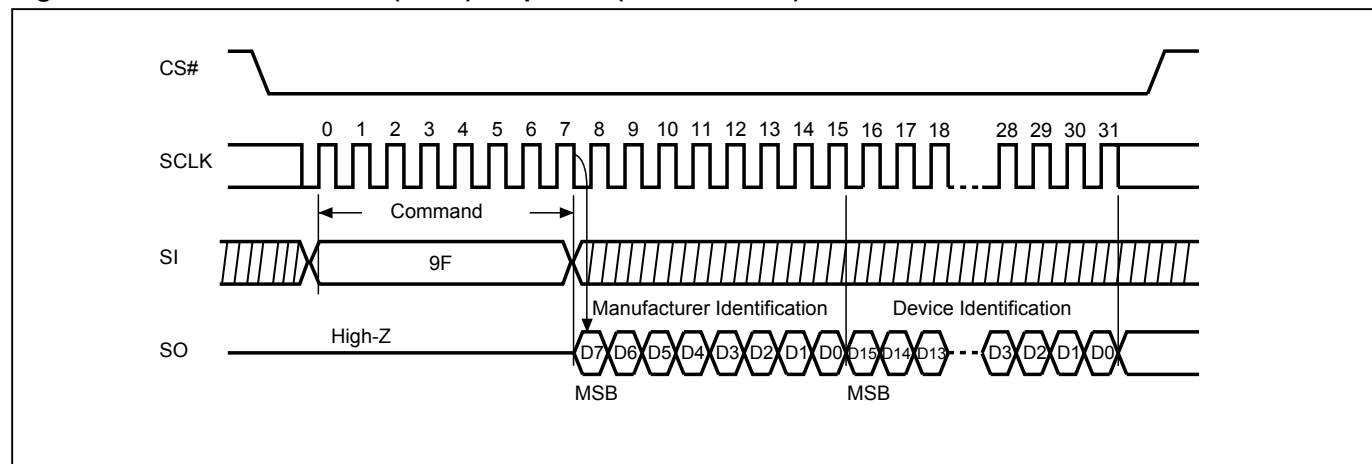


Figure 14. Read Status Register (RDSR) Sequence (Command 05)

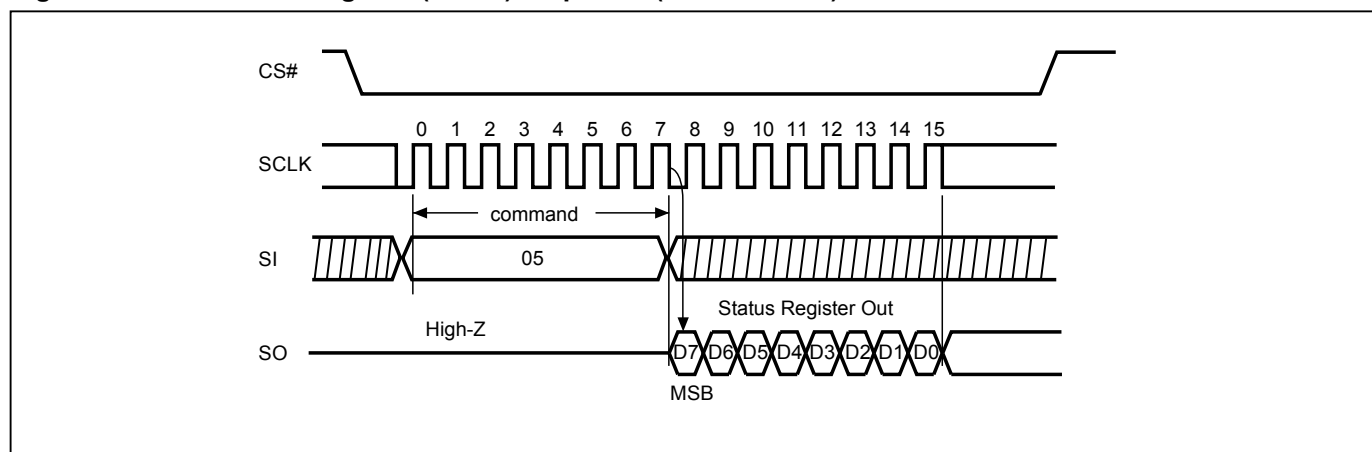


Figure 15. Write Status Register (WRSR) Sequence (Command 01)

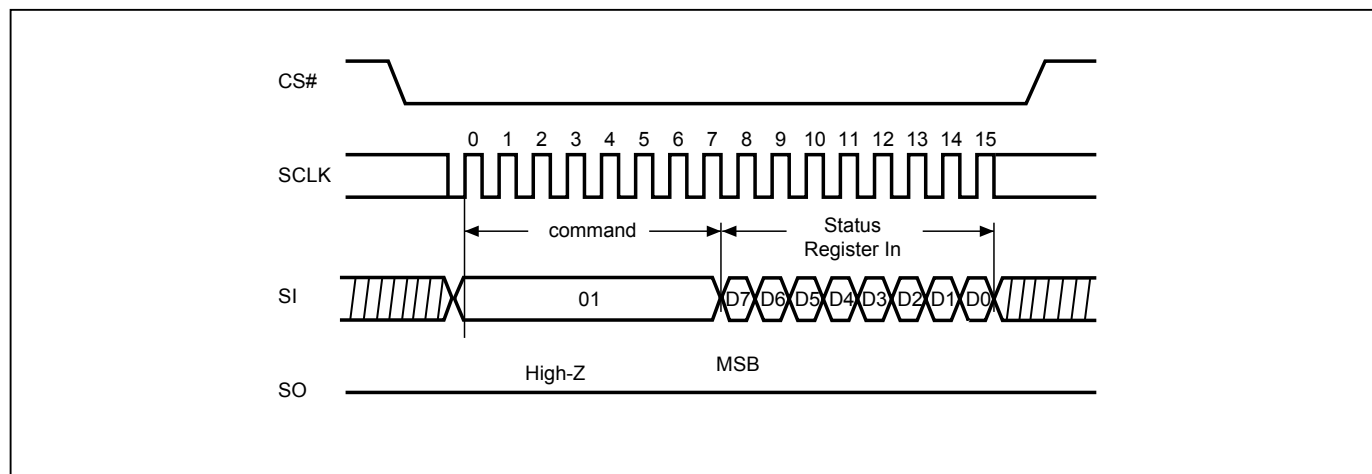


Figure 16. Read Data Bytes (READ) Sequence (Command 03)

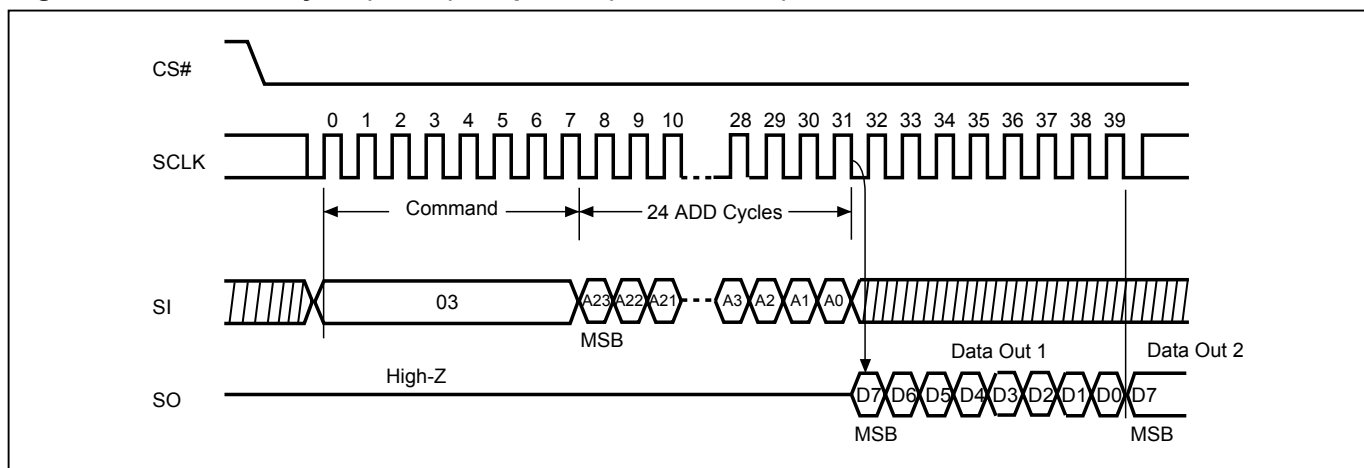


Figure 17. Read at Higher Speed (FAST_READ) Sequence (Command 0B)

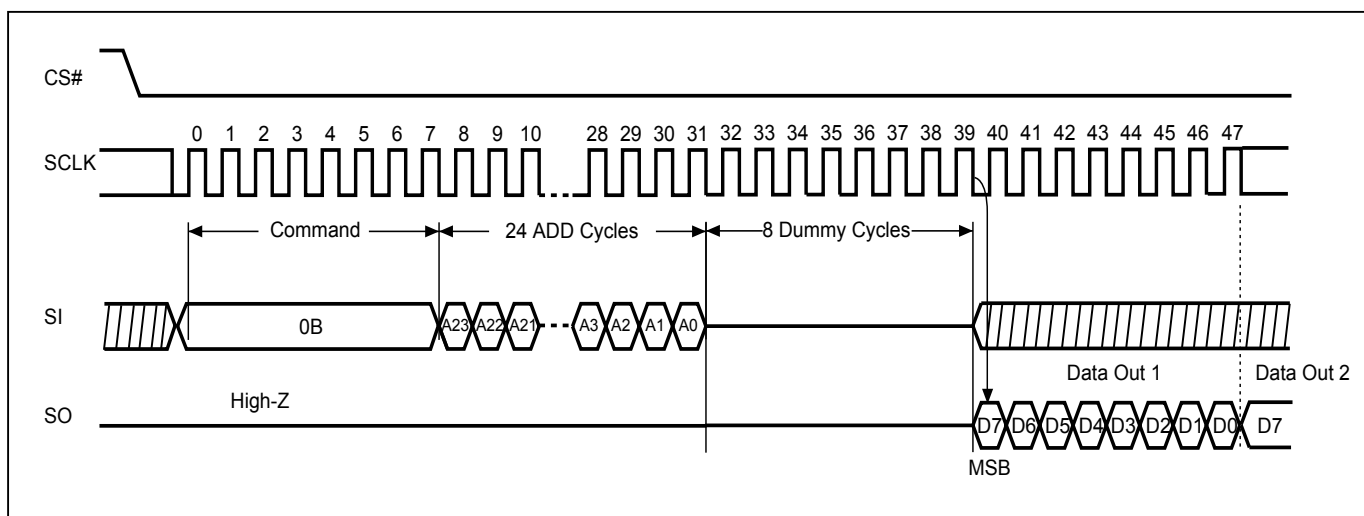


Figure 18. Fast DT Read (FASTDTRD) Sequence (Command 0D)

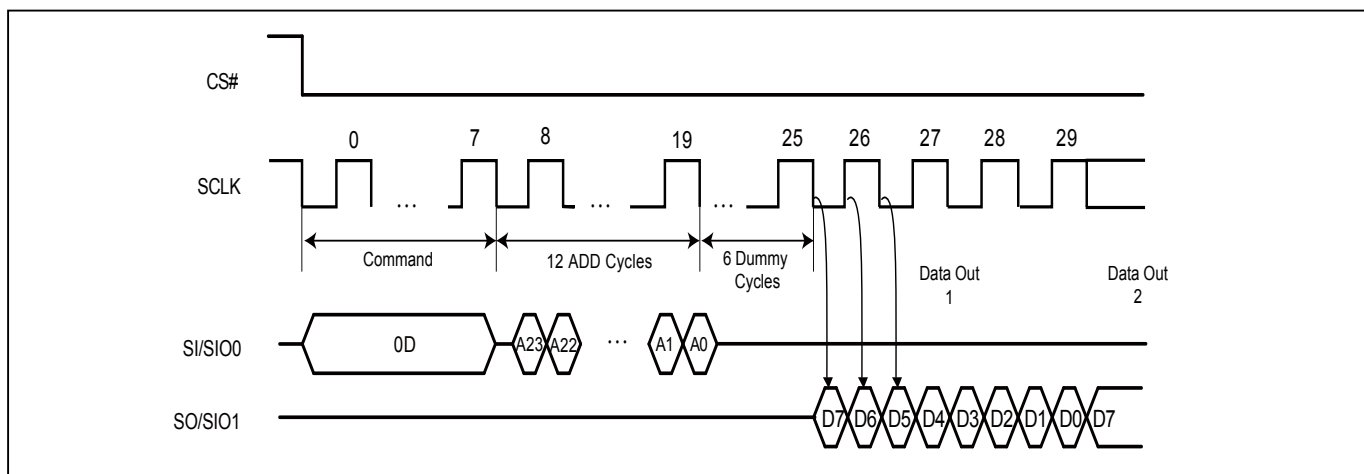
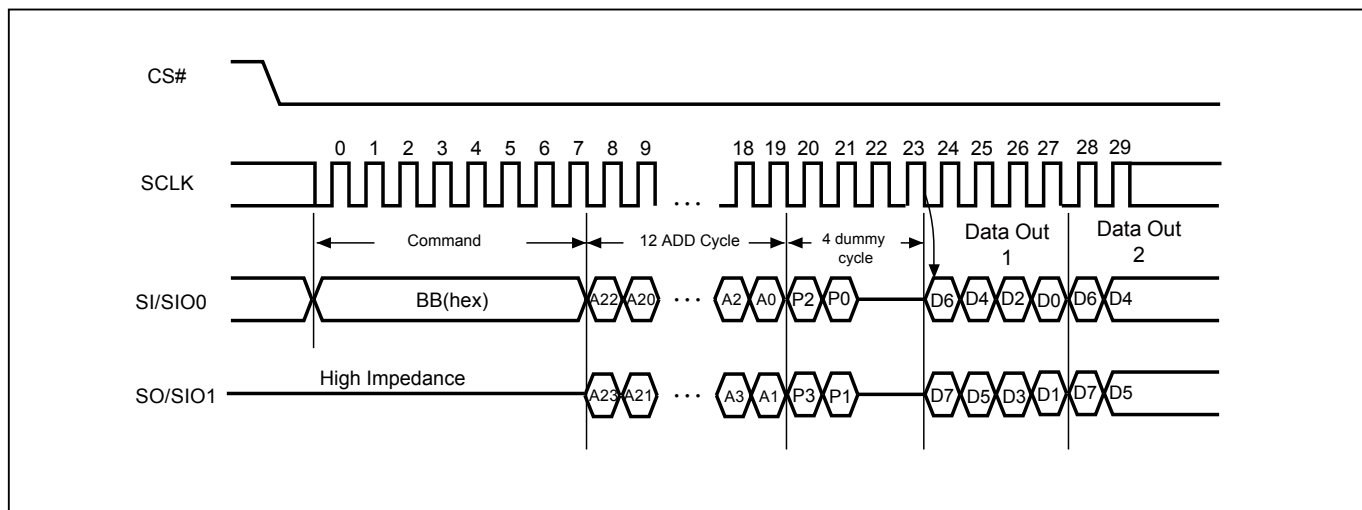
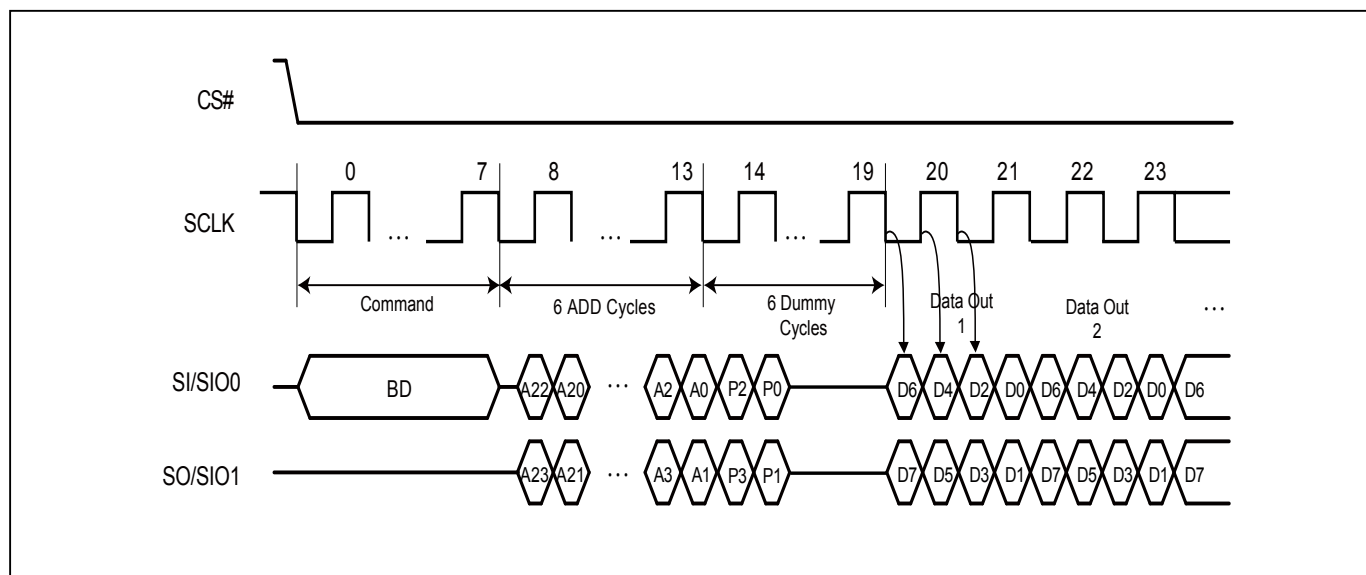


Figure 19. 2 x I/O Read Mode Sequence (Command BB)



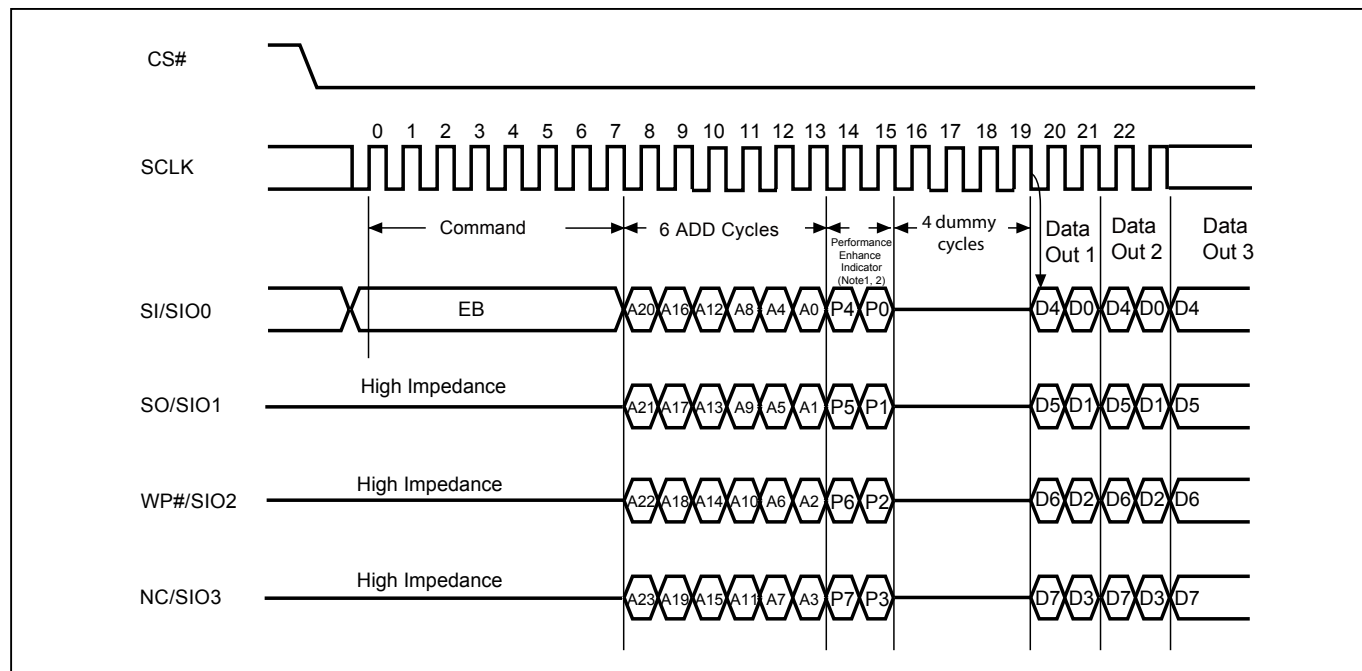
Note: SI/SIO0 or SO/SIO1 should be kept "0h" or "Fh" in the first two dummy cycles. In other words, P2=P0 or P3=P1 is necessary.

Figure 20. Fast Dual I/O DT Read (2DTRD) Sequence (Command BD)



Note: SI/SIO0 or SO/SIO1 should be kept "0h" or "Fh" in the first two dummy cycles. In other words, P2=P0 or P3=P1 is necessary.

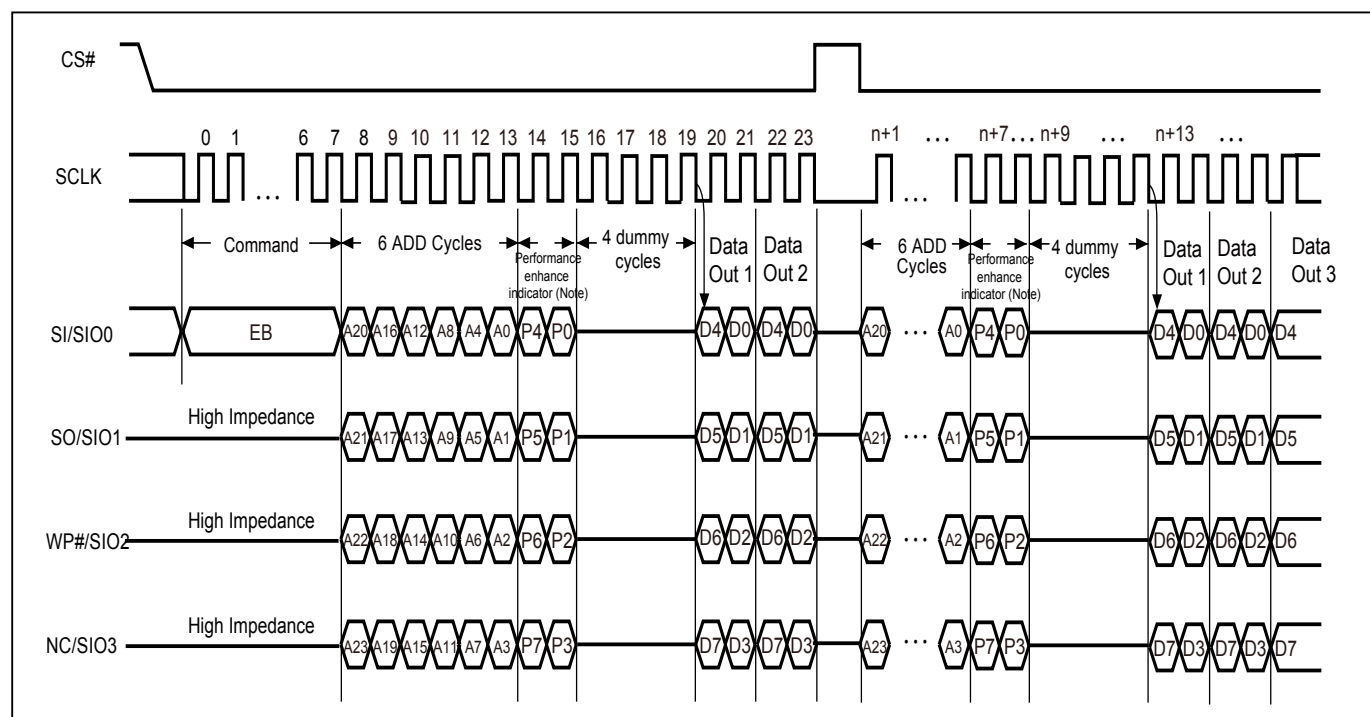
Figure 21. 4 x I/O Read Mode Sequence (Command EB)



Notes:

1. Hi-impedance is inhibited for the two clock cycles.
2. P7≠P3, P6≠P2, P5≠P1 & P4≠P0 (Toggling) will result in entering the performance enhance mode.

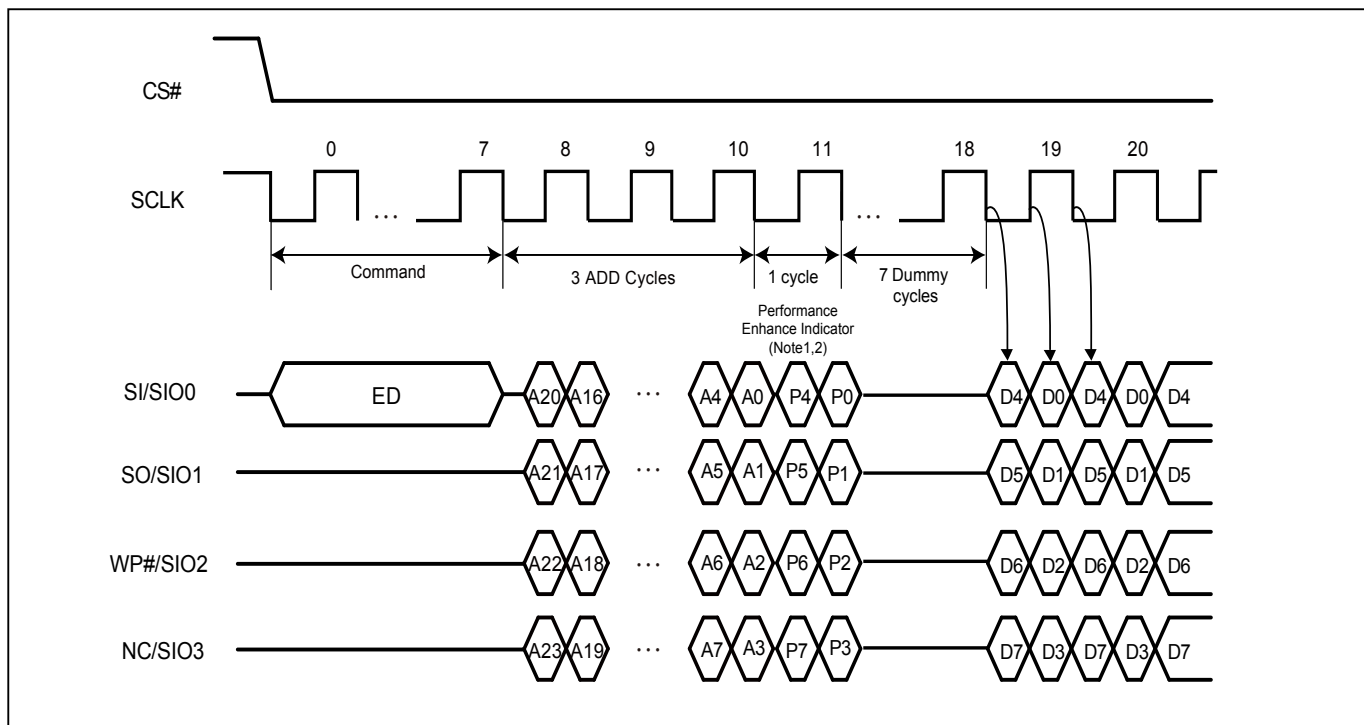
Figure 22. 4 x I/O Read Enhance Performance Mode Sequence (Command EB)



Notes:

1. Performance enhance mode: if P7≠P3 & P6≠P2 & P5≠P1 & P4≠P0 (Toggling), ex: A5, 5A, F0, 0F.
2. Reset the performance enhance mode: if P7=P3 or P6=P2 or P5=P1 or P4=P0, ex: AA, 55, 00, FF.

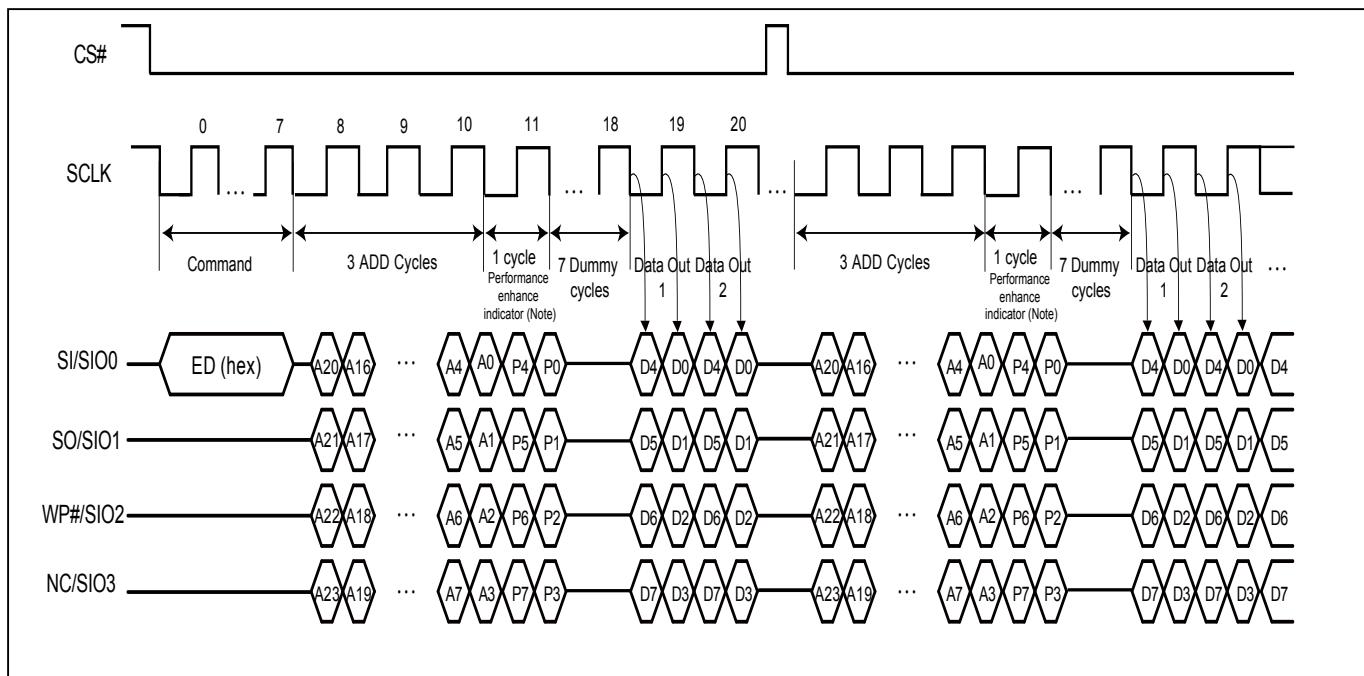
Figure 23. Fast Quad I/O DT Read (4DTRD) Sequence (Command ED)



Notes:

1. Hi-impedance is inhibited for this clock cycle.
2. P7≠P3, P6≠P2, P5≠P1 & P4≠P0 (Toggling) will result in entering the performance enhance mode.

Figure 24. Fast Quad I/O DT Read (4DTRD) Enhance Performance Sequence (Command ED)



Note: Performance enhance, if P7≠P3 & P6≠P2 & P5≠P1 & P4≠P0 (Toggle)

Figure 25. Sector Erase (SE) Sequence (Command 20)

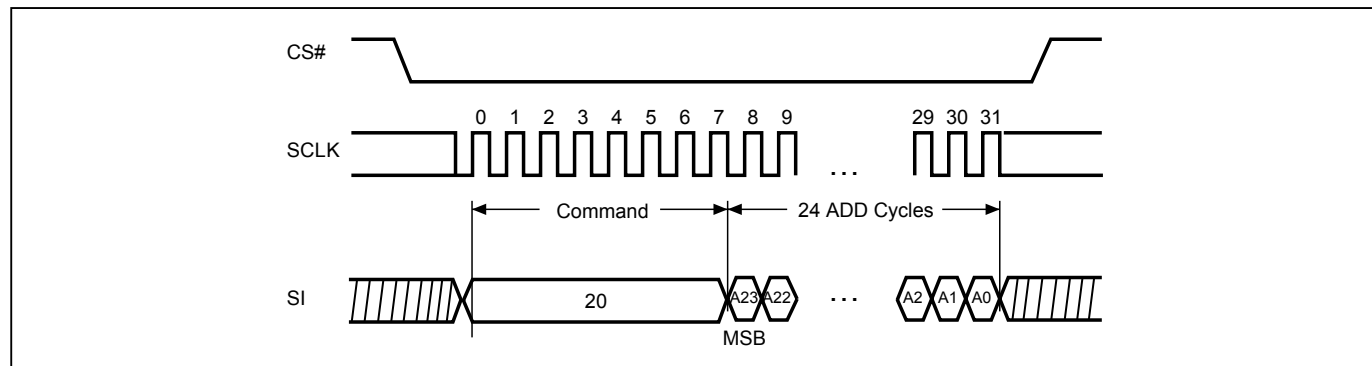


Figure 26. Block Erase (BE/BE32K) Sequence (Command D8/52)

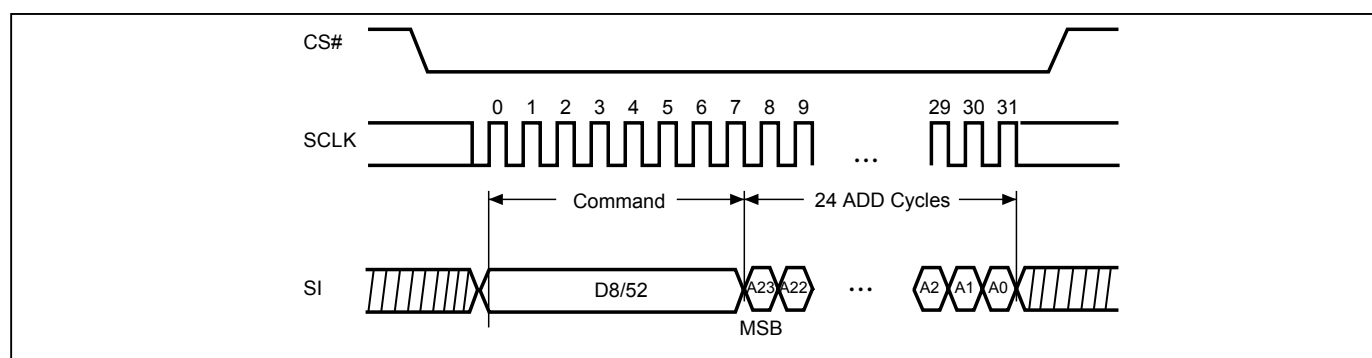


Figure 27. Chip Erase (CE) Sequence (Command 60 or C7)

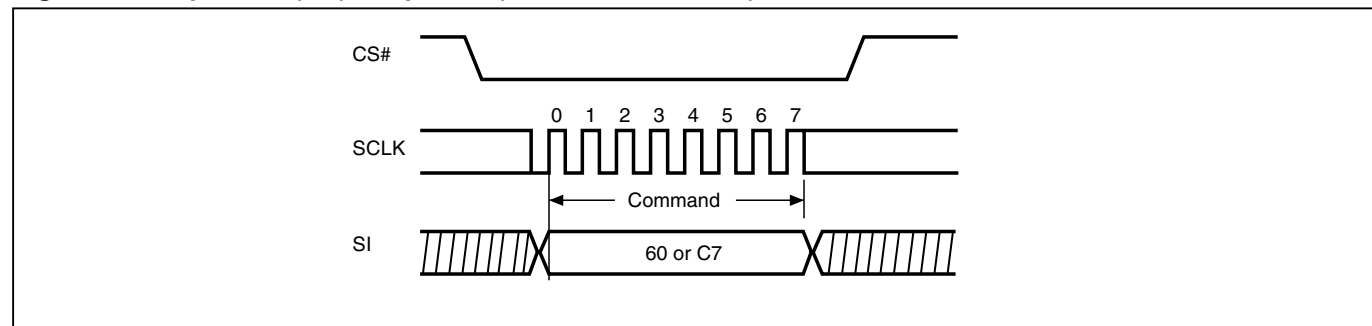


Figure 28. Page Program (PP) Sequence (Command 02)

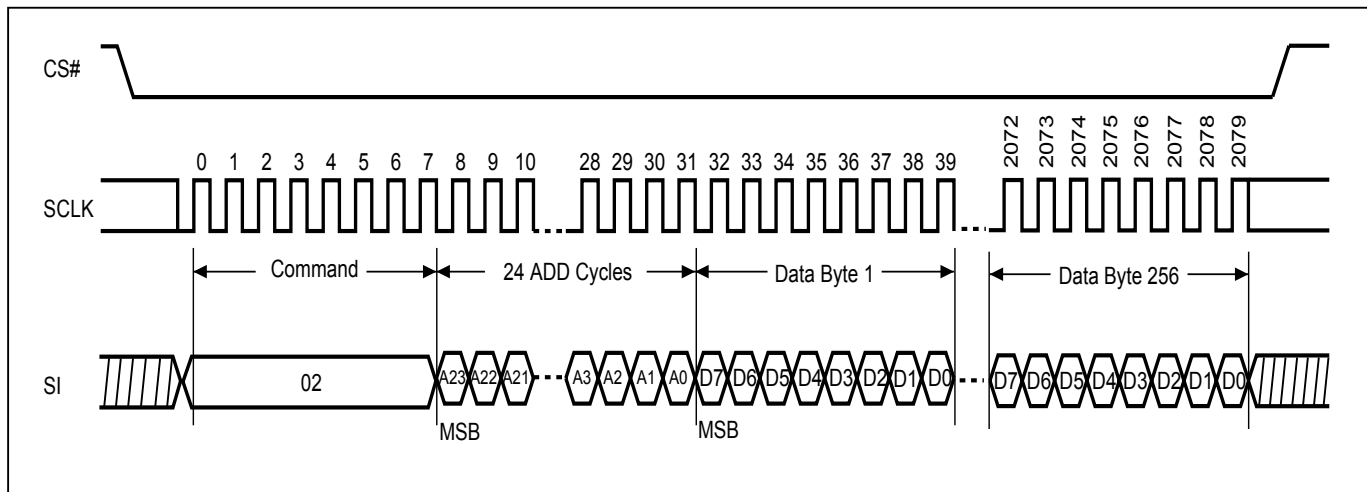


Figure 29. 4 x I/O Page Program (4PP) Sequence (Command 38)

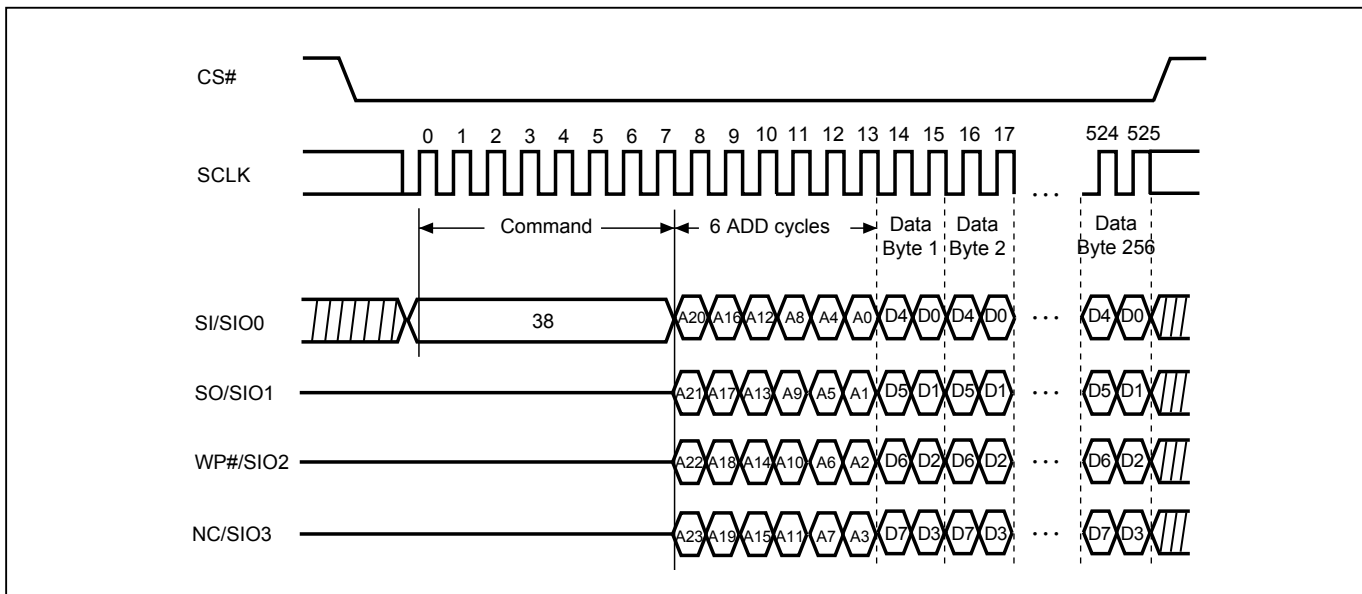
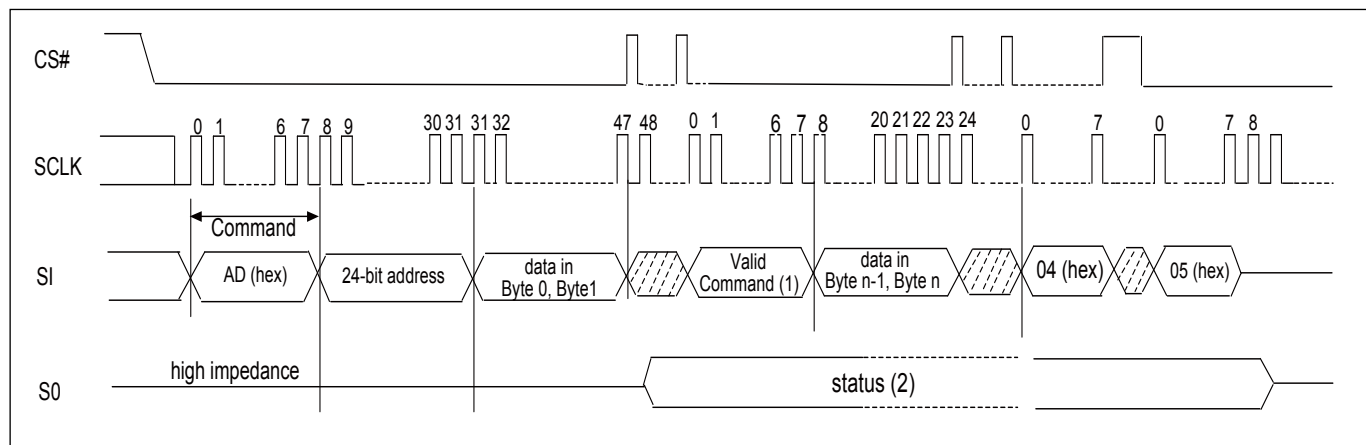


Figure 30. Continuously Program (CP) Mode Sequence with Hardware Detection (Command AD)



Notes:

- (1) During CP mode, the valid commands are CP command (AD hex), WRDI command (04 hex), RDSR command (05 hex), and RDSCUR command (2B hex).
- (2) Once an internal programming operation begins, CS# goes low will drive the status on the SO pin and CS# goes high will return the SO pin to tri-state.
- (3) To end the CP mode, either reaching the highest unprotected address or sending Write Disable (WRDI) command (04 hex) may achieve it and then it is recommended to send RDSR command (05 hex) to verify if CP mode is ended.

Figure 31-1. Enter Parallel Mode (ENPLM) Sequence (Command 55)

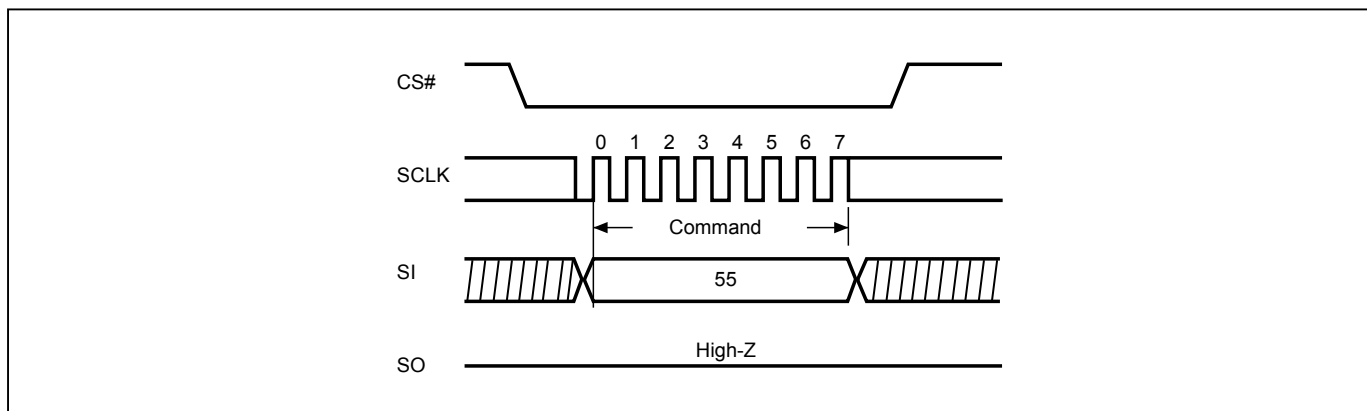


Figure 31-2. Exit Parallel Mode (EXPLM) Sequence (Command 45)

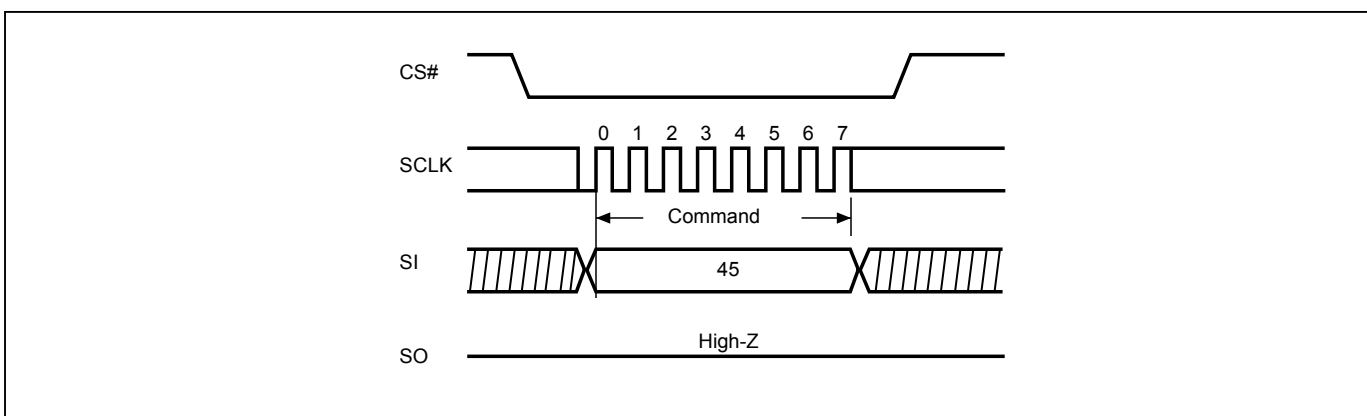
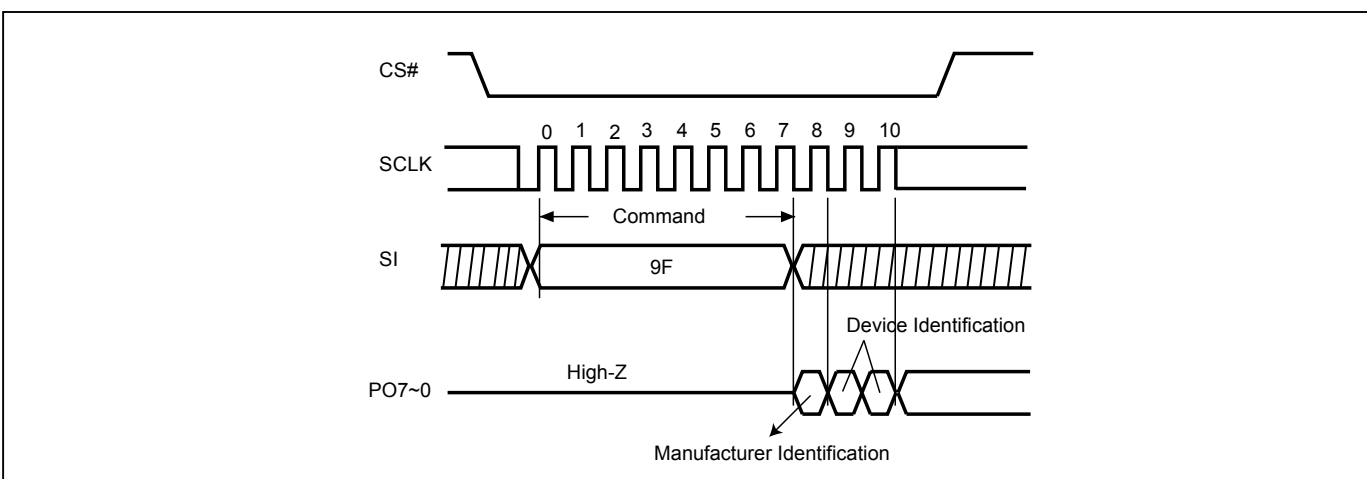
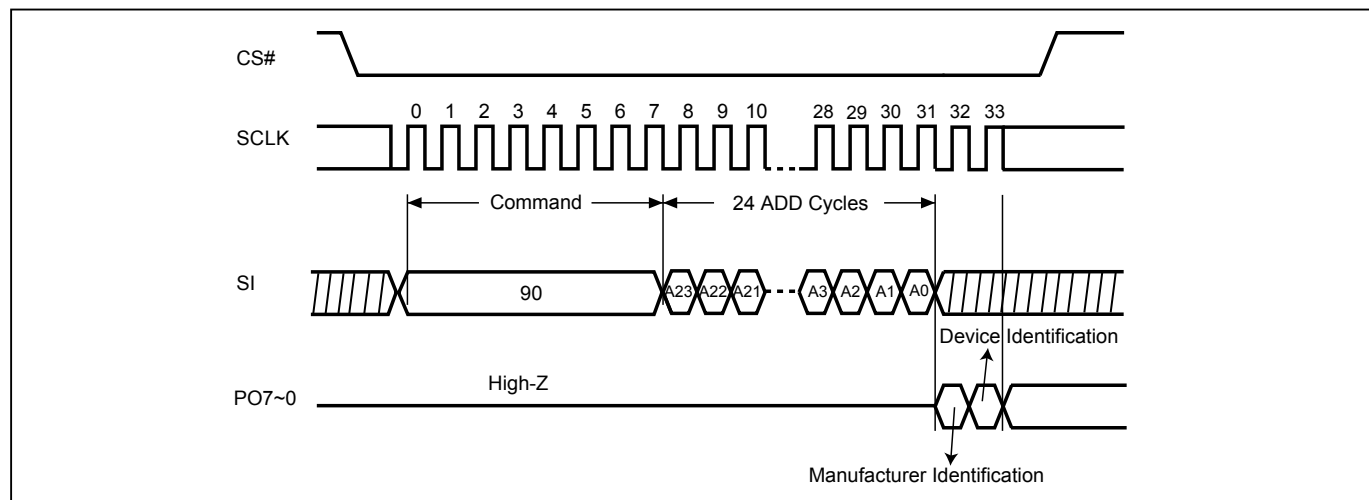


Figure 31-3. Parallel Mode Read Identification (Parallel RDID) Sequence (Command 9F)



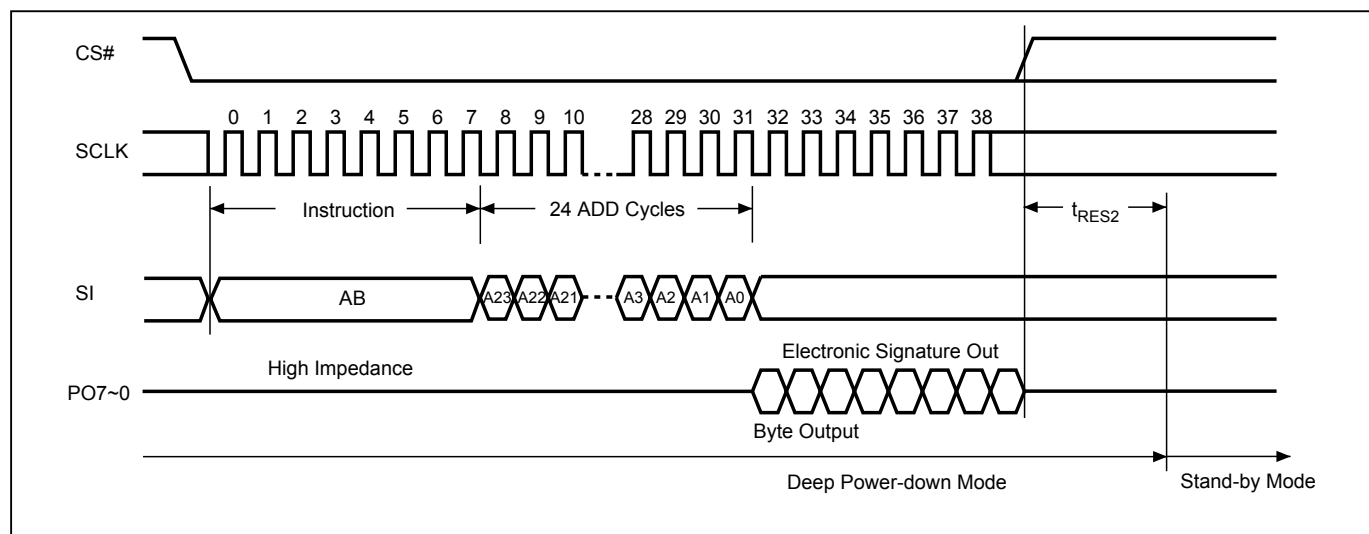
Note: There are 3 data bytes which would be output sequentially for Manufacturer and Device ID 1'st byte (Memory Type) and Device ID 2'nd byte (Memory Density).

Figure 31-4. Parallel Mode Read Electronic Manufacturer & Device ID (Parallel REMS) Sequence (Command 90)



Note: A0=0 will output the Manufacturer ID first and A0=1 will output Device ID first. A1~A23 don't care.

Figure 31-5. Parallel Mode Release from Deep Power-down (RDP) and Read Electronic Signature (RES) Sequence



Note: Under parallel mode, the fastest access clock freq. will be changed to 6MHz(SCLK pin clock freq.)

To release from Deep Power-down mode and read ID in parallel mode, which requires a parallel mode command (55h) before the read status register command.

To exit parallel mode, it requires a (45h) command or power-off/on sequence.

Figure 31-6. Parallel Mode Read Array (Parallel READ) Sequence (Command 03)

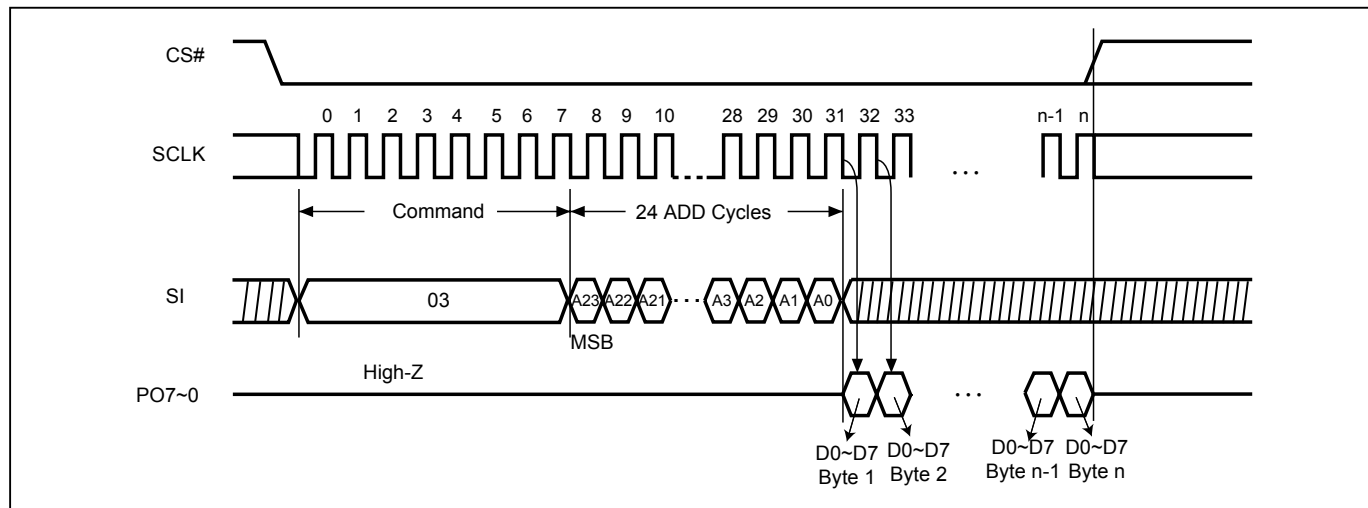


Figure 31-7. Parallel Mode Page Program (Parallel PP) Sequence (Command 02)

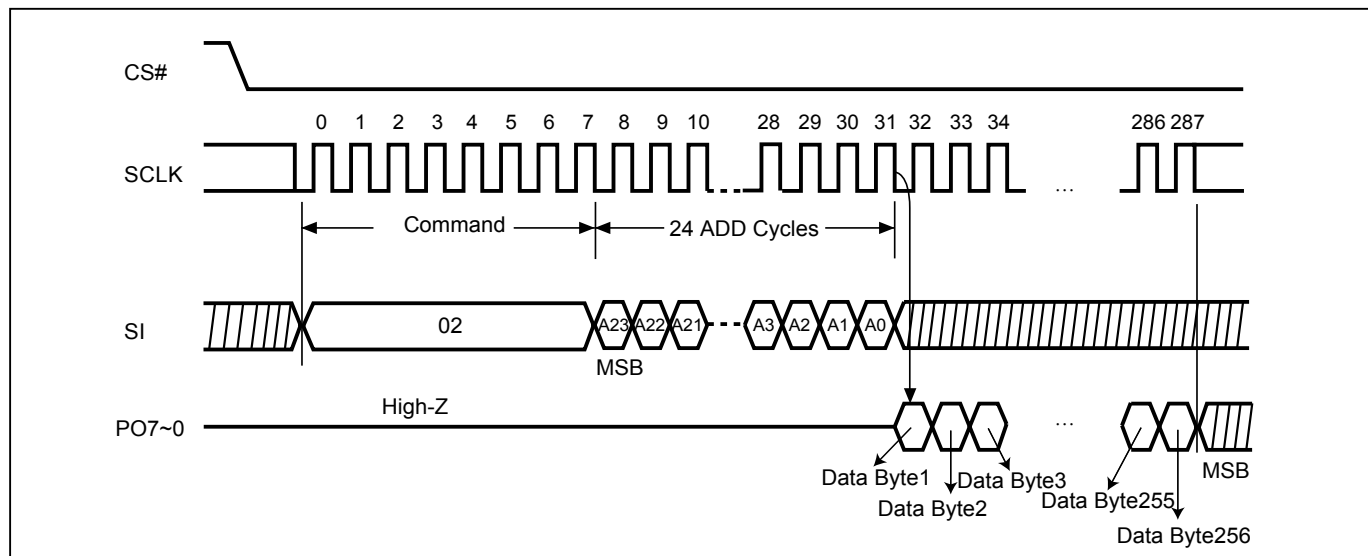


Figure 32. Deep Power-down (DP) Sequence (Command B9)

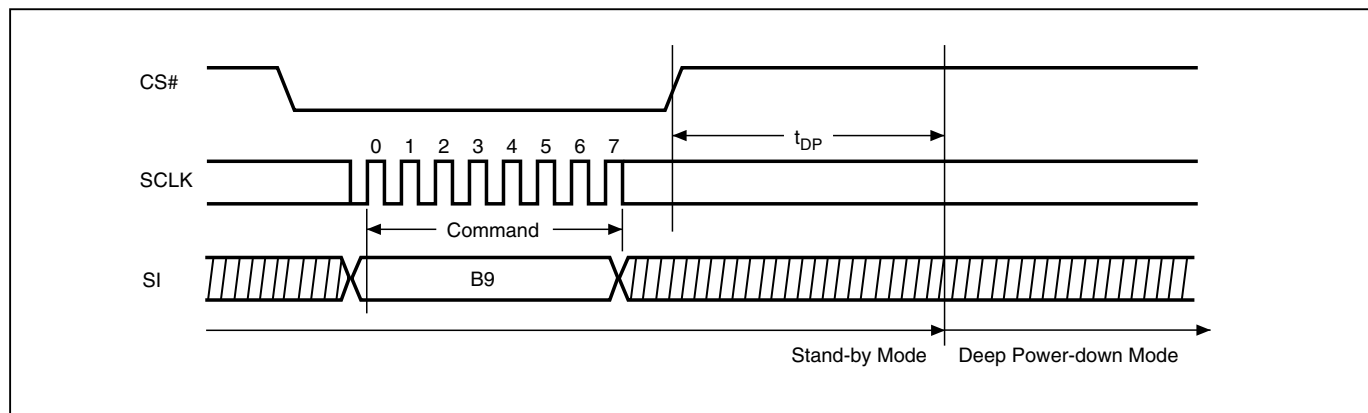


Figure 33. Read Electronic Signature (RES) Sequence (Command AB)

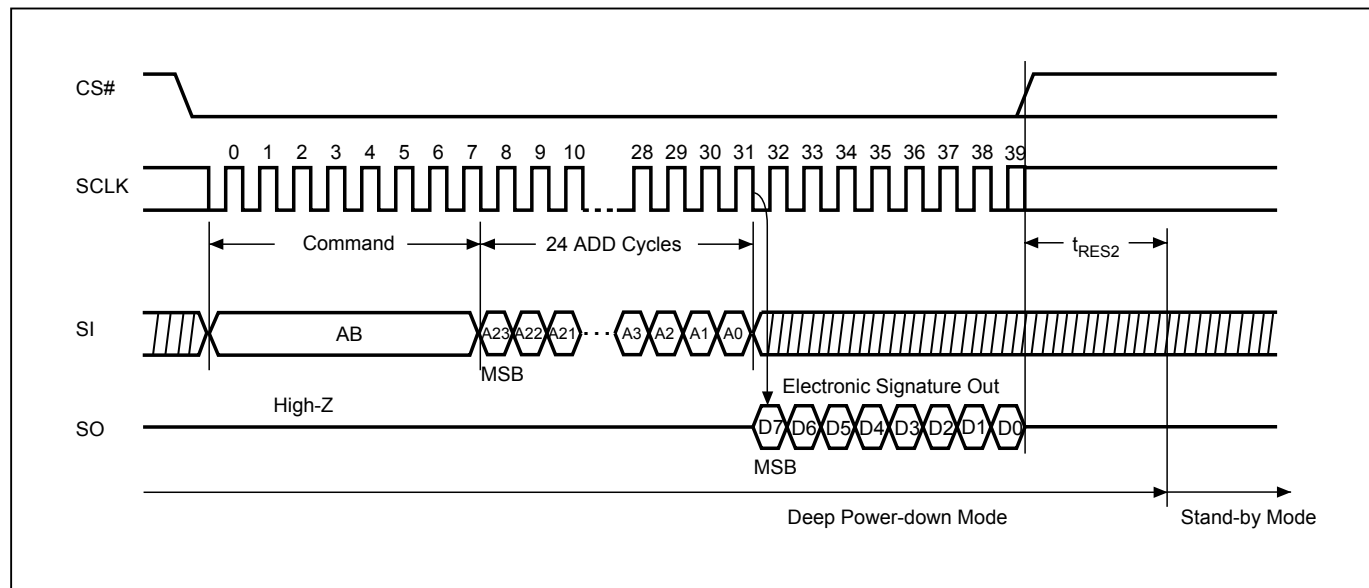


Figure 34. Release from Deep Power-down (RDP) Sequence (Command AB)

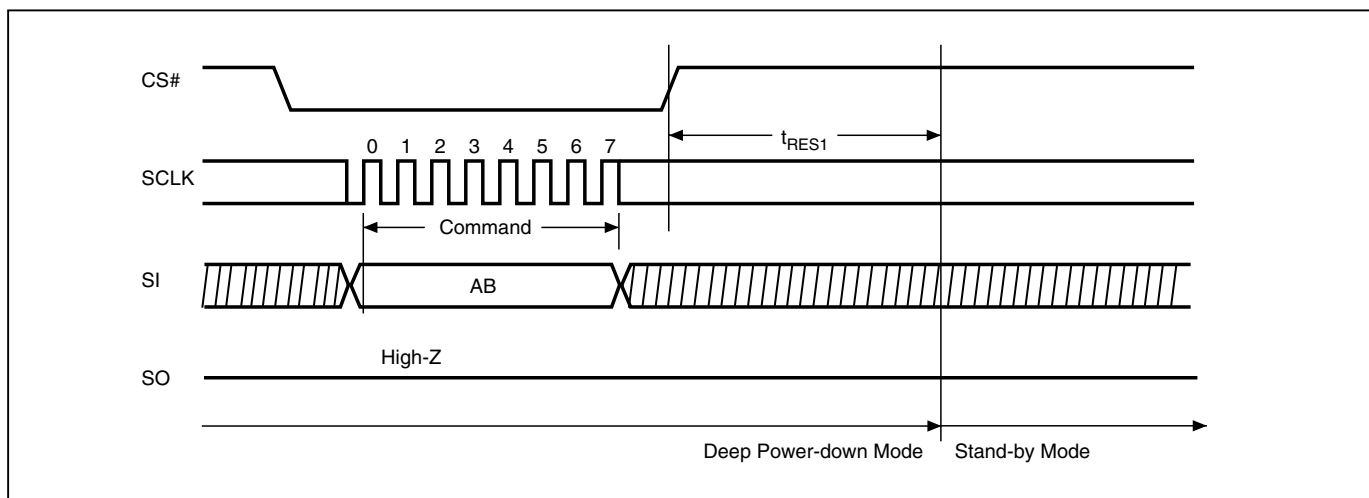
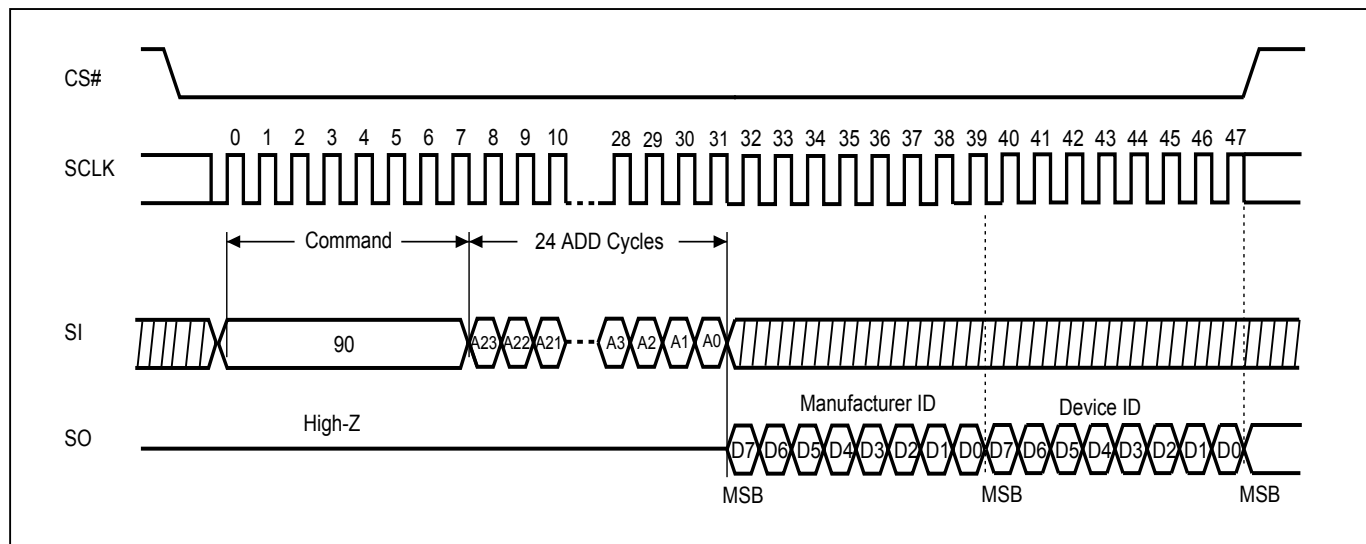


Figure 35. Read Electronic Manufacturer & Device ID (REMS) Sequence (Command 90 or EF or DF or CF)



Notes:

1. A0=0 will output the Manufacturer ID first and A0=1 will output Device ID first. A1~A23 is don't care.
2. Instruction is either 90(hex) or EF(hex) or DF(hex) or CF(hex).

Figure 36. Write Protection Selection (WPSEL) Sequence (Command 68)

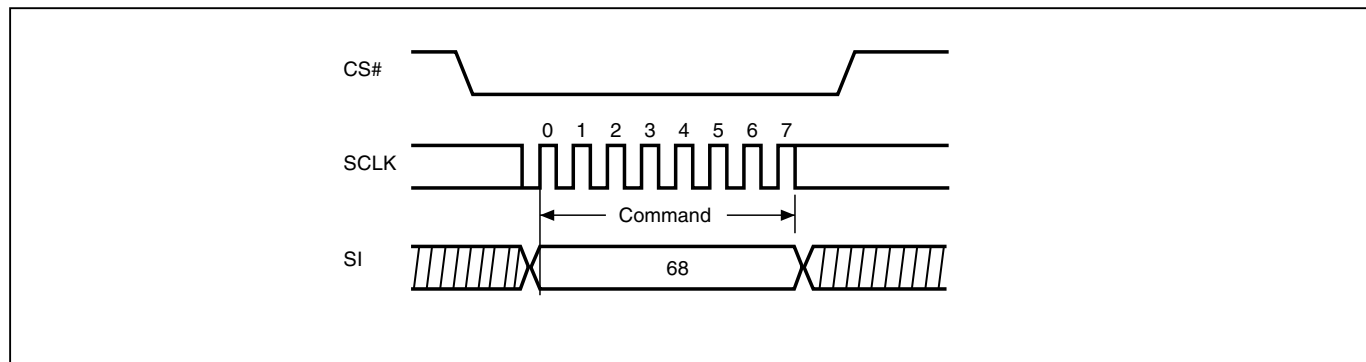


Figure 37. Single Block Lock/Unlock Protection (SBLK/SBULK) Sequence (Command 36/39)

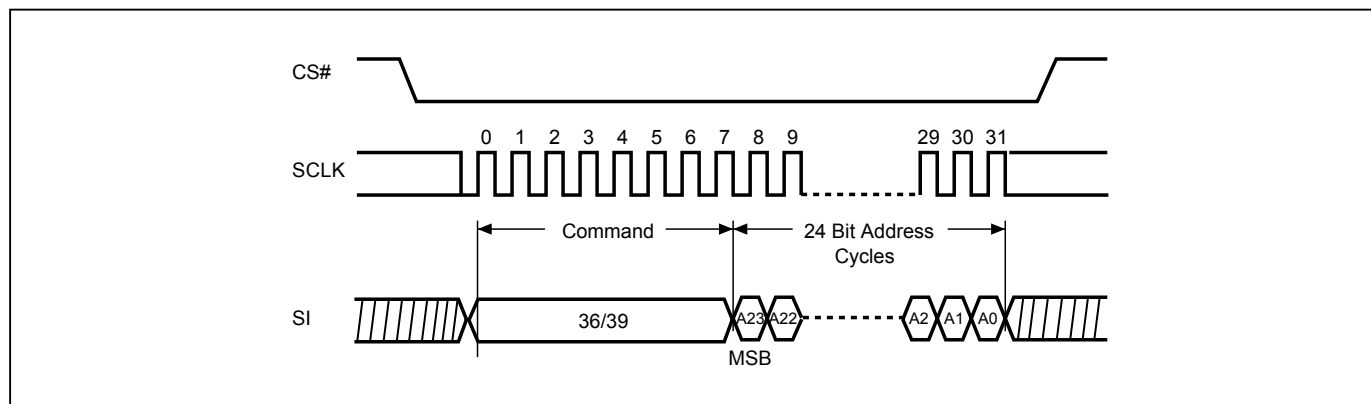


Figure 38. Read Block Protection Lock Status (RDBLOCK) Sequence (Command 3C)

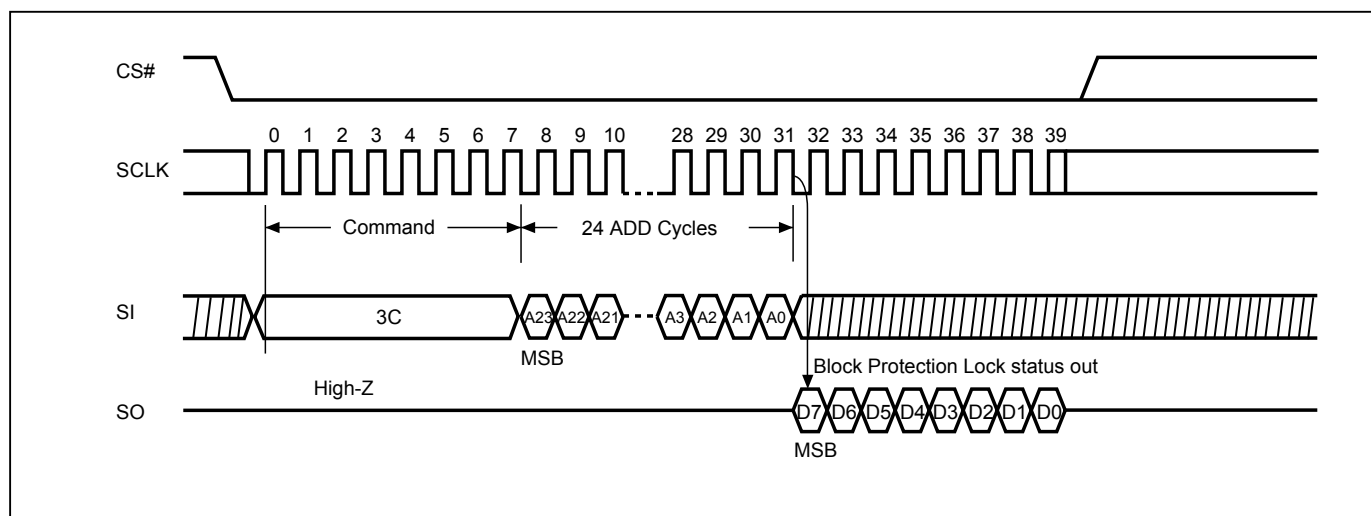


Figure 39. Gang Block Lock/Unlock (GBLK/GBULK) Sequence (Command 7E/98)

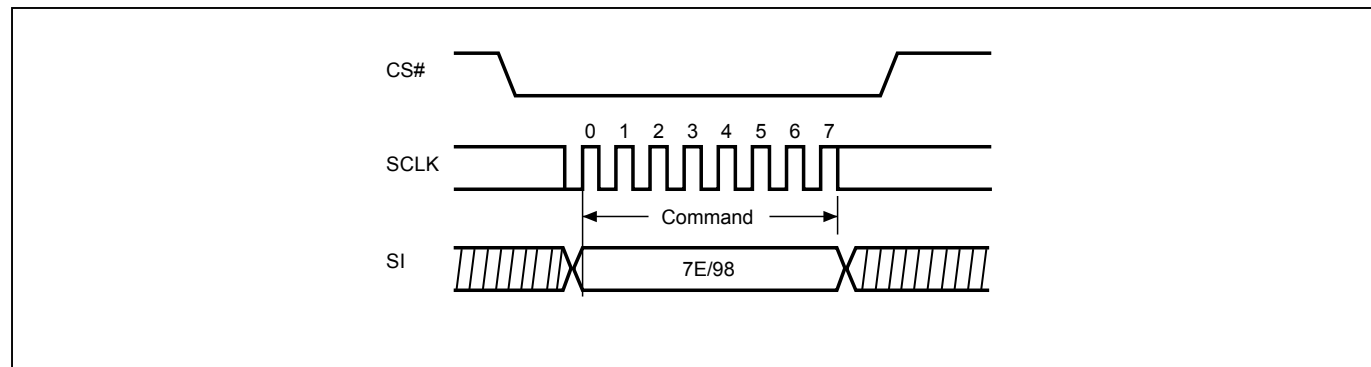
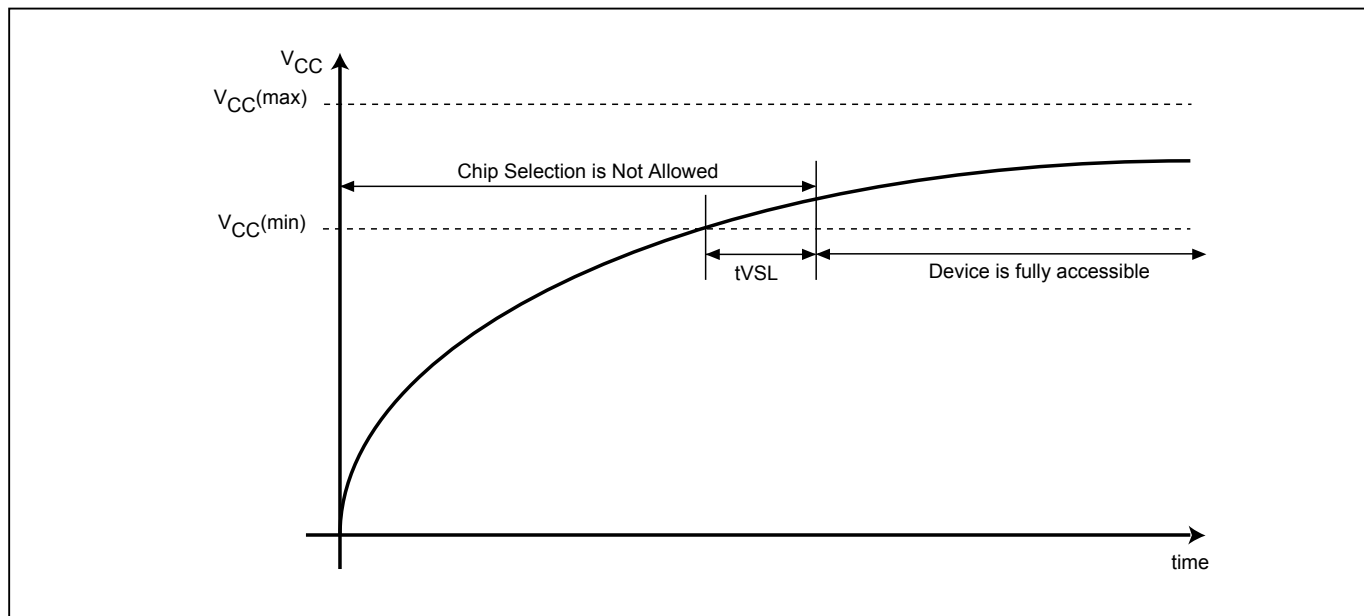


Figure 40. Power-up Timing



Note: VCC (max.) is 3.6V and VCC (min.) is 2.7V.

Table 9. Power-Up Timing

| Symbol | Parameter | Min. | Max. | Unit |
|---------|---------------------|------|------|------|
| tVSL(1) | VCC(min) to CS# low | 300 | | us |

Note: The parameter is characterized only.

INITIAL DELIVERY STATE

The device is delivered with the memory array erased: all bits are set to 1 (each byte contains FFh). The Status Register contains 00h (all Status Register bits are 0).

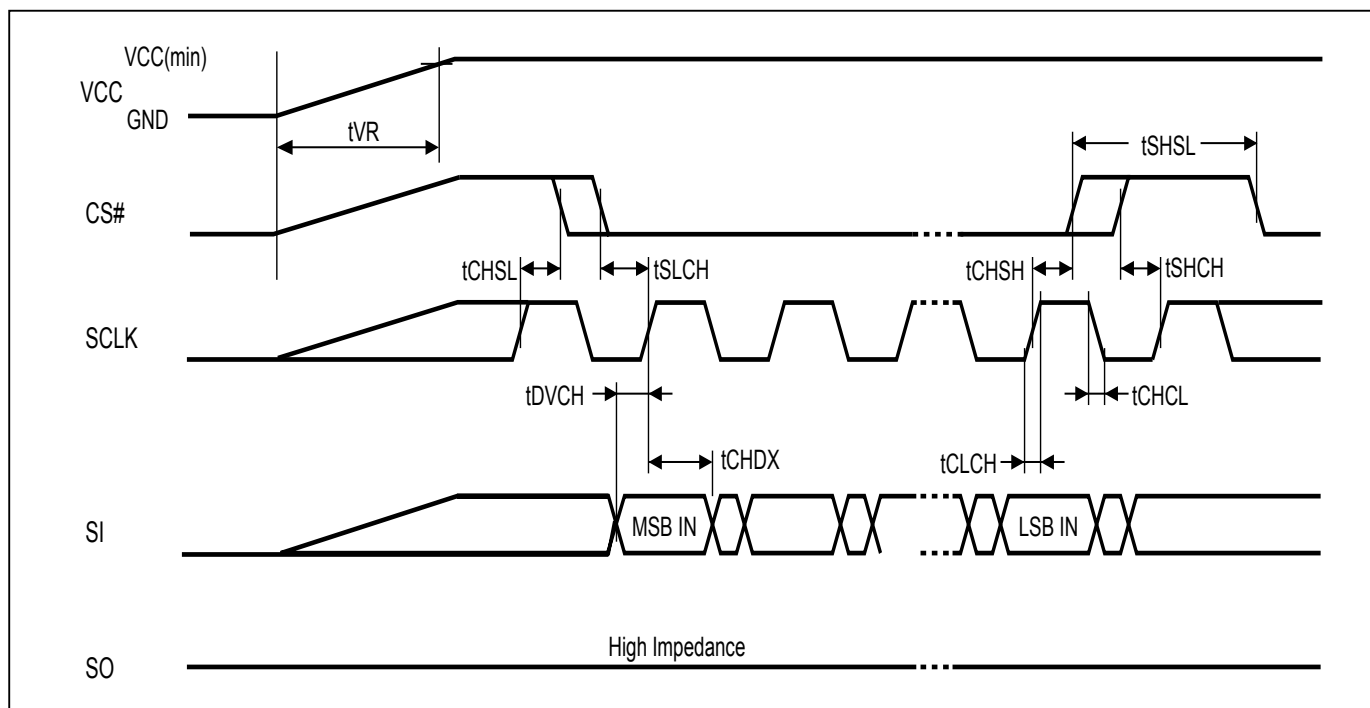
OPERATING CONDITIONS

At Device Power-Up and Power-Down

AC timing illustrated in [Figure 41](#) and [Figure 42](#) are for the supply voltages and the control signals at device power-up and power-down. If the timing in the figures is ignored, the device will not operate correctly.

During power-up and power-down, CS# needs to follow the voltage applied on VCC to keep the device not to be selected. The CS# can be driven low when VCC reach Vcc(min.) and wait a period of tVSL.

Figure 41. AC Timing at Device Power-Up



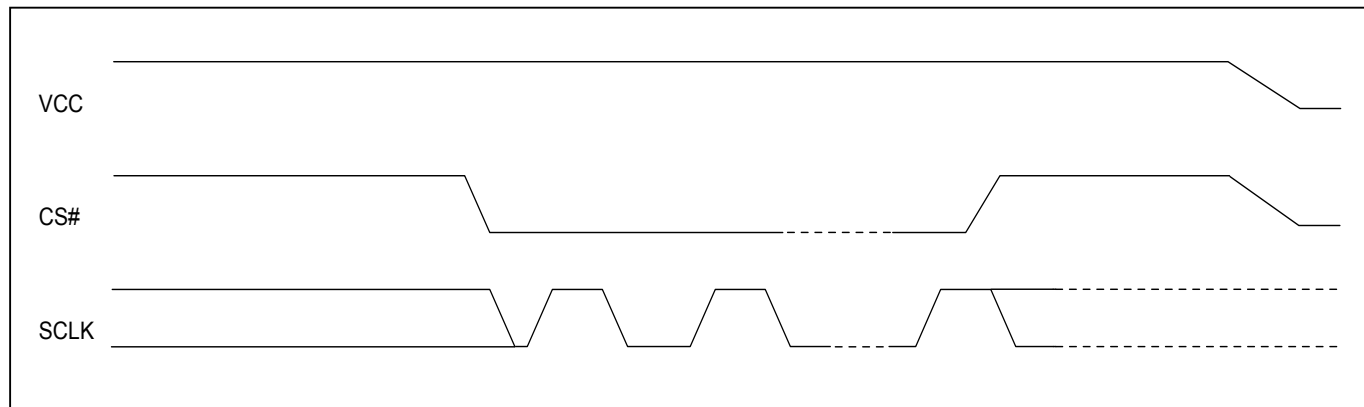
| Symbol | Parameter | Notes | Min. | Max. | Unit |
|--------|---------------|-------|------|--------|------|
| tVR | VCC Rise Time | 1 | 20 | 500000 | us/V |

Notes :

1. Sampled, not 100% tested.
2. For AC spec tCHSL, tSLCH, tDVCH, tCHDX, tSHSL, tCHSH, tSHCH, tCHCL, tCLCH in the figure, please refer to "[AC CHARACTERISTICS](#)" table.

Figure 42. Power-Down Sequence

During power-down, CS# needs to follow the voltage drop on VCC to avoid mis-operation.



ERASE AND PROGRAMMING PERFORMANCE

| Parameter | Typ. (1) | Max. (2) | Unit |
|--|----------|----------|--------|
| Write Status Register Cycle Time | 40 | 100 | ms |
| Sector Erase Time (4KB) | 60 | 300 | ms |
| Block Erase Time (64KB) | 0.7 | 2 | s |
| Block Erase Time (32KB) | 0.5 | 2 | s |
| Chip Erase Time | 80 | 200 | s |
| Byte Program Time (via page program command) | 9 | 300 | us |
| Page Program Time | 1.4 | 5 | ms |
| Erase/Program Cycle | 100,000 | | cycles |

Notes:

1. Typical program and erase time assumes the following conditions: 25°C, 3.3V, and checkerboard pattern.
2. Under worst conditions of 85°C and 2.7V.
3. System-level overhead is the time required to execute the first-bus-cycle sequence for the programming command.

DATA RETENTION

| Parameter | Condition | Min. | Max. | Unit |
|----------------|-----------|------|------|-------|
| Data retention | 55°C | 20 | | years |

LATCH-UP CHARACTERISTICS

| | Min. | Max. |
|---|--------|------------|
| Input Voltage with respect to GND on all power pins, SI, CS# | -1.0V | 2 VCCmax |
| Input Voltage with respect to GND on SO | -1.0V | VCC + 1.0V |
| Current | -100mA | +100mA |
| Includes all pins except VCC. Test conditions: VCC = 3.0V, one pin at a time. | | |

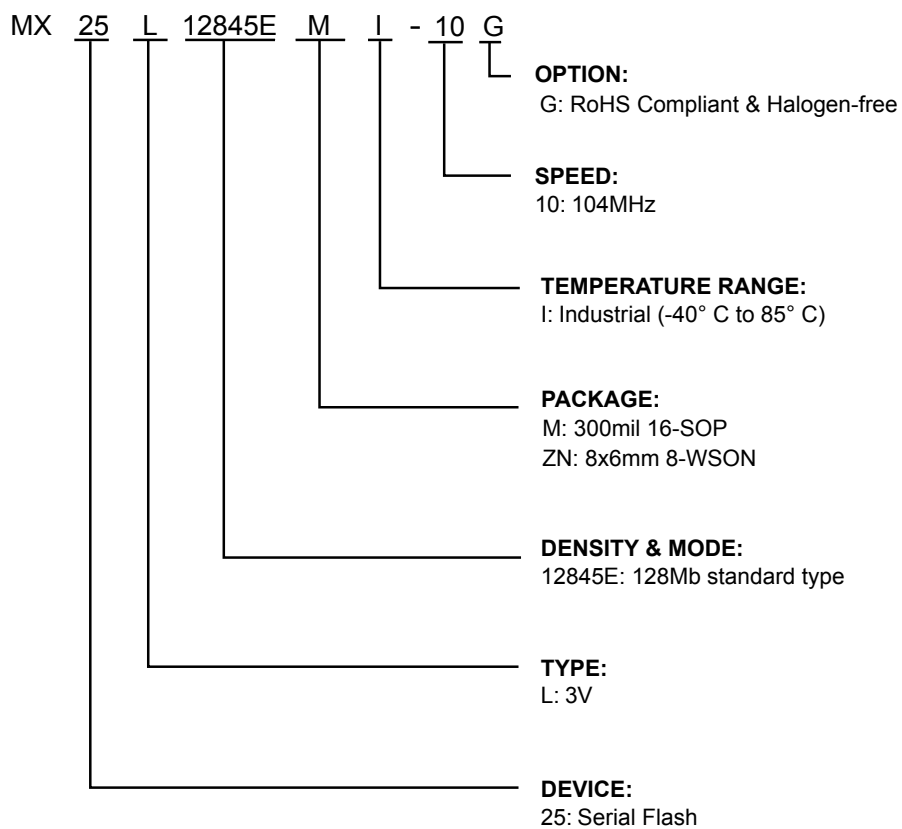


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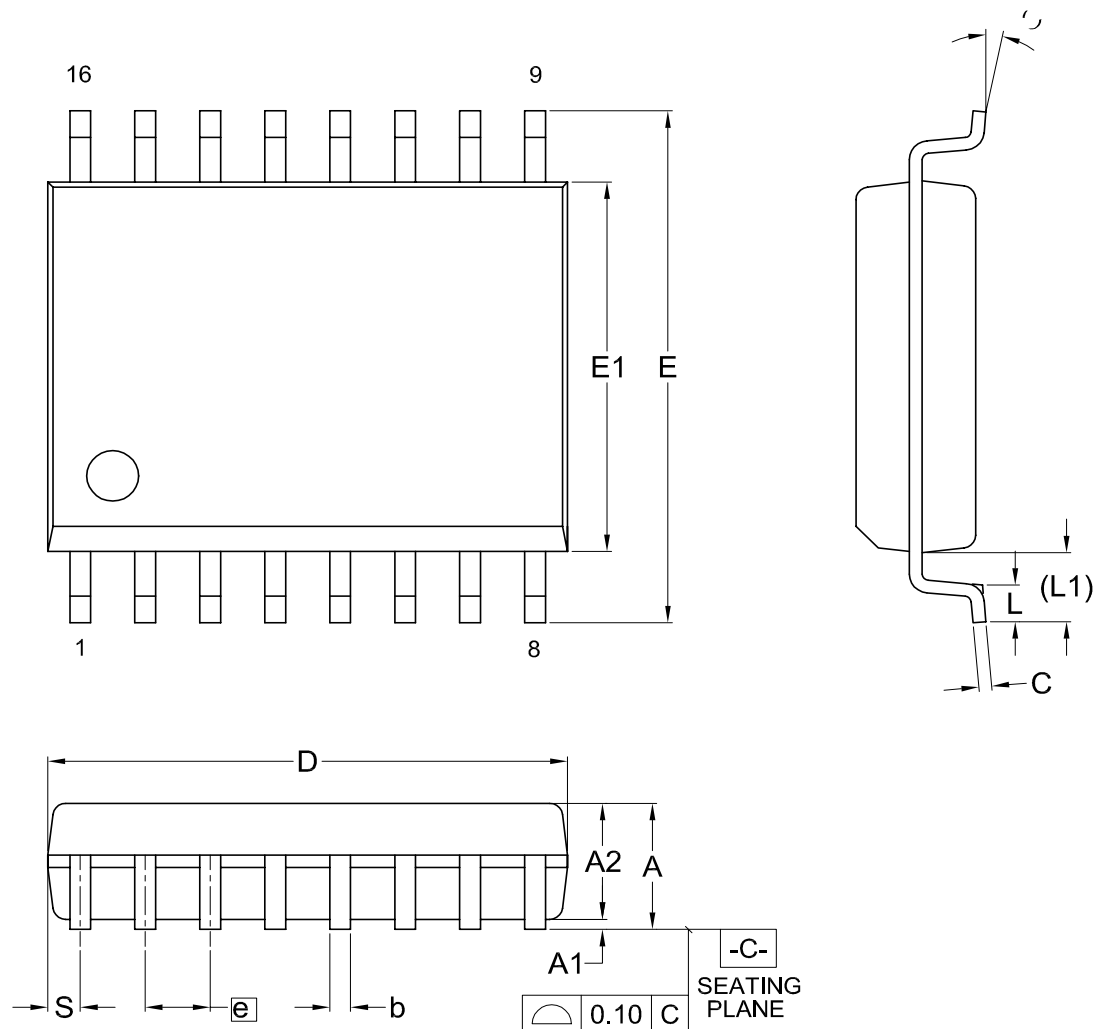
ORDERING INFORMATION

| PART NO. | CLOCK (MHz) | TEMPERATURE | PACKAGE | Remark |
|--------------------|----------------|-------------|--------------------|-------------------|
| MX25L12845EMI-10G | 104 | -40°C~85°C | 16-SOP (300mil) | RoHS Compliant |
| MX25L12845EZNI-10G | 104 | -40°C~85°C | 8-WSON (8x6mm) | RoHS Compliant |

PART NAME DESCRIPTION

PACKAGE INFORMATION

Doc. Title: Package Outline for SOP 16L (300MIL)

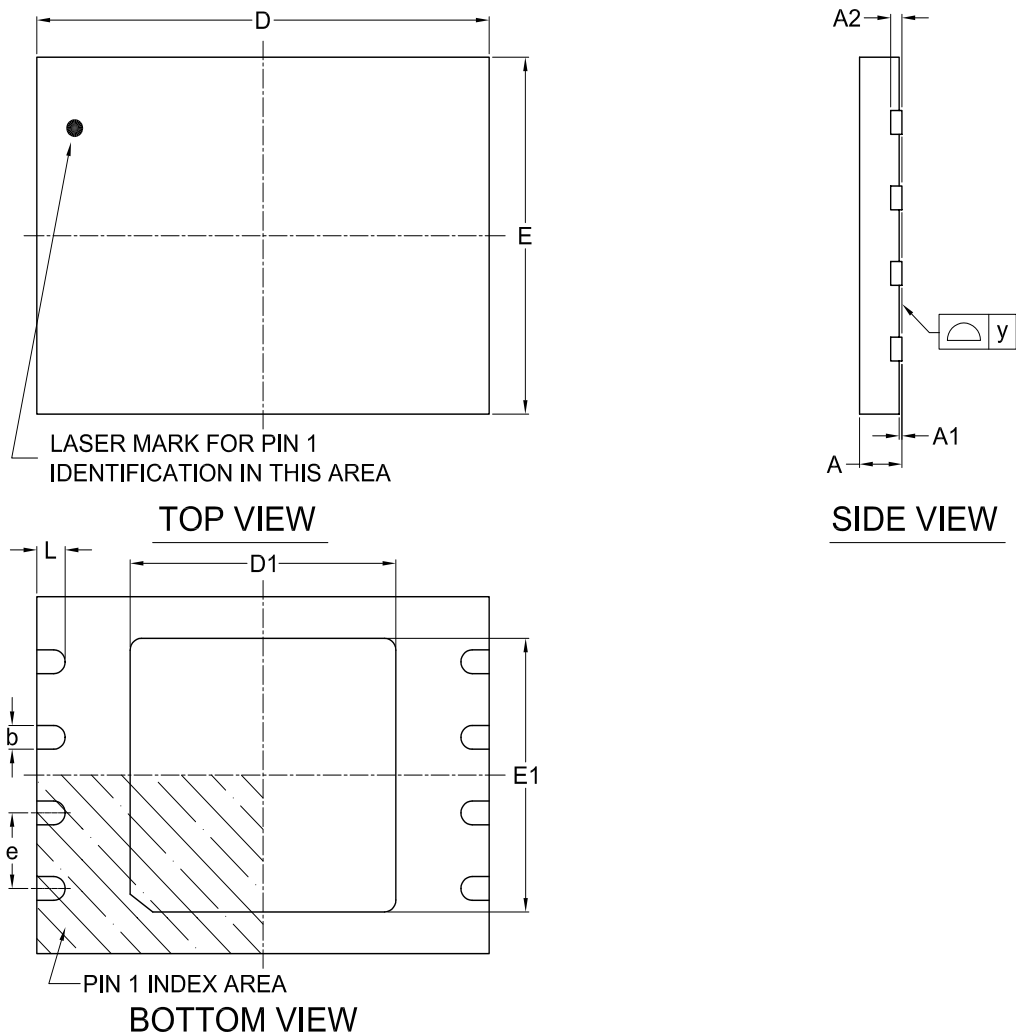


Dimensions (inch dimensions are derived from the original mm dimensions)

| SYMBOL | | A | A1 | A2 | b | C | D | E | E1 | e | L | L1 | S | Θ |
|--------|------|-------|-------|-------|-------|-------|-------|-------|-------|-------|-------|-------|-------|---|
| UNIT | | | | | | | | | | | | | | |
| mm | Min. | --- | 0.10 | 2.34 | 0.36 | 0.20 | 10.10 | 10.10 | 7.42 | --- | 0.40 | 1.31 | 0.51 | 0 |
| | Nom. | --- | 0.20 | 2.39 | 0.41 | 0.25 | 10.30 | 10.30 | 7.52 | 1.27 | 0.84 | 1.44 | 0.64 | 5 |
| | Max. | 2.65 | 0.30 | 2.44 | 0.51 | 0.30 | 10.50 | 10.50 | 7.60 | --- | 1.27 | 1.57 | 0.77 | 8 |
| Inch | Min. | --- | 0.004 | 0.092 | 0.014 | 0.008 | 0.397 | 0.397 | 0.292 | --- | 0.016 | 0.052 | 0.020 | 0 |
| | Nom. | --- | 0.008 | 0.094 | 0.016 | 0.010 | 0.405 | 0.405 | 0.296 | 0.050 | 0.033 | 0.057 | 0.025 | 5 |
| | Max. | 0.104 | 0.012 | 0.096 | 0.020 | 0.012 | 0.413 | 0.413 | 0.299 | --- | 0.050 | 0.062 | 0.030 | 8 |

| Dwg. No. | Revision | Reference | | | |
|-----------|----------|-----------|------|--|--|
| | | JEDEC | EIAJ | | |
| 6110-1402 | 10 | MS-013 | | | |

Doc. Title: Package Outline for WSON 8L (8x6x0.8MM, LEAD PITCH 1.27MM)



Note:

This package has an exposed metal pad underneath the package. It is recommended to leave the metal pad floating or to connect it to the same ground as the GND pin of the package. Do not connect the metal pad to any other voltage or signal line on the PCB. Avoid placing vias or traces underneath the metal pad. Connection of this metal pad to any other voltage or signal line can result in shorts and/or electrical malfunction of the device.

Dimensions (inch dimensions are derived from the original mm dimensions)

| SYMBOL UNIT | | A | A1 | A2 | b | D | D1 | E | E1 | L | e | y |
|----------------|------|-------|-------|-------|-------|-------|-------|-------|-------|-------|------|-------|
| | | | | | | | | | | | | |
| mm | Min. | 0.70 | --- | --- | 0.35 | 7.90 | 4.60 | 5.90 | 4.50 | 0.40 | --- | 0.00 |
| | Nom. | --- | --- | 0.20 | 0.40 | 8.00 | 4.70 | 6.00 | 4.60 | 0.50 | 1.27 | --- |
| | Max. | 0.80 | 0.05 | --- | 0.48 | 8.10 | 4.80 | 6.10 | 4.70 | 0.60 | --- | 0.08 |
| Inch | Min. | 0.028 | --- | --- | 0.014 | 0.311 | 0.181 | 0.232 | 0.177 | 0.016 | --- | 0.00 |
| | Nom. | --- | --- | 0.008 | 0.016 | 0.315 | 0.185 | 0.236 | 0.181 | 0.020 | 0.05 | --- |
| | Max. | 0.032 | 0.002 | --- | 0.019 | 0.319 | 0.189 | 0.240 | 0.185 | 0.024 | --- | 0.003 |

| Dwg. No. | Revision | Reference | | | |
|-----------|----------|-----------|------|--|--|
| | | JEDEC | EIAJ | | |
| 6110-3402 | 8 | MO-220 | | | |

REVISION HISTORY

| Revision No. | Description | Page | Date |
|--------------|---|---------------------|-------------|
| 1.0 | 1. Removed "Preliminary" | P5 | MAY/19/2009 |
| | 2. Merge MX25L6445E and MX25L12845E together | All | |
| | 3. Add CFI mode content | P37 | |
| | 4. Align waveform format | All | |
| | 5. Modify tCH/tCL value, from rev0.06 tCH/tCL=5.5ns to rev1.0 tCH/tCL(FAST_READ/READ)=4.5/9ns | P43,45 | |
| | 6. Change command table format | P15,16 | |
| | 7. Added " DATA RETENTION " Condition | P66 | |
| | 8. Modified sector erase time from 90ms to 60ms | P5,43,46, P66 | |
| | 9. Modified 128Mb chip erase time (max) from 512s to 200s | P46,66 | |
| 1.1 | 1. Added 128M 8-WSON EPN | P67 | JUL/16/2009 |
| | 2. Change RDCFI command from A5 to 5A | P16,37 | |
| 1.2 | 1. Added DMC Code content table | P37~39 | OCT/21/2009 |
| | 2. Removed MX25L12845EZNI-10G advanced information remark | P69 | |
| | 3. Changed the naming "CFI mode" as "DMC mode" | All | |
| 1.3 | 1. Corrected error | P8,43,44,54 | APR/01/2010 |
| | 2. Added wording "e.g. Vcc and CS# ramp up simultaneously" | P68 | |
| | 3. Modified low active read and standby current consumption and deep power down current consumption | P67 | |
| | 4. Deleted parallel mode condition | P5,43~44,69 | |
| | 5. Modified table of "Read DMC mode (RDDMC)" | P43 | |
| | 6. Added " Input Test Waveforms And Measurement Level " | P37~39 | |
| | 7. Modified tSLCH, tSHCH from 8ns to 5ns | P42 | |
| 1.4 | 1. Removed DMC sequence description & content table | P45,47 | |
| | 2. Revised low active read current spec | P6,14,16,37 | JUL/14/2010 |
| | 3. Revised Table 7-1 and Table 7-2 | P5 | |
| | | P40~41 | |
| 1.5 | 1. Removed MX25L6445E information from the previous combined version of MX25L6445E/MX25L12845E | All | AUG/15/2011 |
| | 2. Modified description for RoHS compliance | P6,63,64 | |
| | 3. Revised Figure 18. Fast DT Read (FASTDTRD) Sequence ; Figure 20. Fast Dual I/O DT Read (2DTRD) Sequence ; Figure 23. Fast Quad I/O DT Read (4DTRD) Sequence ; and Figure 24. Fast Quad I/O DT Read (4DTRD) Enhance Performance . | P46,47,49 | |
| | 4. Corrected ILO TEST CONDITIONS in Table 7 | P39 | |
| | 5. Revised Storage Temperature | P37 | |
| | 6. Revised CP mode completion method descriptions | P26 | |
| | 7. Revised DEVICE OPERATION descriptions | P13 | |
| 1.6 | 1. Added Quad I/O Read Frequency: 85MHz@VCC=3.0V~3.6V | P40 | SEP/13/2011 |
| 1.7 | 1. Revised the description in The individual block lock mode | P31 | OCT/05/2011 |
| 1.8 | 1. Modified Input Capacitance & Output Capacitance | P43 | FEB/10/2012 |
| | 2. Modified Figure 42. Power-Down Sequence | P67 | |
| | 3. Changed ordering information format | P69 | |
| | 4. Added Read SFDP (RDSFDP) Mode | P6,13,14, P36~41,46 | |
| 1.9 | 1. Modified ABSOLUTE MAXIMUM RATINGS table | P43 | SEP/06/2013 |



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